



HY16F3913

Datasheet

高精度混合信號處理控制器

4X44 ~ 8X40 LCD Driver

32-bit 低功耗微控制器

21-bit ENOB $\Sigma\Delta$ ADC

128KB Flash ROM

AC Impedance Converter AFE

HY16F3913

21-bit ENOB Σ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



目錄

1. 特性	5
2. 引腳名稱定義	6
2.1. HY16F3913 LQFP100 引腳圖	6
2.2. HY16F3913 QFN88 引腳圖	7
2.3. 引腳定義與功能描述	8
2.4. 引腳複用功能及複用功能優先級	18
2.5. 封裝片標記訊息	21
3. 應用電路	22
3.1. HCT 血糖儀應用電路	22
4. 功能概述	23
4.1. 內部框圖	23
4.2. 中央處理器核心方框圖	24
4.3. 相關的支援文檔	24
4.4. 時鐘系統網路	25
4.5. 電源系統網路	26
4.6. 24-bit Σ ADC 網路	27
4.7. 低電壓比較器網路	28
4.8. 看門狗(WDT)網路	29
4.9. 定時計數器 A 網路	29
4.10. 定時計數器 B 網路	30
4.11. 定時計數器 C 網路	31
4.12. 定時計數器 B2 網路	32

HY16F3913

21-bit ENOB Σ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



4.13.	32-bit SPI 網路	33
4.14.	UART1/UART2 網路.....	33
4.15.	I ² C 網路	34
4.16.	硬體萬年曆 RTC 網路.....	34
4.17.	LCD 網路.....	35
4.18.	Reset/BOR1/BOR2 網路.....	35
4.19.	GPIO	36
4.20.	交流阻抗量測類比前端-12-bit DAC I 網路	37
4.21.	交流阻抗量測類比前端-12-bit DAC II 網路	38
4.22.	交流阻抗量測類比前端-Rail to Rail OPAMP1 網路	38
4.23.	交流阻抗量測類比前端-Rail to Rail OPAMP2 網路	39
4.24.	交流阻抗量測類比前端-Rail to Rail OPAMP3 網路	39
4.25.	交流阻抗量測類比前端-BIA Module 網路	40
5.	電氣特性	41
5.1.	MCU Electrical Characteristics	41
5.2.	AC Impedance Converter AFE Electrical Characteristics	54
6.	訂貨資訊	69
7.	封裝尺寸資訊	70
7.1.	LQFP100(L100)	70
7.2.	QFN88(N088)(TYPE1).....	71
7.3.	QFN88(N088)(TYPE2).....	73
8.	修訂記錄	75

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



注意：

- 1、本說明書中的內容，隨著產品的改進，有可能不經過預告而更改。請客戶及時到本公司網站下載更新 <http://www.hycontek.com>。
- 2、本規格書中的圖形、應用電路等，因第三方工業所有權引發的問題，本公司不承擔其責任。
- 3、本產品在單獨應用的情況下，本公司保證它的性能、典型應用和功能符合說明書中的條件。當使用在客戶的產品或設備中，以上條件我們不作保證，建議客戶做充分的評估和測試。
- 4、請注意輸入電壓、輸出電壓、負載電流的使用條件，使 IC 內的功耗不超過封裝的容許功耗。對於客戶在超出說明書中規定額定值使用產品，即使是瞬間的使用，由此所造成的損失，本公司不承擔任何責任。
- 5、本產品雖內置防靜電保護電路，但請不要施加超過保護電路性能的過大靜電。
- 6、本規格書中的產品，未經書面許可，不可使用在要求高可靠性的電路中。例如健康醫療器械、防災器械、車輛器械、車載器械及航空器械等對人體產生影響的器械或裝置，不得作為其部件使用。
- 7、本公司一直致力於提高產品的品質和可靠度，但所有的半導體產品都有一定的失效概率，這些失效概率可能會導致一些人身事故、火災事故等。當設計產品時，請充分留意冗餘設計並採用安全指標，這樣可以避免事故的發生。
- 8、本規格書中內容，未經本公司許可，嚴禁用於其他目的之轉載或複製。

HY16F3913

21-bit ENOB Σ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



1. 特性

數字特性

- 32-bit 1T Andes Core E801 內核
- 支援 AndesSight C IDE 開發環境指令集
- 寬工作電壓 VDD5V: 2.0V ~ 5.5V.
- 工作溫度-40 to 85°C
- 低功耗(Typical@VDD5V=3.3V) :
 - 待機模式 : 4.5uA@LSRC=32KHz
 - 休眠模式 : 1.8uA
- 128KB Flash ROM
 - Write/Erase 的週期次數為 : 100,000 次
 - Write/Read/Erase 的操作電壓 $\geq 2.0V$
 - 內建硬件 ISP 功能 · 可線上更新 Flash
- 8KB SRAM
- 16-bit Timer A, Timer B(兩組), Timer C, WDT
- 16-bit PWM 控制器及訊號捕抓功能
- 硬體實現 I²C/32-bit SPI/UART(兩通道) 通訊介面
- 硬體實現時鐘 RTC 萬年曆功能
- 高達 72 個可編程複用型 I/O
 - 最多 24 個通用型數位輸出入埠
 - 最多 48 個可選擇 LCD 埠或數位輸出入埠
- 4x44 ~ 8x40 LCD 液晶驅動器
 - 1/3、1/4、1/5、1/6、1/8Duty
 - 1/3 及 1/4 Bias 選擇
 - 支援 R Type 驅動方式
 - 內建 Charge Pump 穩壓線路 · 可提供 6 段 VLCD 偏壓 · 分別為 2.8V, 3.0V, 3.3V, 3.9V, 4.5V 及 5.0V

模擬特性

- 類比工作電壓 VDDA: 2.4V ~ 3.6V
- 內建低雜訊 24-bit Σ ADC
 - ADC 支援 x1~x4 訊號放大
 - 內建低雜訊放大器 x8,x16,x32 訊號放大
 - 輸入參考訊號可解析至 65nVrms (Gain=128)
 - 最高轉換率高達 15K sps
 - 低溫飄係數與內置絕對溫度傳感(TPS)
- 外部高速晶震頻率高達 16MHz
- 外部低速晶震低至 32768Hz
- 內建 RC 高速震盪器頻率
 - 頻率可達 4.147MHz 及 31.795MHz
 - CPU 執行速度最高可達 16MHz
- 內建 RC 低速震盪器頻率低至 32KHz
- 電源模塊
 - 內建四段可調整穩壓電源(VDDA)
 - 1.2V 帶隙參考電壓(REFO)
- 多功能比較器 Comparator
 - 支援外部電壓輸入比較
 - 支援 15 段 LVD 低電壓檢測(2.0V~4.0V)
- 交流阻抗量測類比前端 AFE 硬體
 - 內建 24-bit Σ ADC、兩組 12-bit DAC、3 組 Rail-to-rail OPAM 等硬體
 - 電化學分析(Electrochemical analysis)
 - 生物阻抗分析模塊(Bioelectrical Impedance Analysis Module) · 功能如下:
 - AC waveform frequency: 122Hz~250KHz
 - Impedence Range: 1K ~ 1M Ω
 - Phase detector: 0~90°

Part No.	24-b Σ ADC	Flash (byte)	SRAM (byte)	TPS	RTC	I/O	Timer (bit x ch.)	PWM (bit x ch.)	Serial Interface	LCD (com x seg)	Impedance Converter AFE	ISP Mode	BIA Module	Package
HY16F3913-L100	9-CH	128K	8K	Y	Y	22+ 48 *	16bit x 3	8bit x 4 16bit x 2	UART x2 32bits SPI I ² C	4x44 6x42 8x40	Y	Y	Y	LQFP100
HY16F3913-N088	5-CH	128K	8K	Y	Y	24+ 38 *	16bit x 3	8bit x 4 16bit x 2	UART x2 32bits SPI I ² C	4x34 6x32 8x30	Y	Y	Y	QFN88

*: LCD pin shared I/O

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



2. 引腳名稱定義

2.1. HY16F3913 LQFP100 引腳圖

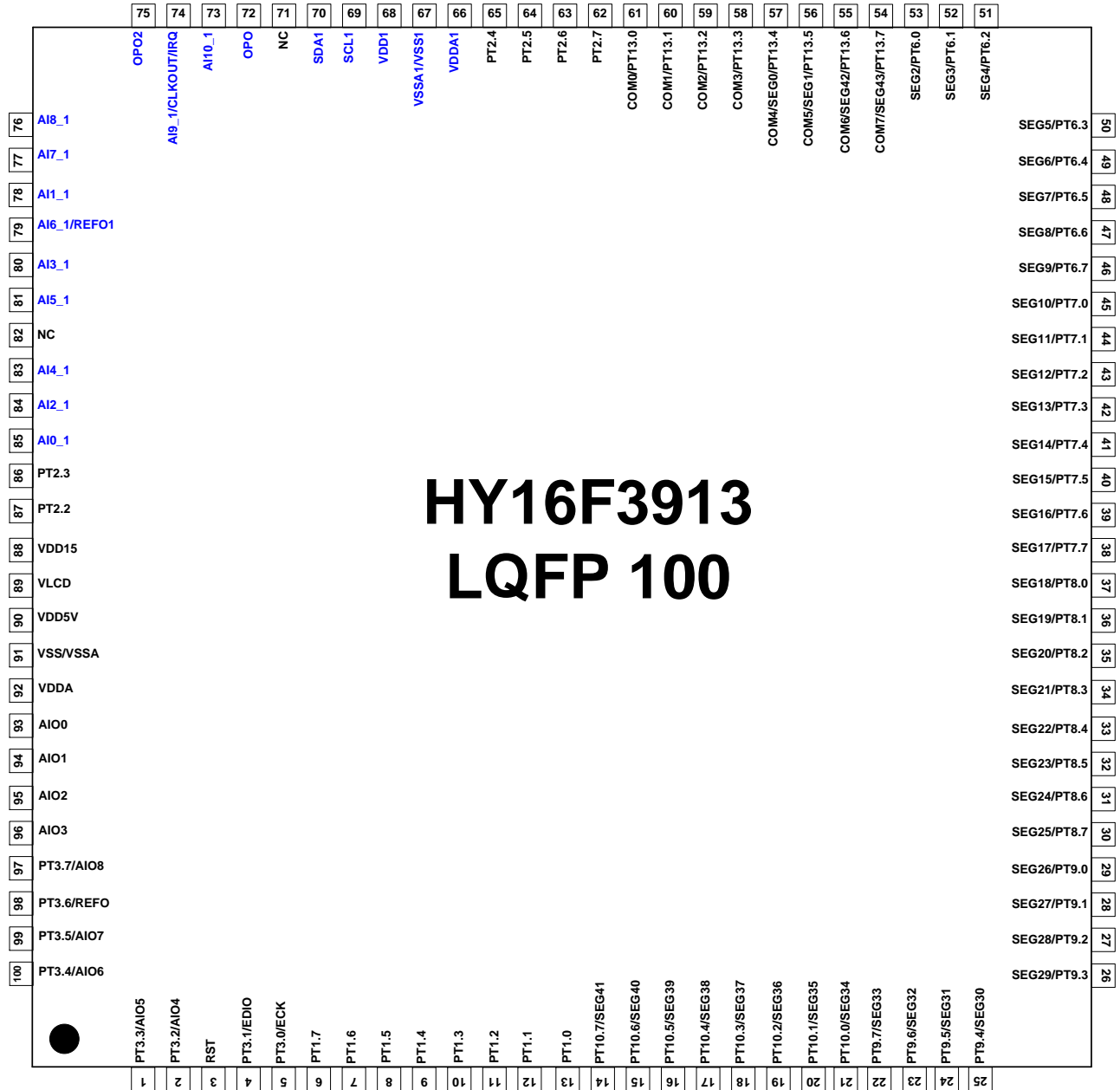


圖 2-1 HY16F3913 LQFP100 引腳圖

說明：腳位 66~85 屬於交流阻抗量測類比前端的相關引腳

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



2.2. HY16F3913 QFN88 引腳圖

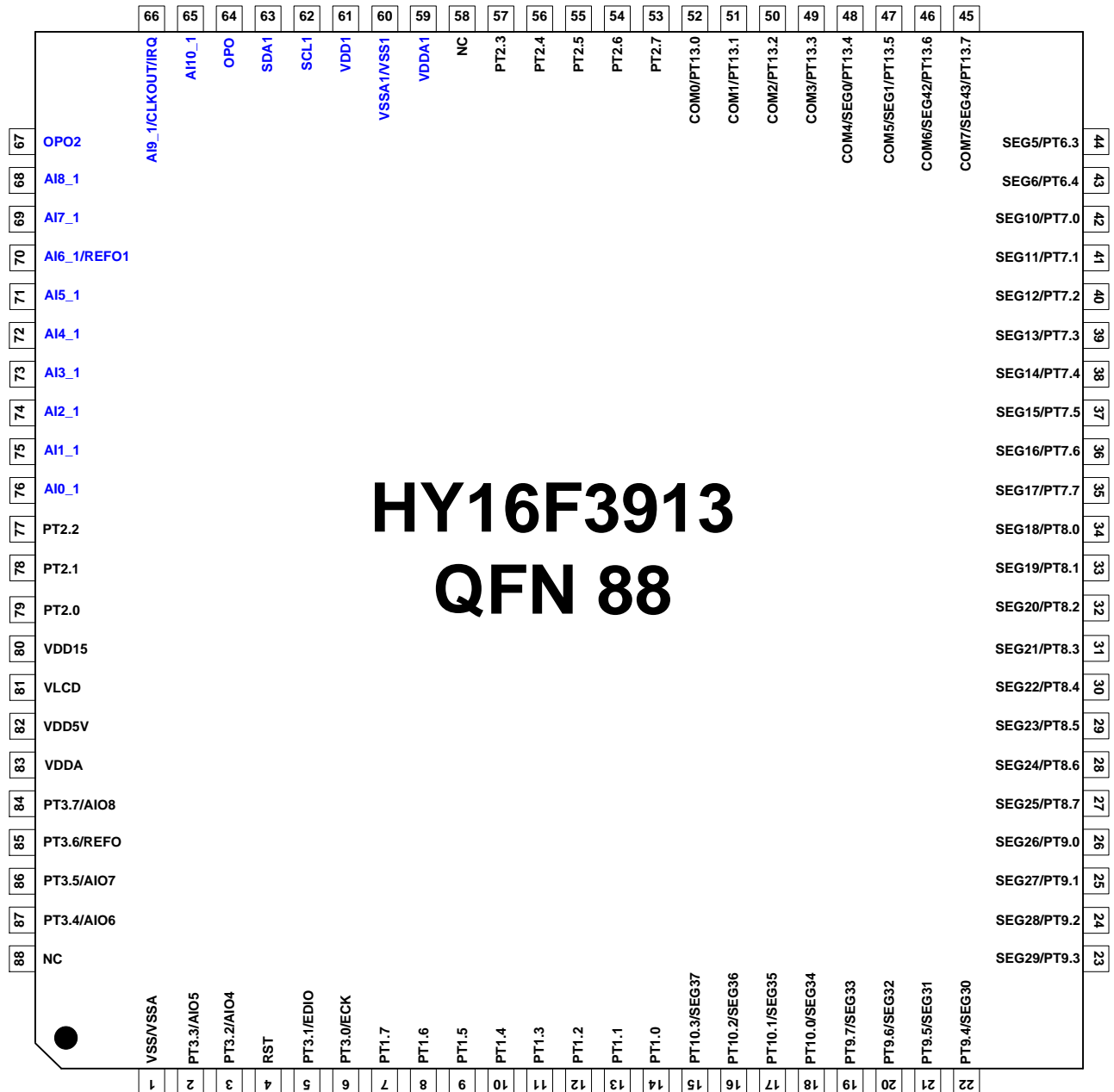


圖 2-2 HY16F3913 QFN88 引腳圖

說明：腳位 59-76 屬於交流阻抗量測類比前端的相關引腳

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



2.3. 引腳定義與功能描述

2.3.1. 引腳定義

"I" : Input, "O" : Output, "A" : Analog, "S" : Smith triggers, "C" : CMOS I/O, "P" : Power Source, "/" : or, "X" : Ignorable.

封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
1	2	PT3.3	I/O	S/C	通用數字輸入/輸出引腳
		INT3.3	I	S	外部中斷源 INT3.3 輸入引腳
		AIO5	I/O	A	ADC 模擬輸入引腳 AIO5
2	3	PT3.2	I/O	S/C	通用數字輸入/輸出引腳
		INT3.2	I	S	外部中斷源 INT3.2 輸入引腳
		AIO4	I/O	A	ADC 模擬輸入引腳 AIO4
3	4	RST	I	D	復位引腳(低電位有效) · 需外接 10nF 對地電容
4	5	PT3.1	I/O	S/C	通用數字輸入/輸出引腳
		INT3.1	I	S	外部中斷源 INT3.1 輸入引腳
		EDIO	I/O	D	開發調試通訊口(EDM)數據線輸入/輸出引腳 · RST=L 時可動作
5	6	PT3.0	I/O	S/C	通用數字輸入/輸出引腳
		INT3.0	I	S	外部中斷源 INT3.0 輸入引腳
		ECK	I/O	D	開發調試通訊口(EDM)時鐘線引腳 · RST=L 時可動作
6	7	PT1.7	I/O	S/C	通用數字輸入/輸出引腳
		INT1.7	I	S	外部中斷源 INT1.7 輸入引腳
		PWM3_2	O	C	TimerB2, PWM3_2 輸出引腳
		MOSI_2	O	C	SPI 通訊數據線引腳 MOSI_2(主機輸出 · 從機輸入)
		RX2_2	I	S	EUART2 通訊接收線引腳 RX2_2
		TCI2_4	I	S	捕捉比較器輸入源引腳 TCI2_4
		SDA_4	I/O	S/C	I ² C 通訊數據線引腳 SDA_4
7	8	PT1.6	I/O	S/C	通用數字輸入/輸出引腳
		INT1.6	I	S	外部中斷源 INT1.6 輸入引腳
		PWM2_2	O	C	TimerB2, PWM2_2 輸出引腳
		MISO_2	I	S	SPI 通訊數據線引腳 MISO_2(主機輸入 · 從機輸出)
		TX2_2	O	C	EUART2 通訊發送線引腳 TX2_2
		TCI1_4	I	S	捕捉比較器輸入源引腳 TCI1_4
		SCL_4	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_4
8	9	PT1.5	I/O	S/C	通用數字輸入/輸出引腳
		INT1.5	I	S	外部中斷源 INT1.5 輸入引腳
		PWM1_2	O	C	TimerB, PWM1_2 輸出引腳
		CK_2	O	C	SPI 通訊時鐘線引腳 CK_2

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		RX_2	I	S	EUART 通訊接收線引腳 RX_2
		TCI2_3	I	S	捕捉比較器輸入源引腳 TCI2_3
		SDA_3	I/O	S/C	I ² C 通訊數據線引腳 SDA_3
9	10	PT1.4	I/O	S/C	通用數字輸入/輸出引腳
		INT1.4	I	S	外部中斷源 INT1.4 輸入引腳
		PWM0_2	O	C	TimerB, PWM0_2 輸出引腳
		CS_2	I	S	SPI 通訊使能引腳 CS_2
		TX_2	O	C	EUART 通訊發送線引腳 TX_2
		TCI1_3	I	S	捕捉比較器輸入源引腳 TCI1_3
		SCL_3	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_3
10	11	PT1.3	I/O	S/C	通用數字輸入/輸出引腳
		INT1.3	I	S	外部中斷源 INT1.3 輸入引腳
		PWM3_1	O	C	TimerB2, PWM3_1 輸出引腳
		MOSI_1	O	C	SPI 通訊數據線引腳 MOSI_1(主機輸出·從機輸入)
		RX2_1	I	S	EUART2 通訊接收線引腳 RX2_1
		TCI2_2	I	S	捕捉比較器輸入源引腳 TCI2_2
		SDA_2	I/O	S/C	I ² C 通訊數據線引腳 SDA_2
11	12	PT1.2	I/O	S/C	通用數字輸入/輸出引腳
		INT1.2	I	S	外部中斷源 INT1.2 輸入引腳
		PWM2_1	O	C	TimerB2, PWM2_1 輸出引腳
		MISO_1	I	S	SPI 通訊數據線引腳 MISO_1(主機輸入·從機輸出)
		TX2_1	O	C	EUART2 通訊發送線引腳 TX2_1
		TCI1_2	I	S	捕捉比較器輸入源引腳 TCI1_2
		SCL_2	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_2
12	13	PT1.1	I/O	S/C	通用數字輸入/輸出引腳
		INT1.1	I	S	外部中斷源 INT1.1 輸入引腳
		PWM1_1	O	C	TimerB, PWM1_1 輸出引腳
		CK_1	O	C	SPI 通訊時鐘線引腳 CK_1
		RX_1	I	S	EUART 通訊接收線引腳 RX_1
		TCI2_1	I	S	捕捉比較器輸入源引腳 TCI2_1
		SDA_1	I/O	S/C	I ² C 通訊數據線引腳 SDA_1
13	14	PT1.0	I/O	S/C	通用數字輸入/輸出引腳
		INT1.0	I	S	外部中斷源 INT1.0 輸入引腳
		PWM0_1	O	C	TimerB, PWM0_1 輸出引腳
		CS_1	I	S	SPI 通訊使能引腳 CS_1
		TX_1	O	C	EUART 通訊發送線引腳 TX_1

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		TCI1_1	I	S	捕捉比較器輸入源引腳 TCI1_1
		SCL_1	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_1
14	-	PT10.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG41	O	A	LCD Segment 41 輸出
15	-	PT10.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG40	O	A	LCD Segment 40 輸出
		TCI3_8	I	S	TimerB2 輸入源引腳 TCI3_8
16	-	PT10.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG39	O	A	LCD Segment 39 輸出
17	-	PT10.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG38	O	A	LCD Segment 38 輸出
		TCI3_7	I	S	TimerB2 輸入源引腳 TCI3_7
18	15	PT10.3	I/O	S/C	通用數字輸入/輸出引腳
		SEG37	O	A	LCD Segment 37 輸出
19	16	PT10.2	I/O	S/C	通用數字輸入/輸出引腳
		SEG36	O	A	LCD Segment 36 輸出
20	17	PT10.1	I/O	S/C	通用數字輸入/輸出引腳
		SEG35	O	A	LCD Segment 35 輸出
21	18	PT10.0	I/O	S/C	通用數字輸入/輸出引腳
		SEG34	O	A	LCD Segment 34 輸出
22	19	PT9.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG33	O	A	LCD Segment 33 輸出
23	20	PT9.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG32	O	A	LCD Segment 32 輸出
24	21	PT9.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG31	O	A	LCD Segment 31 輸出
25	22	PT9.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG30	O	A	LCD Segment 30 輸出
26	23	PT9.3	I/O	S/C	通用數字輸入/輸出引腳
		SEG29	O	A	LCD Segment 29 輸出
		PWM3_7	O	C	TimerB2, PWM3_7 輸出引腳
		MOSI_7	O	C	SPI 通訊數據線引腳 MOSI_7(主機輸出·從機輸入)
		RX2_7	I	S	EUART2 通訊接收線引腳 RX2_7
27	24	PT9.2	I/O	S/C	通用數字輸入/輸出引腳
		SEG28	I	S	LCD Segment 28 輸出

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		PWM2_7	O	C	TimerB2, PWM2_7 輸出引腳
		MISO_7	I	S	SPI 通訊數據線引腳 MISO_7(主機輸入·從機輸出)
		TX2_7	O	C	EUART2 通訊發送線引腳 TX2_7
		TCI3_6	I	S	TimerB2 輸入源引腳 TCI3_6
28	25	PT9.1	I/O	S/C	通用數字輸入/輸出引腳
		SEG27	I	S	LCD Segment 27 輸出
		PWM1_7	O	C	TimerB, PWM1_7 輸出引腳
		CK_7	O	C	SPI 通訊時鐘線引腳 CK_7
		RX_7	I	S	EUART 通訊接收線引腳 RX_7
29	26	PT9.0	I/O	S/C	通用數字輸入/輸出引腳
		SEG26	I	S	LCD Segment 26 輸出
		PWM0_7	O	C	TimerB, PWM0_1 輸出引腳
		CS_7	I	S	SPI 通訊使能引腳 CS_1
		TX_7	O	C	EUART 通訊發送線引腳 TX_1
		TCI3_5	I	S	TimerB2 輸入源引腳 TCI3_5
30	27	PT8.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG25	O	A	LCD Segment 25 輸出
31	28	PT8.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG24	O	A	LCD Segment 24 輸出
32	29	PT8.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG23	O	A	LCD Segment 23 輸出
33	30	PT8.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG22	O	A	LCD Segment 22 輸出
34	31	PT8.3	I/O	S/C	通用數字輸入/輸出引腳
		SEG21	O	A	LCD Segment 21 輸出
		PWM3_8	O	C	TimerB2, PWM3_8 輸出引腳
		MOSI_8	O	C	SPI 通訊數據線引腳 MOSI_8(主機輸出·從機輸入)
		RX2_8	I	S	EUART2 通訊接收線引腳 RX2_8
35	32	PT8.2	I/O	S/C	通用數字輸入/輸出引腳
		SEG20	I	S	LCD Segment 20 輸出
		PWM2_8	O	C	TimerB2, PWM2_8 輸出引腳
		MISO_8	I	S	SPI 通訊數據線引腳 MISO_8(主機輸入·從機輸出)
		TX2_8	O	C	EUART2 通訊發送線引腳 TX2_8
36	33	PT8.1	I/O	S/C	通用數字輸入/輸出引腳
		SEG19	I	S	LCD Segment 19 輸出
		PWM1_8	O	C	TimerB, PWM1_8 輸出引腳

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		CK_8	O	C	SPI 通訊時鐘線引腳 CK_8
		RX_8	I	S	EUART 通訊接收線引腳 RX_8
37	34	PT8.0	I/O	S/C	通用數字輸入/輸出引腳
		SEG18	I	S	LCD Segment 18 輸出
		PWM0_8	O	C	TimerB, PWM0_8 輸出引腳
		CS_8	I	S	SPI 通訊使能引腳 CS_8
		TX_8	O	C	EUART 通訊發送線引腳 TX_8
38	35	PT7.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG17	O	A	LCD Segment 17 輸出
		PWM3_6	O	C	TimerB2, PWM3_6 輸出引腳
		MOSI_6	O	C	SPI 通訊數據線引腳 MOSI_6(主機輸出 · 從機輸入)
		RX2_6	I	S	EUART2 通訊接收線引腳 RX2_6
39	36	PT7.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG16	I	S	LCD Segment 16 輸出
		PWM2_6	O	C	TimerB2, PWM2_6 輸出引腳
		MISO_6	I	S	SPI 通訊數據線引腳 MISO_6(主機輸入 · 從機輸出)
		TX2_6	O	C	EUART2 通訊發送線引腳 TX2_6
		TCI3_4	I	S	TimerB2 輸入源引腳 TCI3_4
40	37	PT7.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG15	O	A	LCD Segment 15 輸出
		PWM1_6	O	C	TimerB, PWM1_6 輸出引腳
		CK_6	O	C	SPI 通訊時鐘線引腳 CK_6
		RC_6	I	S	EUART 通訊接收線引腳 RX_6
41	38	PT7.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG14	O	A	LCD Segment 14 輸出
		PWM0_6	O	C	TimerB, PWM0_6 輸出引腳
		CS_6	O	C	SPI 通訊時鐘線引腳 CS_6
		TX_6	I	S	EUART 通訊發送線引腳 TX_6
		TCI3_3	I	S	TimerB2 輸入源引腳 TCI3_3
42	39	PT7.3	I/O	S/C	通用數字輸入/輸出引腳
		SEG13	O	A	LCD Segment 13 輸出
43	40	PT7.2	I/O	S/C	通用數字輸入/輸出引腳
		SEG12	O	A	LCD Segment 12 輸出
44	41	PT7.1	I/O	S/C	通用數字輸入/輸出引腳
		SEG11	O	A	LCD Segment 11 輸出
45	42	PT7.0	I/O	S/C	通用數字輸入/輸出引腳

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		SEG10	O	A	LCD Segment 10 輸出
46	-	PT6.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG9	O	A	LCD Segment 9 輸出
47	-	PT6.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG8	O	A	LCD Segment 8 輸出
48	-	PT6.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG7	O	A	LCD Segment 7 輸出
49	43	PT6.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG6	O	A	LCD Segment 6 輸出
50	44	PT6.3	I/O	S/C	通用數字輸入/輸出引腳
		SEG5	O	A	LCD Segment 5 輸出
		PWM3_5	O	C	TimerB2, PWM3_5 輸出引腳
		MOSI_5	O	C	SPI 通訊數據線引腳 MOSI_5(主機輸出·從機輸入)
		RX2_5	I	S	EUART2 通訊接收線引腳 RX2_5
51	-	PT6.2	I/O	S/C	通用數字輸入/輸出引腳
		SEG4	O	A	LCD Segment 4 輸出
		PWM2_5	O	C	TimerB2, PWM2_5 輸出引腳
		MISO_5	I	S	SPI 通訊數據線引腳 MISO_5(主機輸入·從機輸出)
		TX2_5	O	C	EUART2 通訊發送線引腳 TX2_5
		TCI3_2	I	S	TimerB2 輸入源引腳 TCI3_2
52	-	PT6.1	I/O	S/C	通用數字輸入/輸出引腳
		SEG3	O	A	LCD Segment 3 輸出
		PWM1_5	O	C	TimerB, PWM1_5 輸出引腳
		CK_5	O	C	SPI 通訊時鐘線引腳 CK_5
		RX_5	I	S	EUART 通訊接收線引腳 RX_5
53	-	PT6.0	I/O	S/C	通用數字輸入/輸出引腳
		SEG2	O	A	LCD Segment 2 輸出
		PWM0_5	O	C	TimerB, PWM0_5 輸出引腳
		CS_5	I	S	SPI 通訊使能引腳 CS_5
		TX_5	O	C	EUART 通訊發送線引腳 TX_5
		TCI3_1	I	S	TimerB2 輸入源引腳 TCI3_1
54	45	PT13.7	I/O	S/C	通用數字輸入/輸出引腳
		SEG43	O	A	LCD Segment 43 輸出
		COM7	O	A	LCD Common 7 輸出
55	46	PT13.6	I/O	S/C	通用數字輸入/輸出引腳
		SEG42	O	A	LCD Segment 42 輸出

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		COM6	O	A	LCD Common 6 輸出
56	47	PT13.5	I/O	S/C	通用數字輸入/輸出引腳
		SEG1	O	A	LCD Segment 1 輸出
		COM5	O	A	LCD Common 5 輸出
57	48	PT13.4	I/O	S/C	通用數字輸入/輸出引腳
		SEG0	O	A	LCD Segment 0 輸出
		COM4	O	A	LCD Common 4 輸出
58	49	PT13.3	I/O	S/C	通用數字輸入/輸出引腳
		COM3	O	A	LCD Common 3 輸出
59	50	PT13.2	I/O	S/C	通用數字輸入/輸出引腳
		COM2	O	A	LCD Common 2 輸出
60	51	PT13.1	I/O	S/C	通用數字輸入/輸出引腳
		COM1	O	A	LCD Common 1 輸出
61	52	PT13.0	I/O	S/C	通用數字輸入/輸出引腳
		COM0	O	A	LCD Common 0 輸出
62	53	PT2.7	I/O	S/C	通用數字輸入/輸出引腳
		HS_XOUT	A	A	外部高速晶震 2~16MHz 輸出引腳
		INT2.7	I	S	外部中斷源 INT2.7 輸入引腳
		PWM3_4	O	C	TimerB2, PWM3_4 輸出引腳
		MOSI_4	O	C	SPI 通訊數據線引腳 MOSI_4(主機輸出·從機輸入)
		RX2_4	I	S	EUART2 通訊接收線引腳 RX2_4
		TCI2_8	I	S	捕捉比較器輸入源引腳 TCI2_8
SDA_8	I/O	S/C	I ² C 通訊數據線引腳 SDA_8		
63	54	PT2.6	I/O	S/C	通用數字輸入/輸出引腳
		HS_XIN	A	A	外部高速晶震 2~16MHz 輸入引腳
		INT2.6	I	S	外部中斷源 INT2.6 輸入引腳
		PWM2_4	O	C	TimerB2, PWM2_4 輸出引腳
		MISO_4	I	S	SPI 通訊數據線引腳 MISO_4(主機輸入·從機輸出)
		TX2_4	O	C	EUART2 通訊發送線引腳 TX2_4
		TCI1_8	I	S	捕捉比較器輸入源引腳 TCI1_8
SCL_8	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_8		
64	55	PT2.5	I/O	S/C	通用數字輸入/輸出引腳
		LS_XIN	A	A	外部低速晶震 32768Hz 輸出引腳
		INT2.5	I	S	外部中斷源 INT2.5 輸入引腳
		PWM1_4	O	C	TimerB, PWM1_4 輸出引腳
		CK_4	O	C	SPI 通訊時鐘線引腳 CK_4

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		RX_4	I	S	EUART 通訊接收線引腳 RX_4
		TCI2_7	I	S	捕捉比較器輸入源引腳 TCI2_7
		SDA_7	I/O	S/C	I ² C 通訊數據線引腳 SDA_7
65	56	PT2.4	I/O	S/C	通用數字輸入/輸出引腳
		LS_XOUT	A	A	外部低速晶震 32768Hz 輸入引腳
		INT2.4	I	S	外部中斷源 INT2.4 輸入引腳
		PWM0_4	O	C	TimerB2, PWM0_4 輸出引腳
		CS_4	O	C	SPI 通訊使能引腳 CS_4
		TX_4	O	C	EUART 通訊發送線引腳 TX_4
		TCI1_8	I	S	捕捉比較器輸入源引腳 TCI1_7
		SCL_7	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_7
66	59	VDDA1	I/O	P	AFE 模擬電壓源輸入/輸出端 · 需外接 1~10uF 對地電容
67	60	VSS1	I	P	AFE 數字接地端引腳
		VSSA1	I	P	AFE 模擬比接地端引腳
68	61	VDD1	I	P	AFE 晶片工作電源電壓輸入引腳 · 需外接 10uF 對地電容
69	62	SCL1	I/O	S/C	AFE 的 I ² C 通訊時鐘線引腳 SCL1
70	63	SDA1	I/O	S/C	AFE 的 I ² C 通訊數據線引腳 SDA1
		IRQ*	O	C	AFE 的 ADC 中斷狀態輸出(複用選擇)
72	64	OPO	A	P	AFE 的 OPAMP2 狀態輸出腳 OPO
73	65	AI10_1	I	A	AFE 的 ADC 模擬輸入引腳 AI10_1
74	66	AI9_1	I	A	AFE 的 ADC 模擬輸入引腳 AI9_1
		CLKOUT	O	C	AFE 的內部 RC 震盪除頻輸出腳
		IRQ	O	C	AFE 的 ADC 中斷狀態輸出
75	67	OPO2	A	P	AFE 的 OPAMP3 狀態輸出腳 OPO2
76	68	AI8_1	I	A	AFE 的 ADC 模擬輸入引腳 AI8_1
77	69	AI7_1	I	A	AFE 的 ADC 模擬輸入引腳 AI7_1
78	75	AI1_1	I	A	AFE 的 ADC 模擬輸入引腳 AI1_1
79	70	AI6_1	I	A	AFE 的 ADC 模擬輸入引腳 AI6_1
		REFO1	I/O	P	AFE 模擬參考電壓 1.2V 輸出引腳 · 需外接 0.1uF 對地電容
80	73	AI3_1	I	A	AFE 的 ADC 模擬輸入引腳 AI3_1
81	71	AI5_1	I	A	AFE 的 ADC 模擬輸入引腳 AI5_1
83	72	AI4_1	I	A	AFE 的 ADC 模擬輸入引腳 AI4_1
84	74	AI2_1	I	A	AFE 的 ADC 模擬輸入引腳 AI2_1
85	76	AI0_1	I	A	AFE 的 ADC 模擬輸入引腳 AI0_1
86	57	PT2.3	I/O	S/C	通用數字輸入/輸出引腳

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
		INT2.3	I	S	外部中斷源 INT2.3 輸入引腳
		LVDOO	O	C	低電壓比較器 LVDO 狀態輸出引腳
		PWM3_3	O	C	TimerB2, PWM3_3 輸出引腳
		MOSI_3	O	C	SPI 通訊數據線引腳 MOSI_3(主機輸出·從機輸入)
		RX2_3	I	S	EUART2 通訊接收線引腳 RX2_3
		TCI2_6	I	S	捕捉比較器輸入源引腳 TCI2_6
		SDA_6	I/O	S/C	I ² C 通訊數據線引腳 SDA_6
87	77	PT2.2	I/O	S/C	通用數字輸入/輸出引腳
		INT2.2	I	S	外部中斷源 INT2.2 輸入引腳
		PWM2_3	O	C	TimerB2, PWM2_3 輸出引腳
		MISO_3	I	S	SPI 通訊數據線引腳 MISO_3(主機輸入·從機輸出)
		TX2_3	O	C	EUART2 通訊發送線引腳 TX2_3
		TCI1_6	I	S	捕捉比較器輸入源引腳 TCI1_6
		SCL_6	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_6
-	78	PT2.1	I/O	S/C	通用數字輸入/輸出引腳
		INT2.1	I	S	外部中斷源 INT2.1 輸入引腳
		PWM1_3	O	C	TimerB, PWM1_3 輸出引腳
		CK_3	O	C	SPI 通訊時鐘線引腳 CK_3
		RX_3	I	S	EUART 通訊接收線引腳 RX_3
		TCI2_5	I	S	捕捉比較器輸入源引腳 TCI2_5
		SDA_5	I/O	S/C	I ² C 通訊數據線引腳 SDA_5
-	79	PT2.0	I/O	S/C	通用數字輸入/輸出引腳
		INT2.0	I	S	外部中斷源 INT2.0 輸入引腳
		PWM0_3	O	C	TimerB2, PWM0_3 輸出引腳
		CS_3	O	C	SPI 通訊使能引腳 CS_3
		TX_3	O	C	EUART 通訊發送線引腳 TX_3
		TCI1_5	I	S	捕捉比較器輸入源引腳 TCI1_5
		SCL_5	I/O	S/C	I ² C 通訊時鐘線引腳 SCL_5
88	80	VDD15	I	P	晶片數位電路電源電壓引腳, 需外接 0.1uF 對地電容
89	81	VLCD	I/O	P	LCD 穩壓電源輸出/LCD 電源輸入·需外接 10uF 對地電容
90	82	VDD5V	I	P	晶片工作電源電壓輸入引腳·需外接 0.1uF 對地濾波電容
91	1	VSS	I	P	數字接地端引腳
		VSSA	I	P	模擬比接地端引腳
92	83	VDDA	I/O	P	模擬電壓源輸入/輸出端·需外接 1~10uF 對地電容
93	-	AIO0	I	A	ADC 模擬輸入引腳 AIO0
94	-	AIO1	I	A	ADC 模擬輸入引腳 AIO1

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

封裝 / 引腳編號		引腳名稱	特性		功能說明
LQFP100	QFN88		型態	緩衝	
95	-	AIO2	I	A	ADC 模擬輸入引腳 AIO2
96	-	AIO3	I	A	ADC 模擬輸入引腳 AIO3
97	84	PT3.7	I/O	S/C	通用數字輸入/輸出引腳
		INT3.7	I	S	外部中斷源 INT3.7 輸入引腳
		LVDIN	I	A	低電壓比較器外部輸入引腳 LVDIN
		AIO8	I	A	ADC 模擬輸入引腳 AIO8
98	85	PT3.6	I/O	S/C	通用數字輸入/輸出引腳
		INT3.6	I	S	外部中斷源 INT3.6 輸入引腳
		REFO	I/O	P	模擬參考電壓 1.2V 輸出引腳，需外接 0.1uF 對地電容
99	86	PT3.5	I/O	S/C	通用數字輸入/輸出引腳
		INT3.5	I	S	外部中斷源 INT3.5 輸入引腳
		AIO7	I/O	A	ADC 模擬輸入引腳 AIO7
100	87	PT3.4	I/O	S/C	通用數字輸入/輸出引腳
		INT3.4	I	S	外部中斷源 INT3.4 輸入引腳
		AIO6	I/O	A	ADC 模擬輸入引腳 AIO6
71 & 82	58 & 88	NC	-	-	空腳，應用時空接即可

表 2-1 引腳定義及引腳功能描述

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



2.4. 引腳複用功能及複用功能優先級

Function	INT	GPIO	Timer C Capture	Special Function	SPI	I ² C	UART	Analog	Timer B/B2 PWM
Output Priority	I/P	I/P	I/P	0	1	2	3	4	5
PT1.0	INT1.0	DIO	TCI1_1		CS_1	SCL_1	Tx_1		PWM0_1
PT1.1	INT1.1	DIO	TCI2_1		CK_1	SDA_1	Rx_1		PWM1_1
PT1.2	INT1.2	DIO	TCI1_2		MISO_1	SCL_2	Tx2_1		PWM2_1
PT1.3	INT1.3	DIO	TCI2_2		MOSI_1	SDA_2	Rx2_1		PWM3_1
PT1.4	INT1.4	DIO	TCI1_3		CS_2	SCL_3	Tx_2		PWM0_2
PT1.5	INT1.5	DIO	TCI2_3		CK_2	SDA_3	Rx_2		PWM1_2
PT1.6	INT1.6	DIO	TCI1_4		MISO_2	SCL_4	Tx2_2		PWM2_2
PT1.7	INT1.7	DIO	TCI2_4		MOSI_2	SDA_4	Rx2_2		PWM3_2
PT2.0	INT2.0	DIO	TCI1_5		CS_3	SCL_5	Tx_3		PWM0_3
PT2.1	INT2.1	DIO	TCI2_5		CK_3	SDA_5	Rx_3		PWM1_3
PT2.2	INT2.2	DIO	TCI1_6		MISO_3	SCL_6	Tx2_3		PWM2_3
PT2.3	INT2.3	DIO	TCI2_6	LVDOO	MOSI_3	SDA_6	Rx2_3		PWM3_3
PT2.4	INT2.4	DIO	TCI1_7	LS_XOUT	CS_4	SCL_7	Tx_4		PWM0_4
PT2.5	INT2.5	DIO	TCI2_7	LS_XIN	CK_4	SDA_7	Rx_4		PWM1_4
PT2.6	INT2.6	DIO	TCI1_8	HS_XIN	MISO_4	SCL_8	Tx2_4		PWM2_4
PT2.7	INT2.7	DIO	TCI2_8	HS_XOUT	MOSI_4	SDA_8	Rx2_4		PWM3_4
PT3.0	INT3.0	DIO		ECK					
PT3.1	INT3.1	DIO		EDIO					
PT3.2	INT3.2	DIOAI						AIO4	
PT3.3	INT3.3	DIOAI						AIO5	
PT3.4	INT3.4	DIOAI						AIO6	
PT3.5	INT3.5	DIOAI						AIO7	
PT3.6	INT3.6	DIOAIO						REFO	
PT3.7	INT3.7	DIOAI						AIO8/LVDIN	
AIO0		AI						AIO0	
AIO1		AI						AIO1	
AIO2		AI						AIO2	
AIO3		AI						AIO3	
PT13.0		DIOAO		COM 0					
PT13.1		DIOAO		COM 1					
PT13.2		DIOAO		COM 2					
PT13.3		DIOAO		COM 3					

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



Function	INT	GPIO	Timer C Capture	Special Function	SPI	I ² C	UART	Analog	Timer B/B2 PWM
Output Priority	I/P	I/P	I/P	0	1	2	3	4	5
PT13.4		DIOAO		COM 4/SEG 0					
PT13.5		DIOAO		COM 5/SEG 1					
PT13.6		DIOAO		COM 6/SEG 42					
PT13.7		DIOAO		COM 7/SEG 43					
PT6.0		DIOAO	TCI3_1	SEG 2	CS_5		Tx_5		PWM0_5
PT6.1		DIOAO		SEG 3	CK_5		Rx_5		PWM1_5
PT6.2		DIOAO	TCI3_2	SEG 4	MISO_5		Tx2_5		PWM2_5
PT6.3		DIOAO		SEG 5	MOSI_5		Rx2_5		PWM3_5
PT6.4		DIOAO		SEG 6					
PT6.5		DIOAO		SEG 7					
PT6.6		DIOAO		SEG 8					
PT6.7		DIOAO		SEG 9					
PT7.0		DIOAO		SEG 10					
PT7.1		DIOAO		SEG 11					
PT7.2		DIOAO		SEG 12					
PT7.3		DIOAO		SEG 13					
PT7.4		DIOAO	TCI3_3	SEG 14	CS_6		Tx_6		PWM0_6
PT7.5		DIOAO		SEG 15	CK_6		Rx_6		PWM1_6
PT7.6		DIOAO	TCI3_4	SEG 16	MISO_6		Tx2_6		PWM2_6
PT7.7		DIOAO		SEG 17	MOSI_6		Rx2_6		PWM3_6
PT8.0		DIOAO		SEG 18	CS_8		Tx_8		PWM0_8
PT8.1		DIOAO		SEG 19	CK_8		Rx_8		PWM1_8
PT8.2		DIOAO		SEG 20	MISO_8		Tx2_8		PWM2_8
PT8.3		DIOAO		SEG 21	MOSI_8		Rx2_8		PWM3_8
PT8.4		DIOAO		SEG 22					
PT8.5		DIOAO		SEG 23					
PT8.6		DIOAO		SEG 24					
PT8.7		DIOAO		SEG 25					
PT9.0		DIOAO	TCI3_5	SEG 26	CS_7		Tx_7		PWM0_7
PT9.1		DIOAO		SEG 27	CK_7		Rx_7		PWM1_7
PT9.2		DIOAO	TCI3_6	SEG 28	MISO_7		Tx2_7		PWM2_7
PT9.3		DIOAO		SEG 29	MOSI_7		Rx2_7		PWM3_7
PT9.4		DIOAO		SEG 30					
PT9.5		DIOAO		SEG 31					

HY16F3913

21-bit ENOB $\Sigma\Delta$ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



Function	INT	GPIO	Timer C Capture	Special Function	SPI	I ² C	UART	Analog	Timer B/B2 PWM
Output Priority	I/P	I/P	I/P	0	1	2	3	4	5
PT9.6		DIOAO		SEG 32					
PT9.7		DIOAO		SEG 33					
PT10.0		DIOAO		SEG 34					
PT10.1		DIOAO		SEG 35					
PT10.2		DIOAO		SEG 36					
PT10.3		DIOAO		SEG 37					
PT10.4		DIOAO	TCI3_7	SEG 38					
PT10.5		DIOAO		SEG 39					
PT10.6		DIOAO	TCI3_8	SEG 40					
PT10.7		DIOAO		SEG 41					

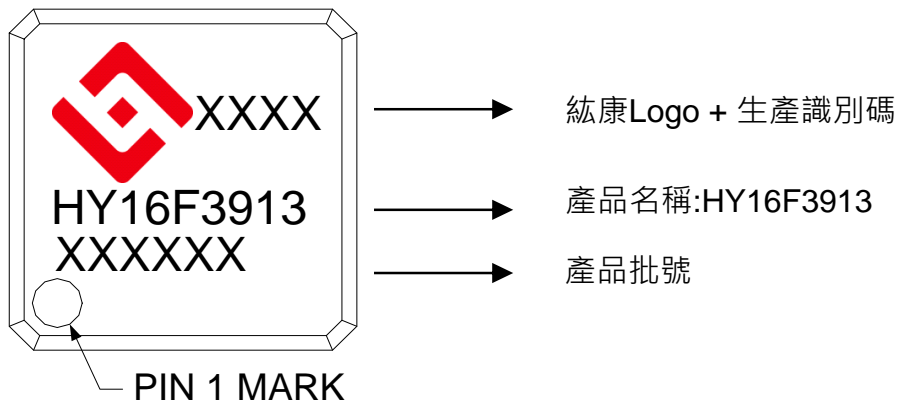
表 2-2 引腳複用功能及優先級描述

HY16F3913

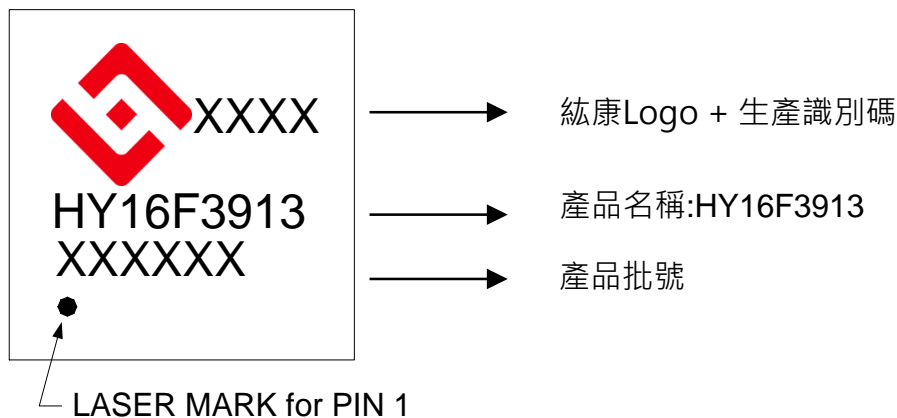
21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

2.5. 封裝片標記訊息

2.5.1. LQFP 封裝片標記訊息



2.5.2. QFN 封裝片標記訊息



HY16F3913

21-bit ENOB $\Sigma\Delta$ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



3. 應用電路

3.1. HCT 血醣儀應用電路

※BIA Module 相關應用之詳細資料請洽紘康科技聯繫窗口

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4. 功能概述

4.1. 内部框图

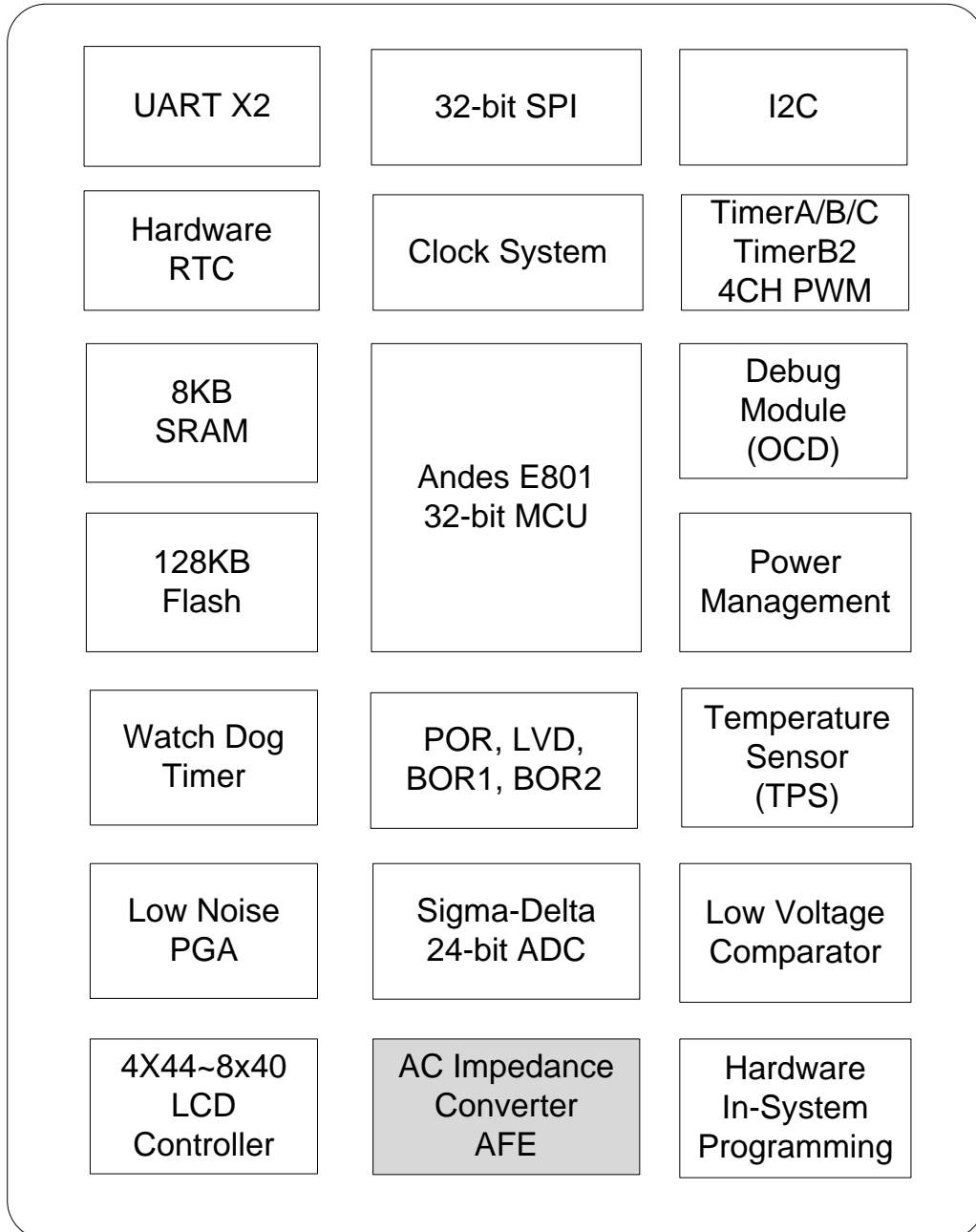


圖4-1 HY16F3913 内部框图

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4.2. 中央處理器核心方框圖

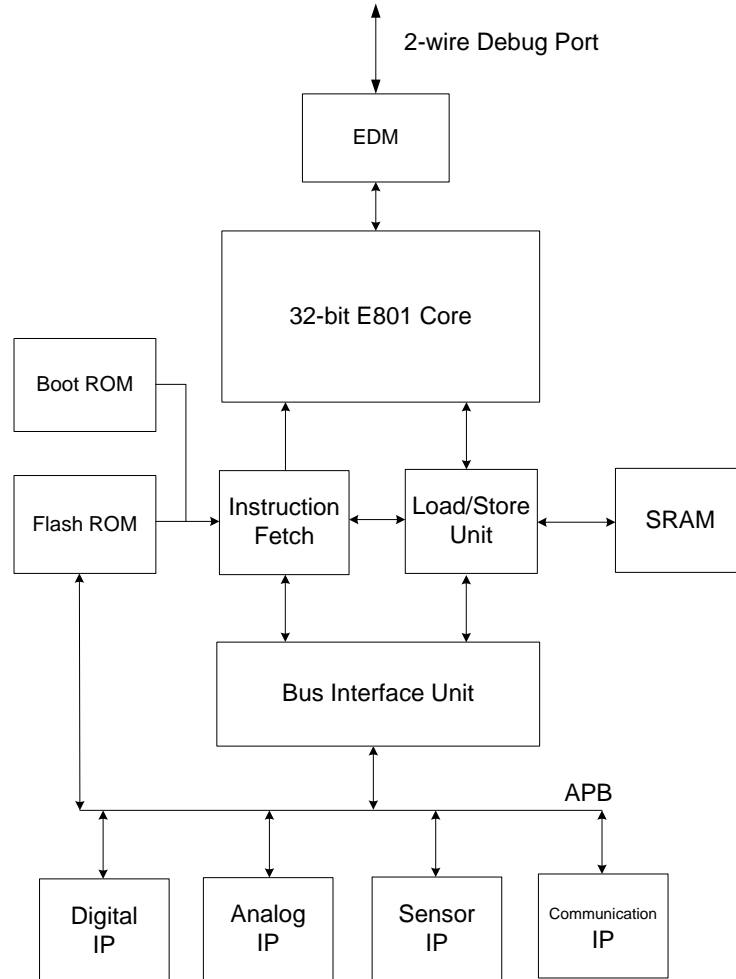


圖4-2 中央處理器核心方框圖

4.3. 相關的支援文檔

檔案名稱	描述
DS-HY16F3913	HY16F3913 系列規格書
UG-HY16F3913	HY16F3913 系列用戶手冊
APD-HY16F39IDE0xx	HY16F3913 系列 C 函數庫手冊
APD-HY16F39IDE0xx	HY16F3913 系列各 IP 使用說明書
APD-HY16IDE030	AndeSight_RDS_V3xx IDE 軟體使用說明書
APD-HY16F39IDE0xx	HY16F3913 系列開發工具硬體使用說明書
APD-HY16IDE006	HY16 系列燒錄器軟體使用說明書
APD-HYIDE020	HY10000-WK09 整合型燒錄器硬體使用說明書

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4.4. 時鐘系統網絡

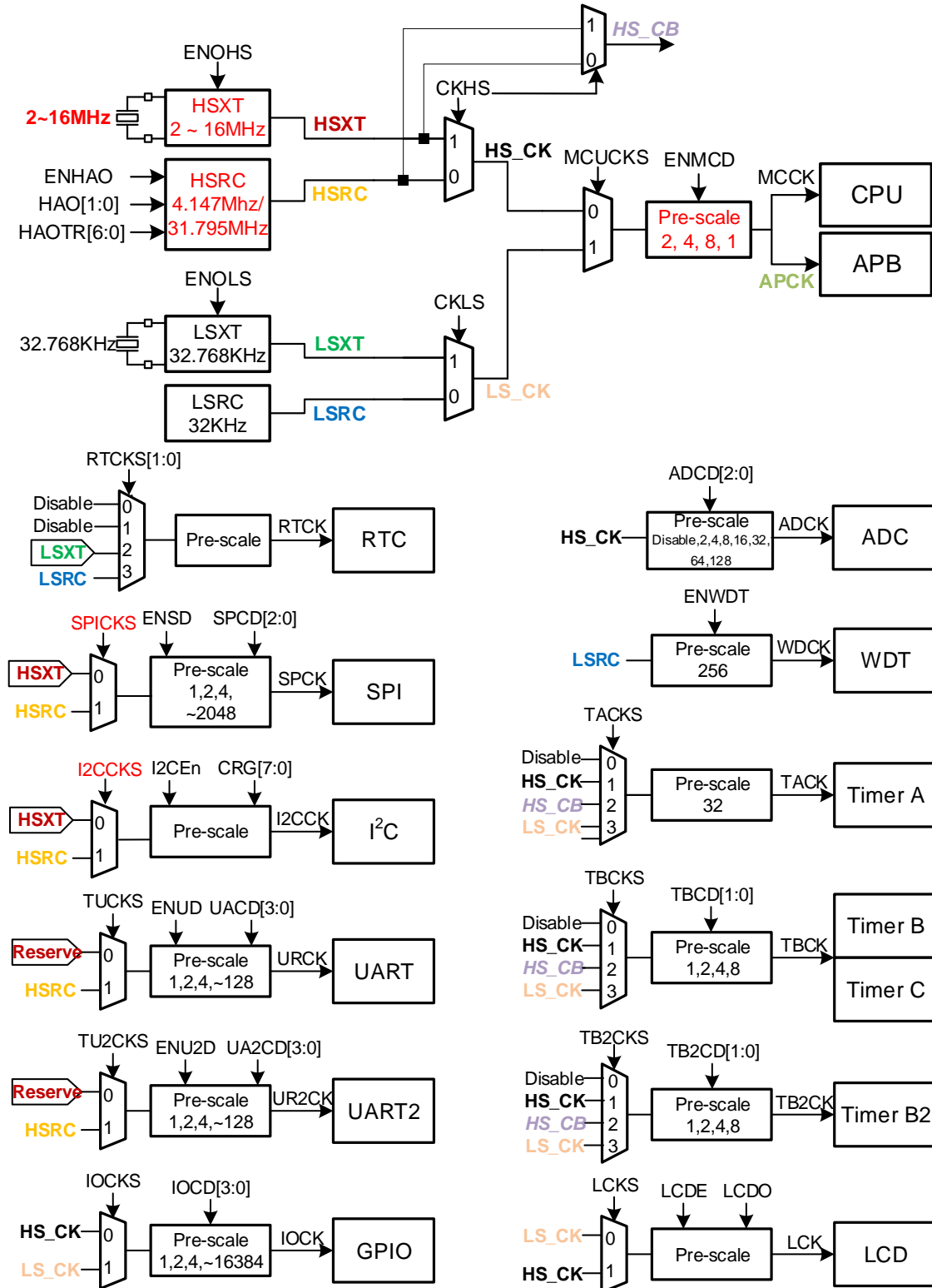


圖 4-3 時鐘系統網路方框圖

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4.5. 電源系統網絡

4.5.1. MCU-電源系統網絡

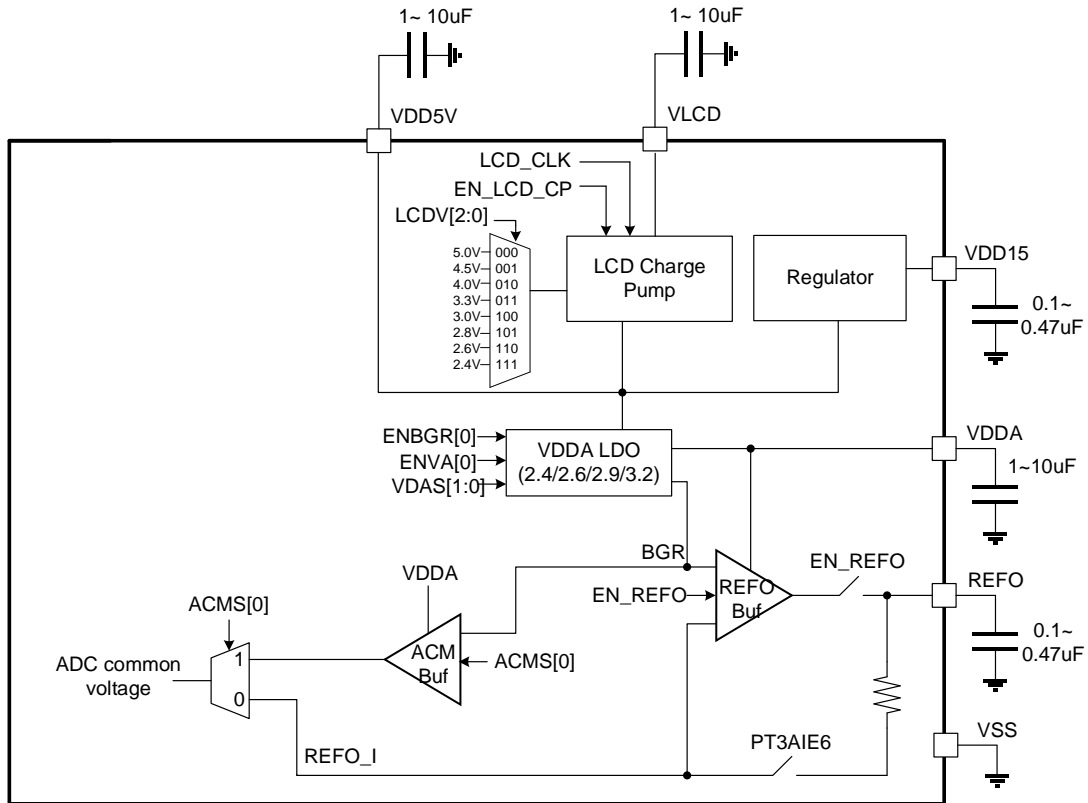


圖4-4 MCU-電源系統網絡方框圖

4.5.2. 交流阻抗量測類比前端-電源系統網絡

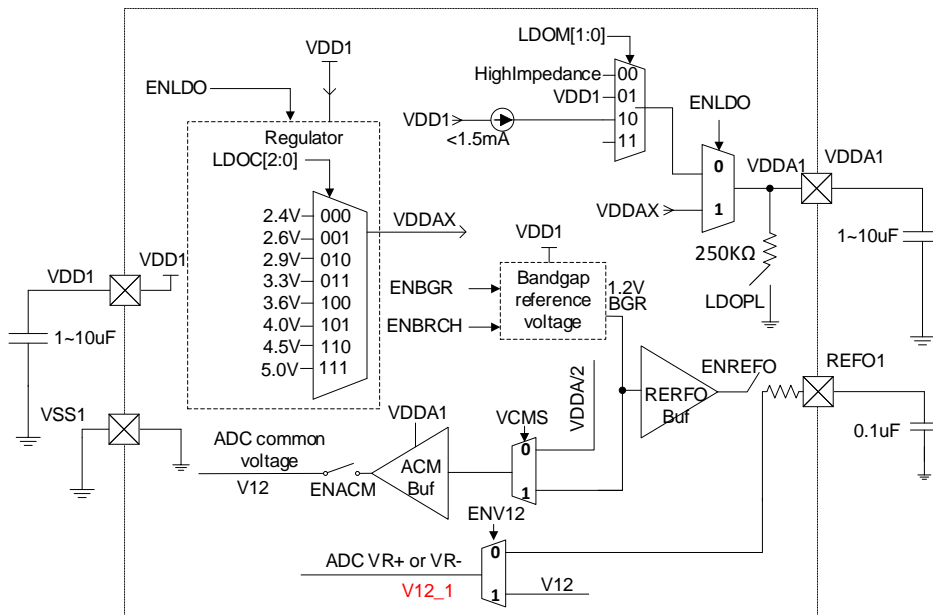


圖4-5 AFE-電源系統網絡方框圖

HY16F3913

21-bit ENOB $\Sigma\Delta$ ADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



4.6. 24-bit $\Sigma\Delta$ ADC 網路

4.6.1. MCU-24-bit $\Sigma\Delta$ ADC 網路

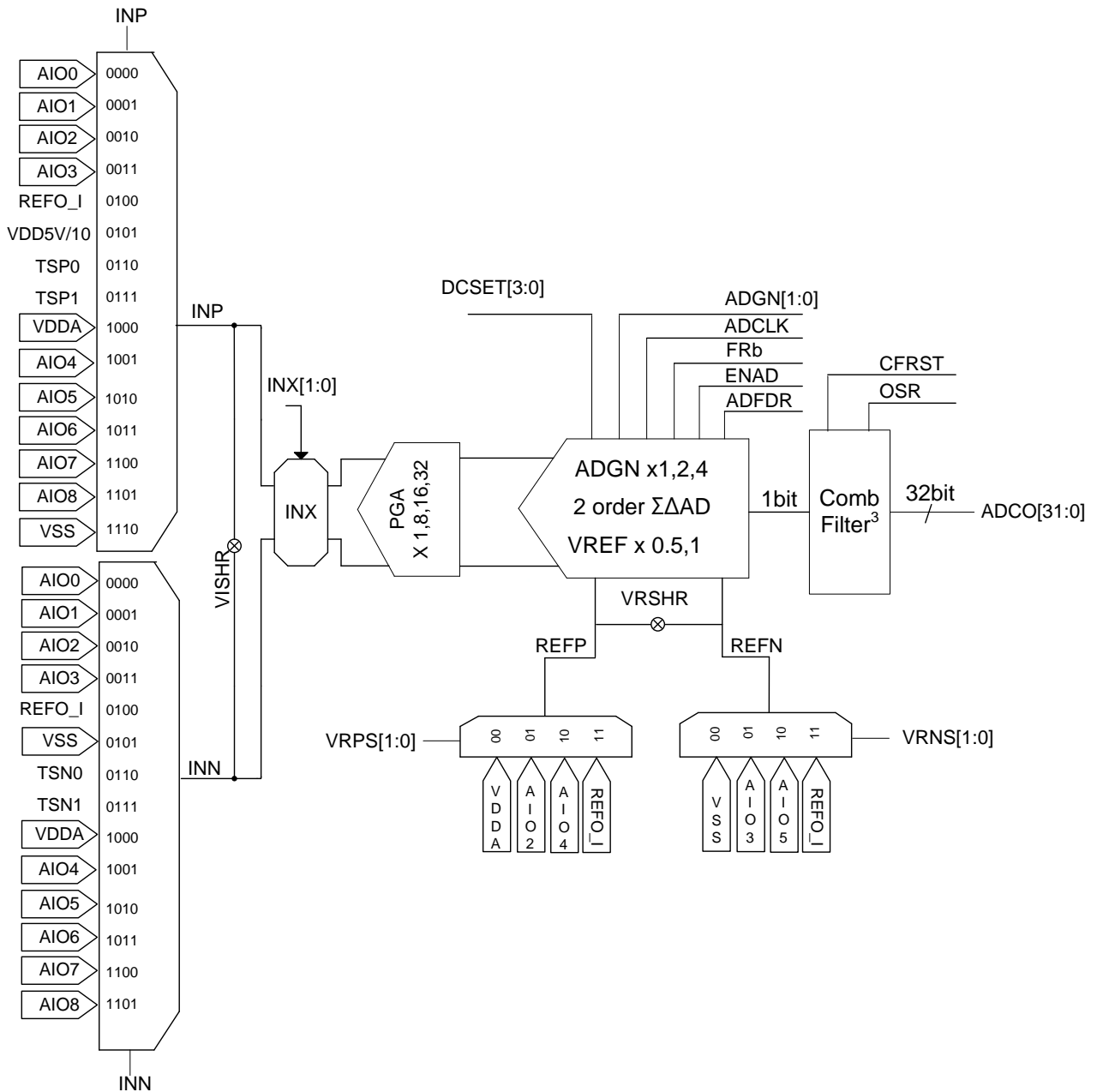


圖4-6 MCU-24-bit $\Sigma\Delta$ ADC網路方框圖

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



4.6.2. 交流阻抗量測類比前端-24-bit ΣADC 網路

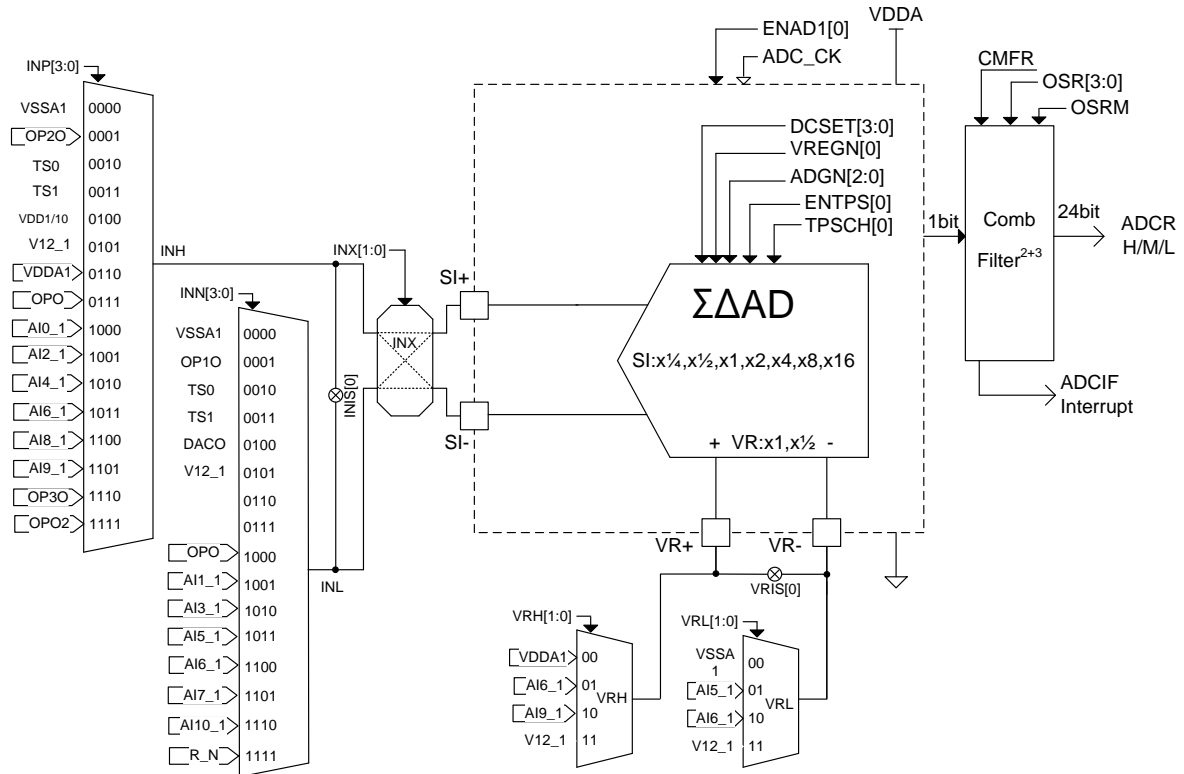


圖4-7 AFE-24-bit ΣADC網路方框圖

4.7. 低電壓比較器網路

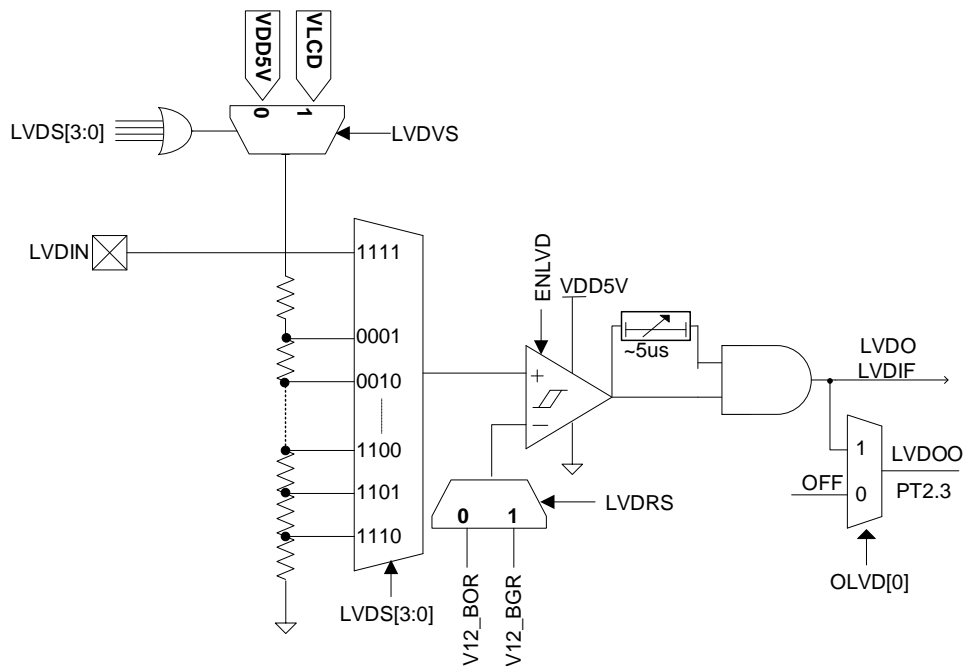


圖4-8 低電壓比較器網路方框圖

4.8. 看門狗(WDT)網路

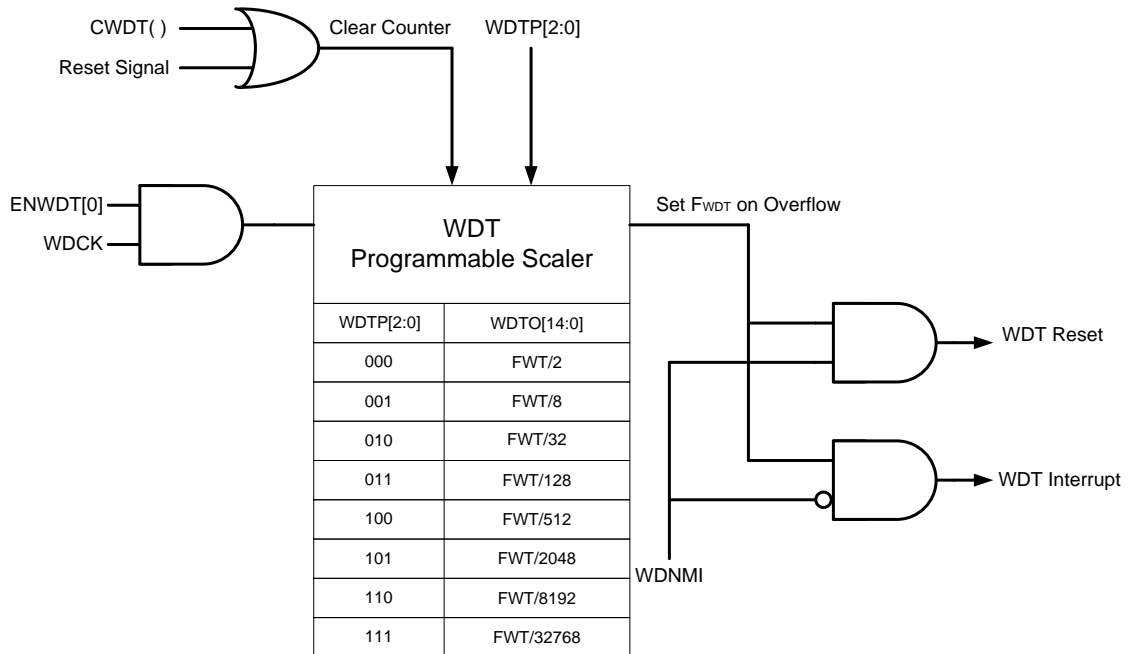


圖4-9 看門狗(WDT)網路方框圖

4.9. 定時計數器 A 網路

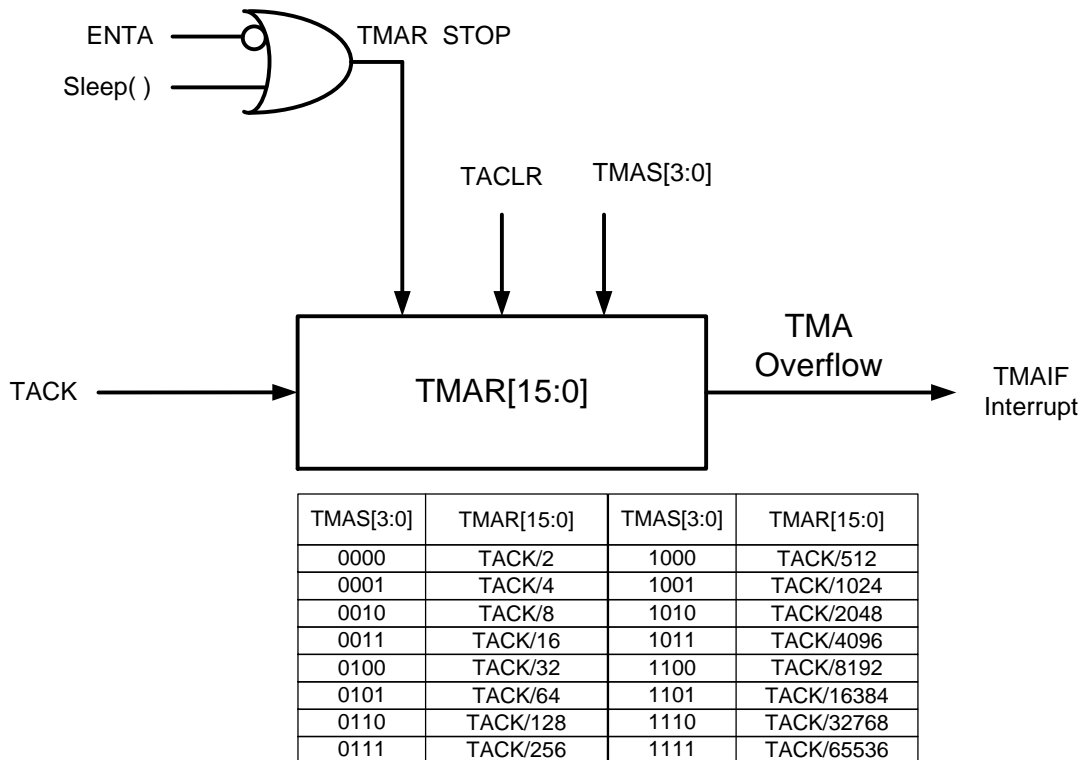


圖4-10 定時計數器A網路方框圖

4.10. 定時計數器 B 網路

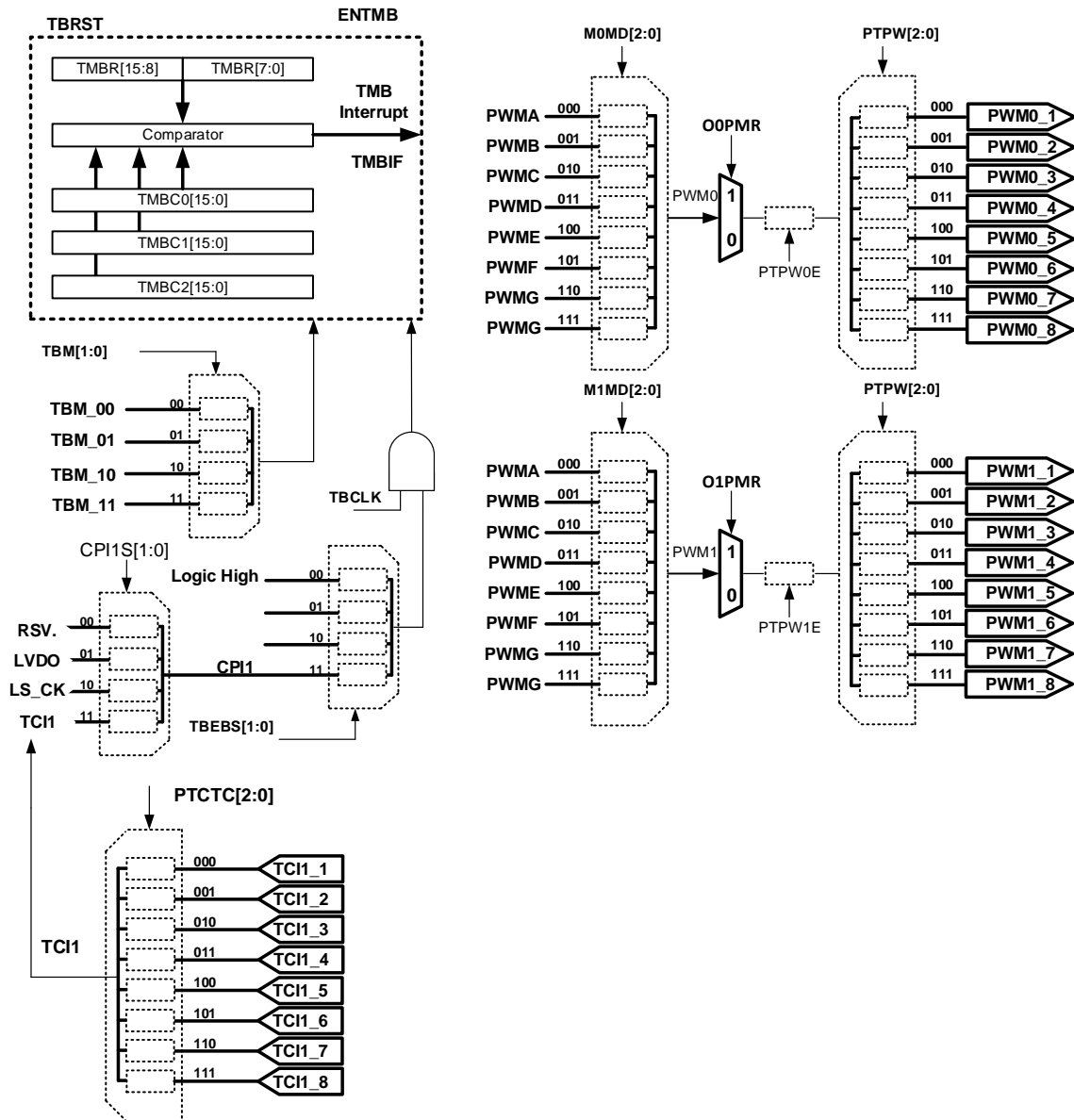


圖4-11 定時計數器B網路方框圖

4.11. 定時計數器 C 網路

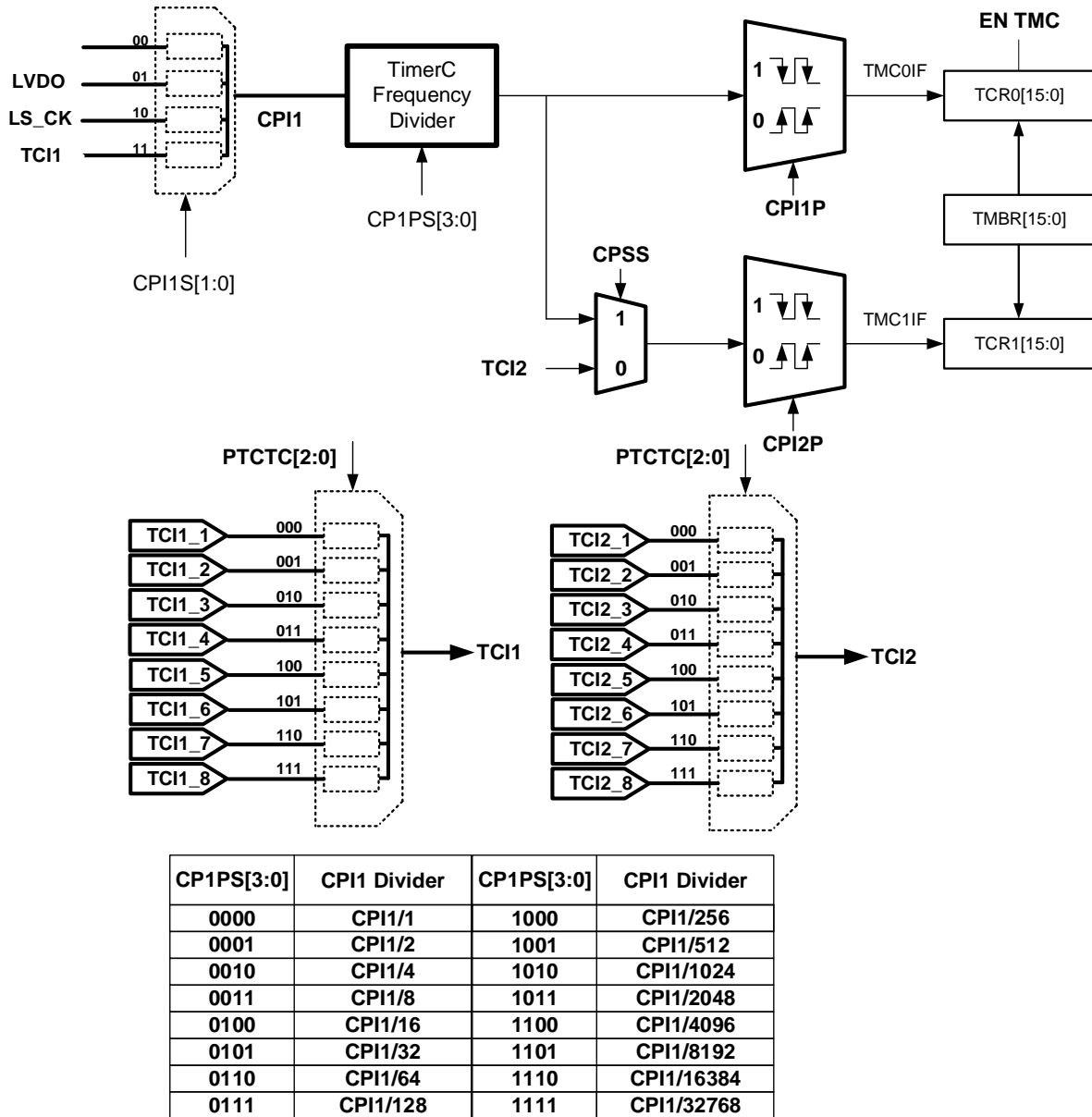


圖4-12 定時計數器C網路方框圖

4.12. 定時計數器 B2 網路

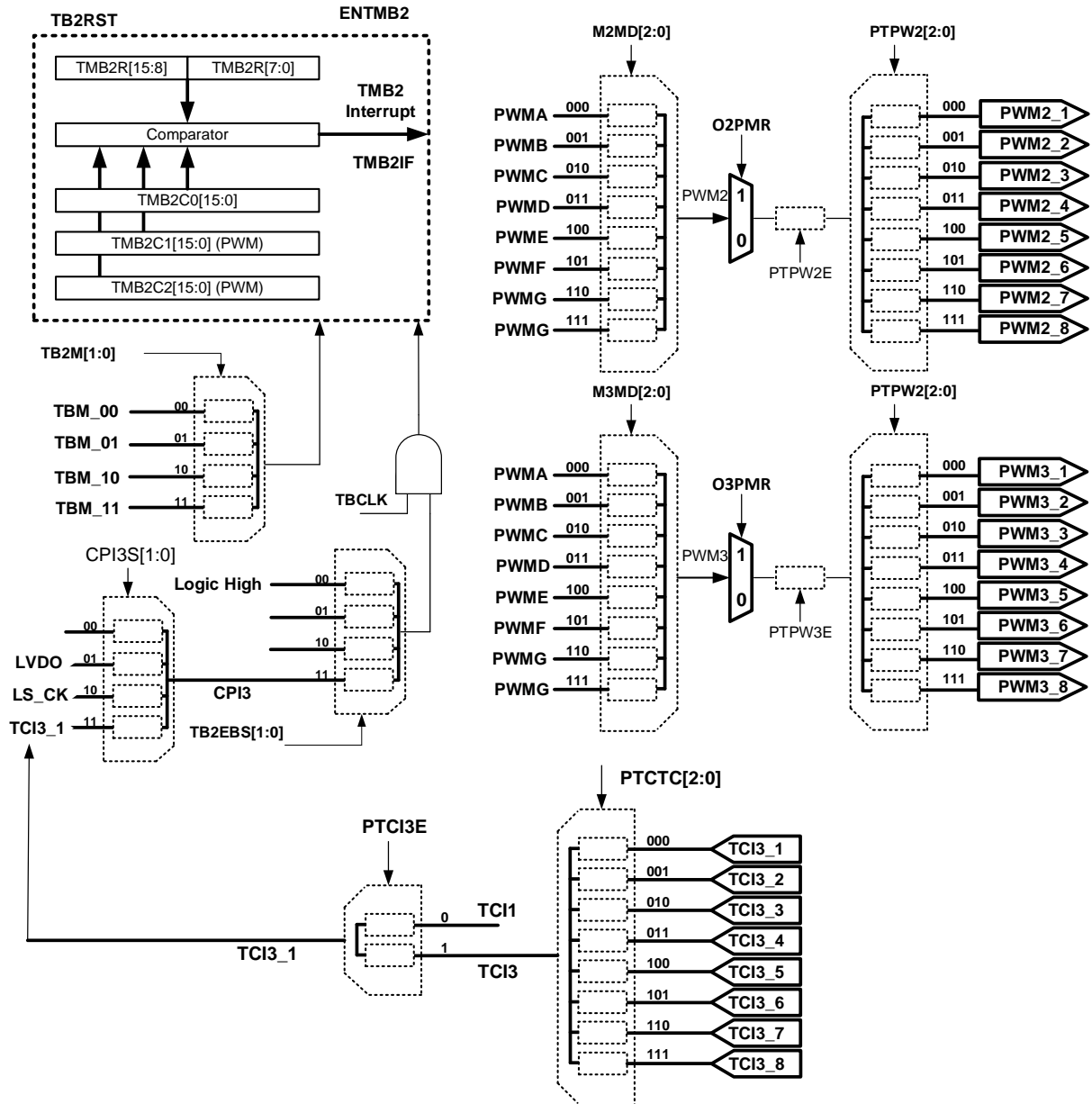


圖4-13 定時計數器B2網路方框圖

4.13. 32-bit SPI 網路

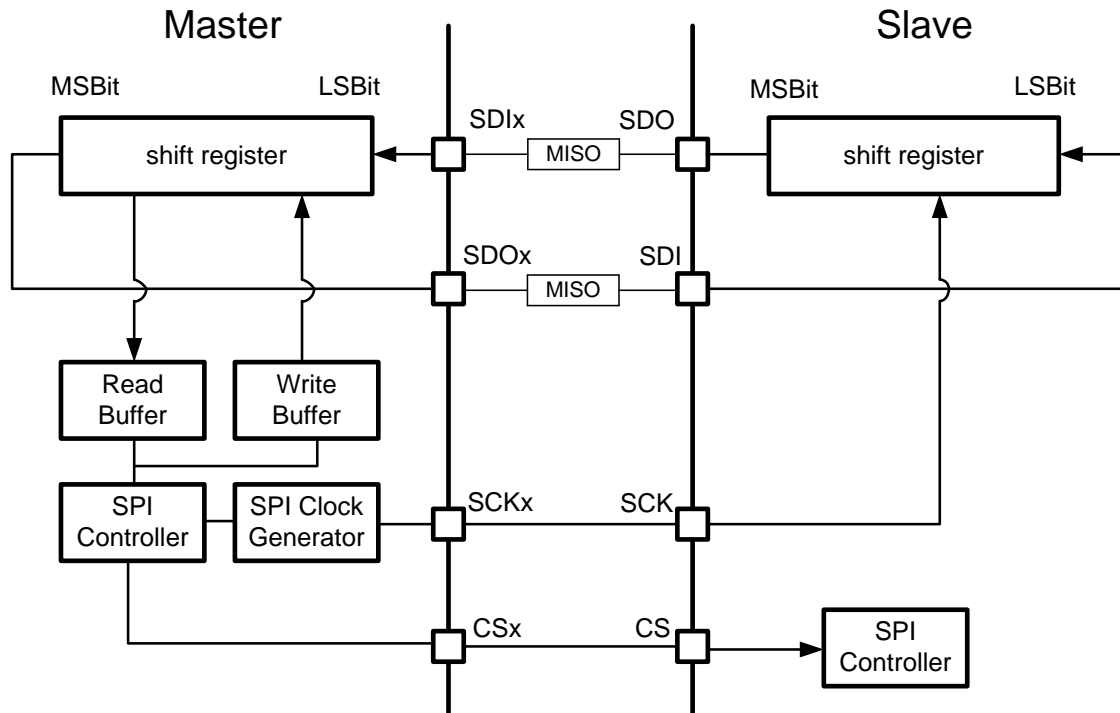


圖4-13 32-bit SPI網路方框圖

4.14. UART1/UART2 網路

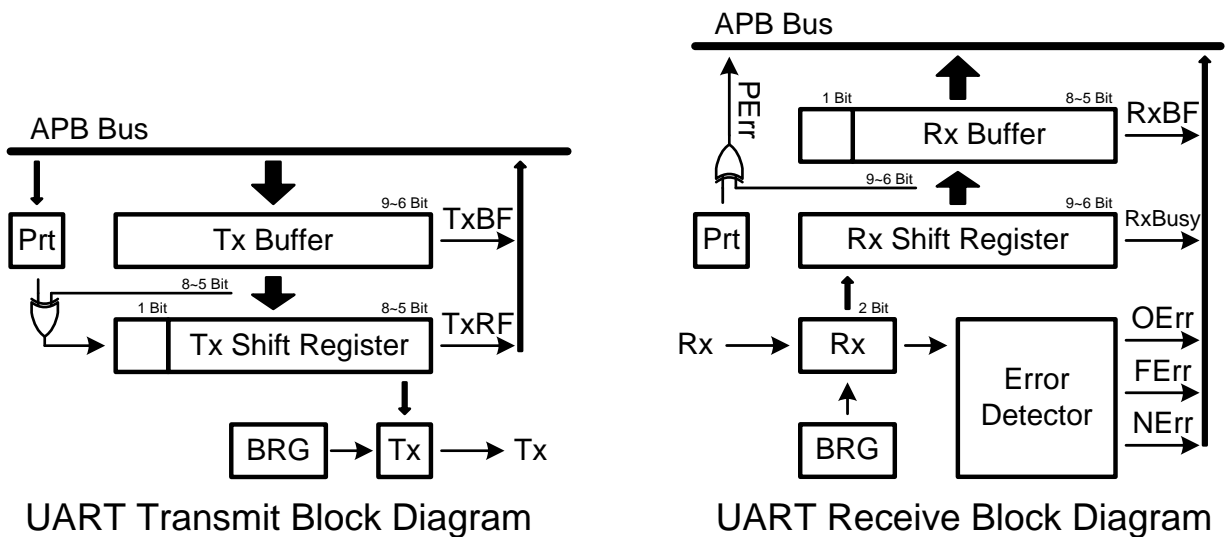


圖4-14 UART1/UART2網路方框圖

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



4.15. I²C 網路

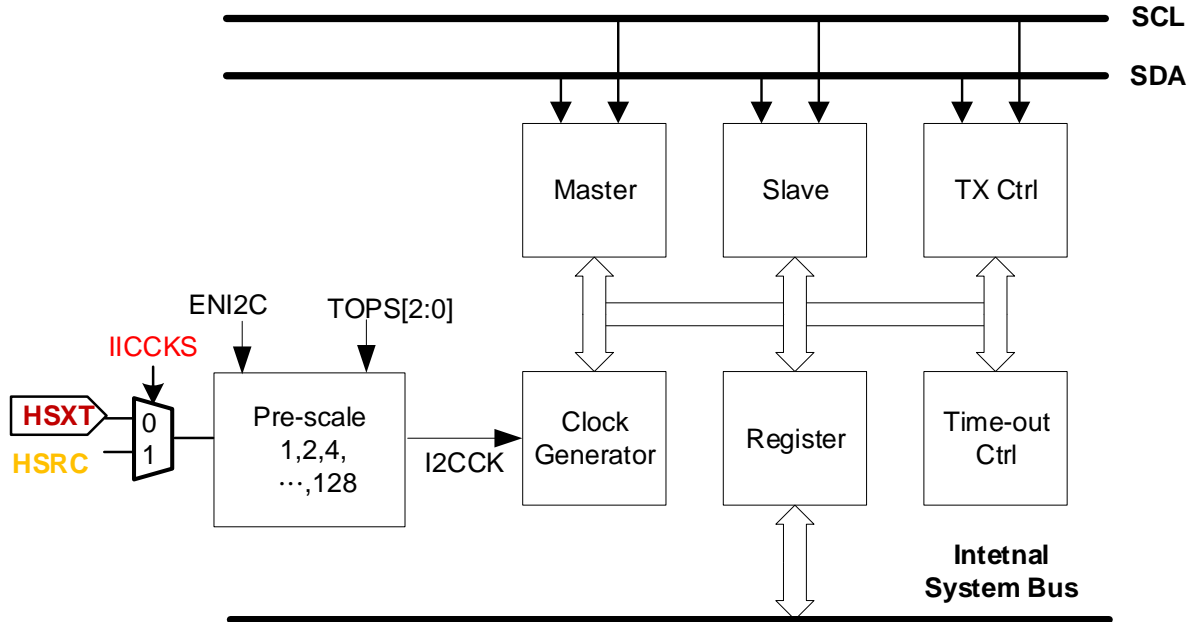


圖4-15 I²C網路方框圖

4.16. 硬體萬年曆 RTC 網路

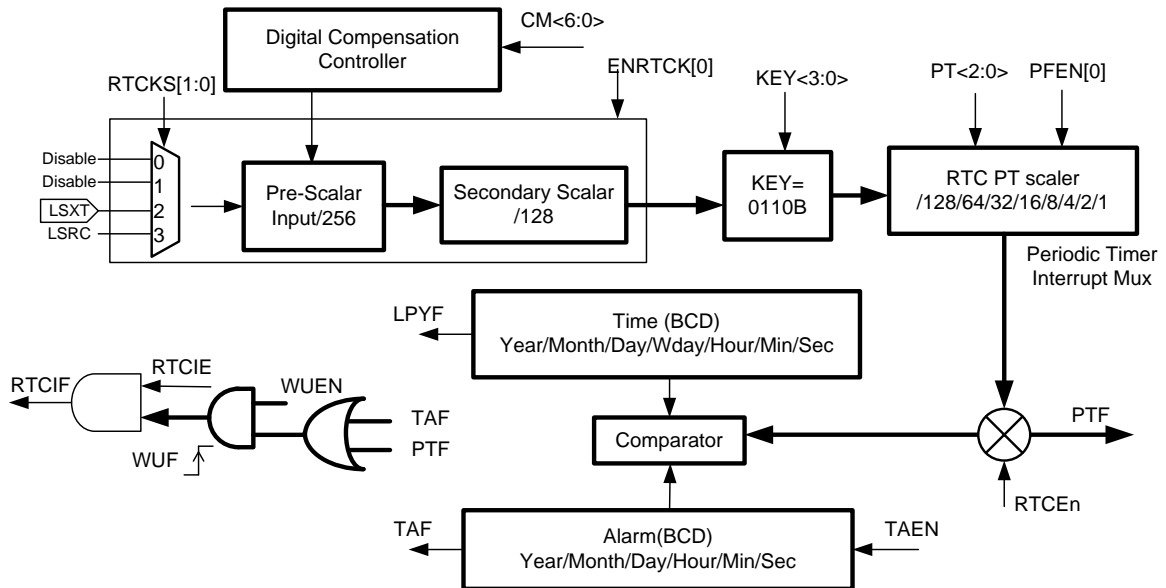


圖4-16 硬體萬年曆RTC網路方框圖

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4.17. LCD 網路

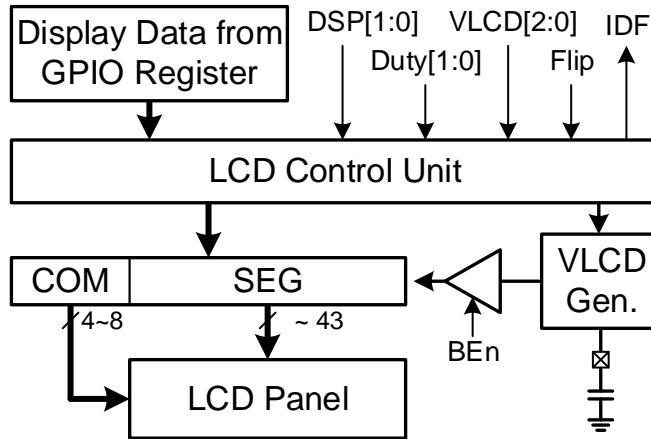


圖4-17 LCD網路方框圖

4.18. Reset/BOR1/BOR2 網路

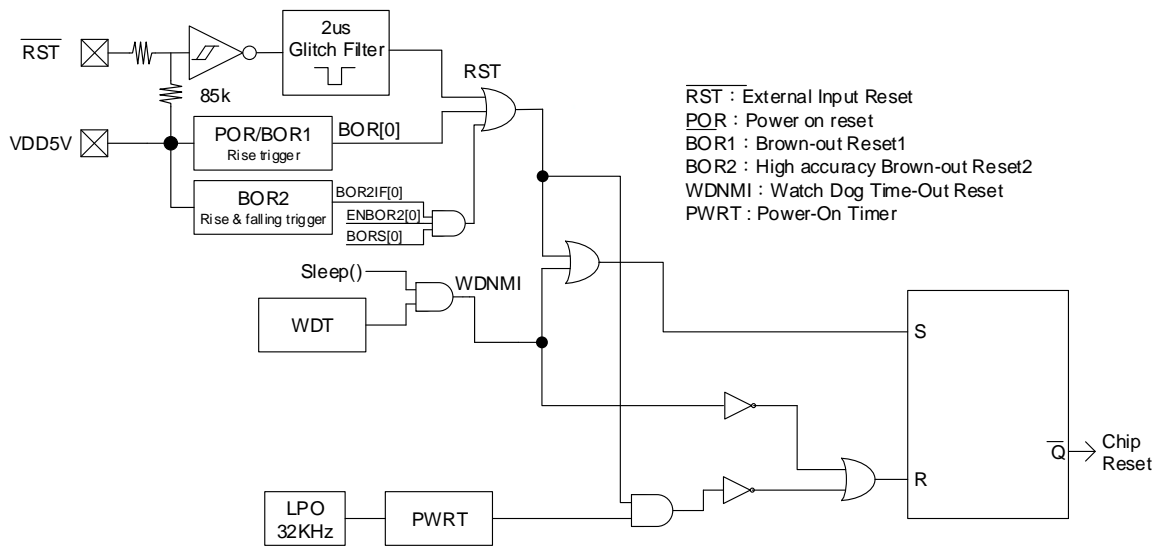


圖4-18 Reset/BOR1/BOR2網路方框圖

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

4.19. GPIO

4.19.1. MCU-Port 1~2 網路

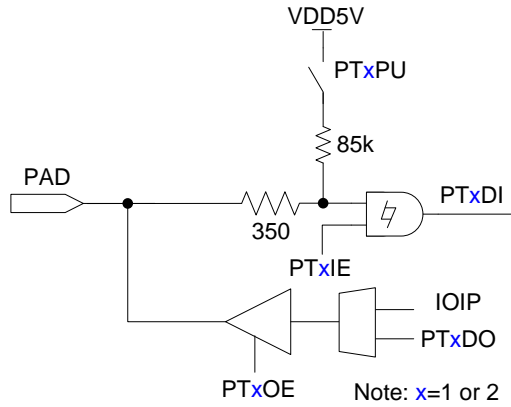


圖4-19 MCU-Port 1~2網路方框圖

4.19.2. MCU-Port3 網路

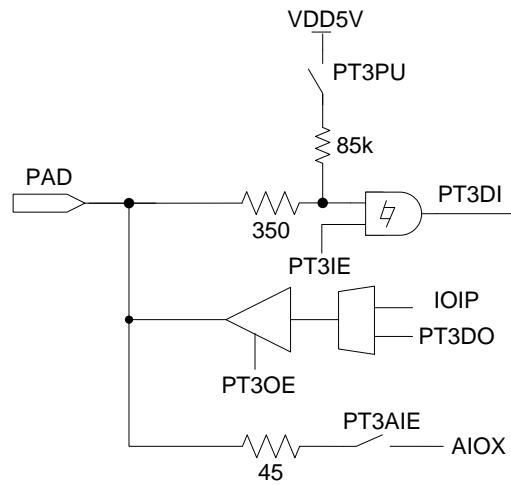


圖4-20 MCU-Port3網路方框圖

4.19.3. MCU-Port6~10、Port13 網路

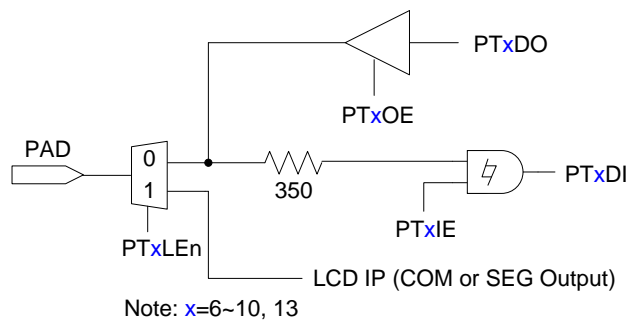


圖4-21 MCU-Port 6~10、Port13網路方框圖

4.19.4. 交流阻抗量測類比前端-PORT CLKOUT/IRQ/AI9_1 網路

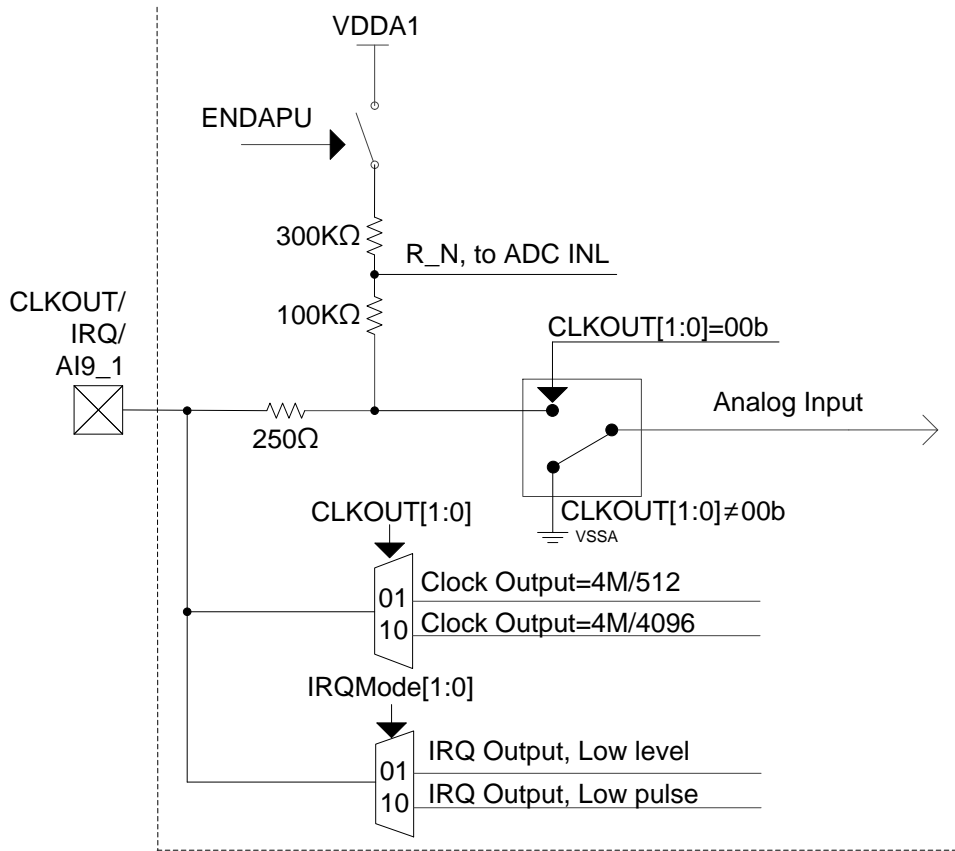


圖4-22 AFE-PORT CLKOUT/IRQ/AI9_1網路方框圖

4.20. 交流阻抗量測類比前端-12-bit DAC I 網路

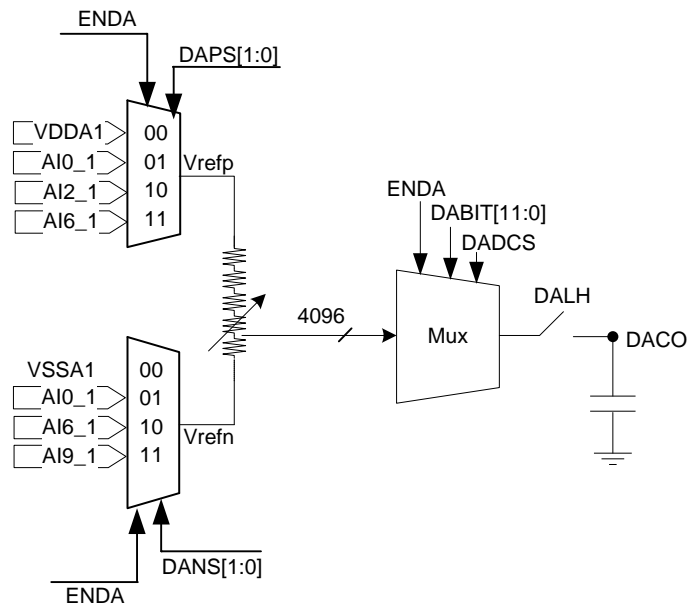


圖4-23 AFE-12-bit DAC I網路方框圖

4.21. 交流阻抗量測類比前端-12-bit DAC II 網路

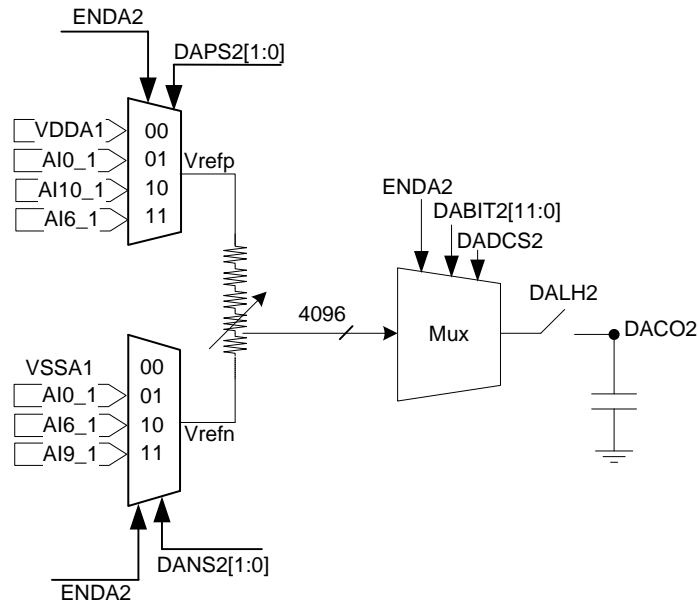


圖4-24 AFE-12-bit DAC II網路方框圖

4.22. 交流阻抗量測類比前端-Rail to Rail OPAMP1 網路

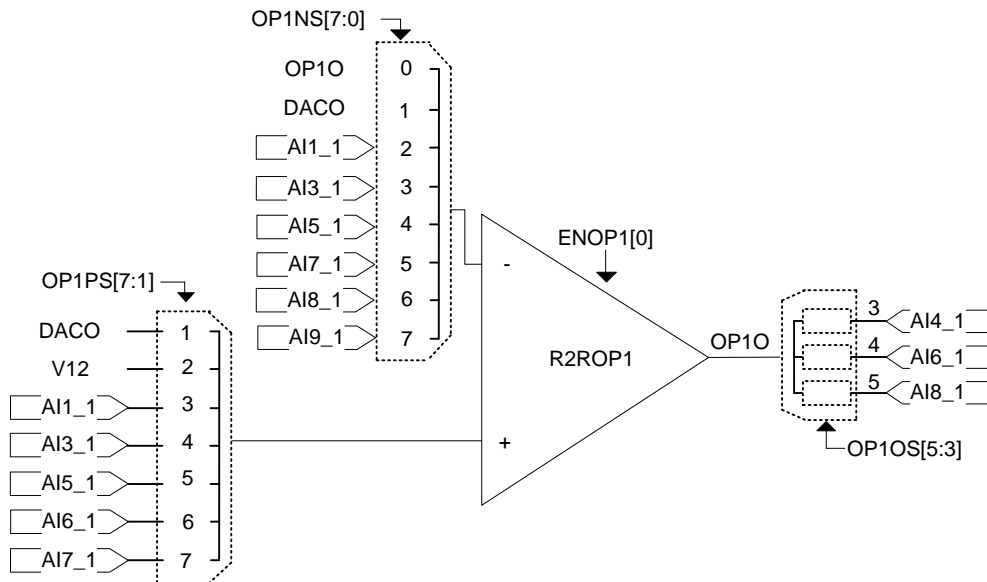


圖4-25 AFE-Rail to Rail OPAMP1網路方框圖

4.23. 交流阻抗量測類比前端-Rail to Rail OPAMP2 網路

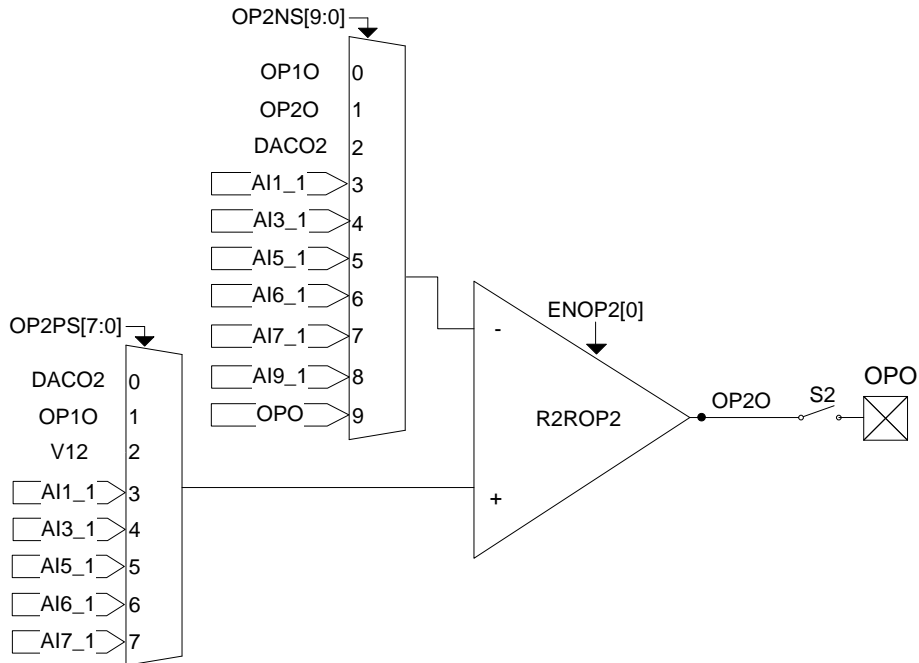


圖4-26 AFE-Rail to Rail OPAMP2網路方框圖

4.24. 交流阻抗量測類比前端-Rail to Rail OPAMP3 網路

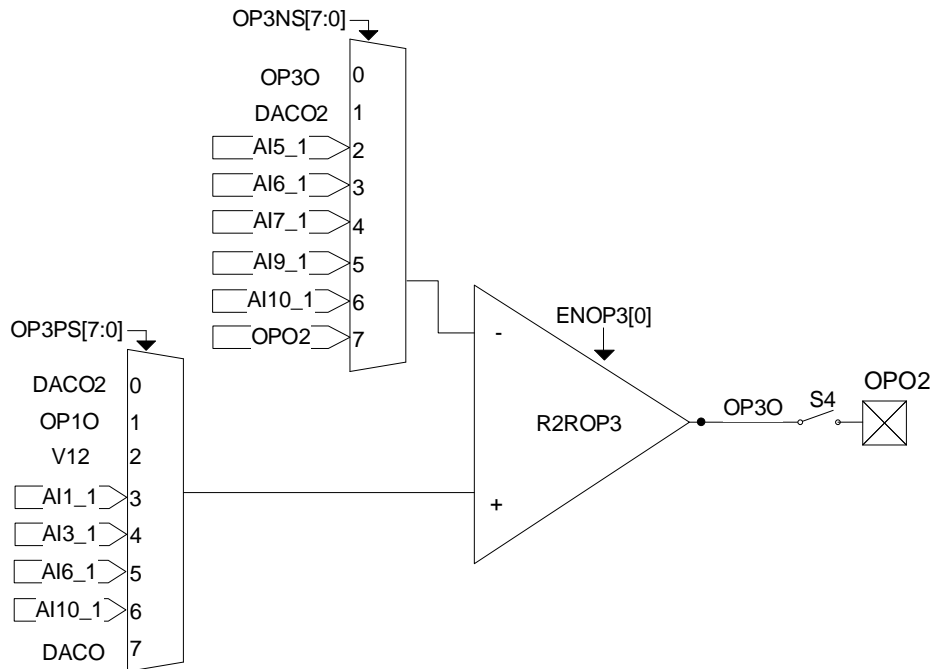


圖4-27 AFE-Rail to Rail OPAMP3網路方框圖

4.25. 交流阻抗量測類比前端-BIA Module 網路

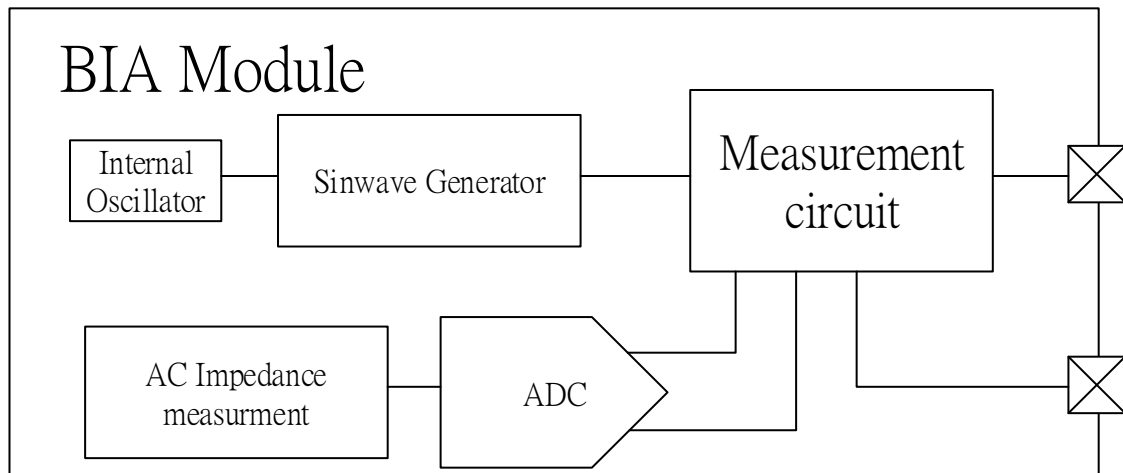


圖4-27 AFE-BIA Module網路方框圖

※BIA Module 詳細資料請洽紘康科技聯繫窗口

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5. 電氣特性

5.1. MCU Electrical Characteristics

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at VDD5V to VSS	-0.2 V to 6.0 V
Voltage applied to any pin	-0.2 V to VDD5V + 0.3 V
Diode current at any device terminal.....	±2mA
Storage temperature, Tstg: (UN programmed device)	-55°C to 150°C
(Programmed device)	-40°C to 85°C
Soldering Temperature (10 Sec)	+260°C
Maximum output current sink by any PORT1 to PORT13 I/O PIN	20mA

5.1.1. Recommended Operating Conditions

VDD5V=3.0V.TA=25°C, Unless Otherwise Noted

Parameter	Sym.	Test Conditions	Min.	Typ.	Max.	Unit
Supply Voltage	VDD5V	Digital power	2.0		5.5	V
Supply Voltage	VDDA	Analog power	2.4		3.6	V
Supply Current	I_Sleep	Sleep Mode, @BOR2 OFF, VDD15 low power mode		1.8	4	uA
	I_Idle01	LSRC=32KHz, MCCK= LSRC/1, LSRC(LPO) IDLE Mode		4.5	8	uA
	I_Idle02	LSXT=32768Hz MCCK= LSRC/1, LSXT IDLE Mode		6	12	uA
	I_Idle03	HSRC=4.147MHz, MCCK= HSRC /1, HSRC IDLE Mode		80	120	uA
	I_Idle04	HSRC=31.795MHz, MCCK= HSRC /2, HSRC IDLE Mode		275	410	uA
	I_Free Run01	HSRC=4.147MHz, MCCK= HSRC/1		0.7		mA
	I_Free Run02	HSRC=31.795MHz, MCCK= HSRC /2,		2.5		mA
Power Up Delay	t _{PU,DLY}	Power on or wake up from sleep mode		4.1	7	ms

Note: HSRC=31.795MHz, MCCK= HSRC /2, CPU operate at VDD5V>=3V.

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.2. Clock System

Typical values are at $T_A=25^{\circ}\text{C}$ and $V_{DD5V} = 3.0\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
External High Speed Oscillator						
VDD5V	Operation voltage		2.0		5.5	V
F _{XHS}	High speed oscillator frequency	OHS_HS = 0b			4	MHz
		OHS_HS = 1b			8	MHz
		OHS_HS = 1b			16	MHz
I _{XHS}	High speed oscillator current	F _{XHS} = 16MHz, OHS_HS = 1b		130		uA
D _{XHS}	Duty of high oscillator		40		60	%
External Low Speed Oscillator						
F _{XLS}	Low speed oscillator frequency	VDD5V = 2.0V ~ 5.5V		32.768		KHz
I _{XLS}	Low speed oscillator current			2		uA
D _{XLS}	Duty of low speed oscillator		40		60	%
Internal High Speed Oscillator						
F _{HAO}	Internal high speed oscillator frequency	F _{HAO} = 4.147MHz, F _{HAO} = 4.147MHz, after trim	-10% -2%	4.147	+10% +2%	MHz
		F _{HAO} = 31.795MHz, F _{HAO} = 31.795MHz, after trim	-10% -2%	31.795	+10% +2%	MHz
		Voltage coefficient		1		%
T _{HAO}	Temperature coefficient	-40~85 $^{\circ}\text{C}$		5		%
I _{HAO}	Internal high speed oscillator current	F _{HAO} = 4.147MHz		50		uA
		F _{HAO} = 31.795MHz (VDD5V >= 3.0V)		180		uA
D _{HAO}	Duty of oscillator		40		60	%
WT _{HAO}	Wake up time	F _{HAO} = 4.147MHz		15		us
Internal Low Speed Oscillator						
F _{LPO}	Internal low speed oscillator frequency		-20%	32	+20%	KHz
	Voltage coefficient	VDD5V = 2.0V ~ 5.5V		1		%
T _{LPO}	Temperature coefficient	-40~85 $^{\circ}\text{C}$		5		%
I _{LPO}	Internal low speed oscillator current			2.5		uA
D _{LPO}	Duty of low speed oscillator		40		60	%

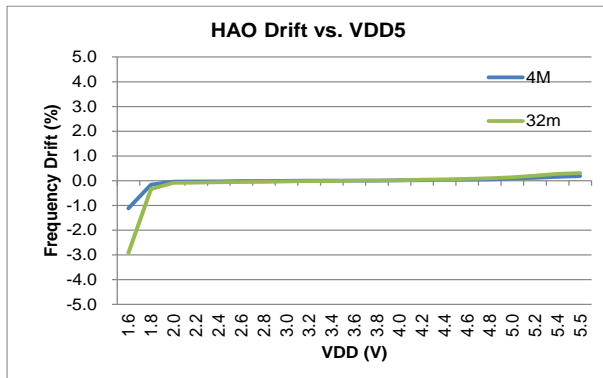


Figure5.1.2-1 HAO vs. VDD5

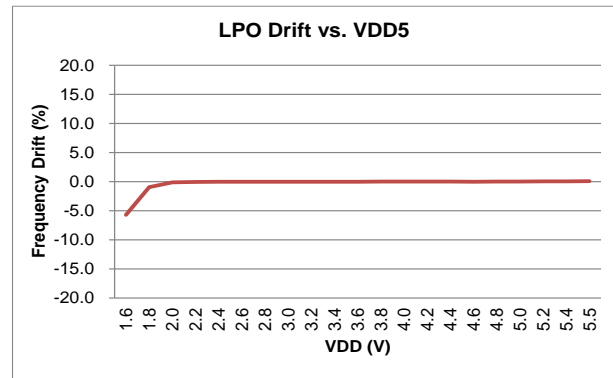


Figure5.1.2-2 LPO vs. VDD5

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

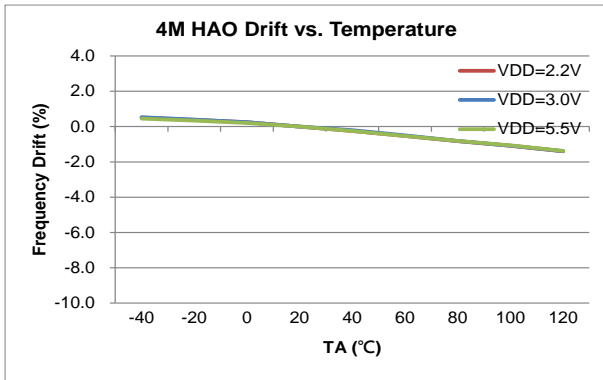


Figure5.1.2-3 HAO vs. Temperature

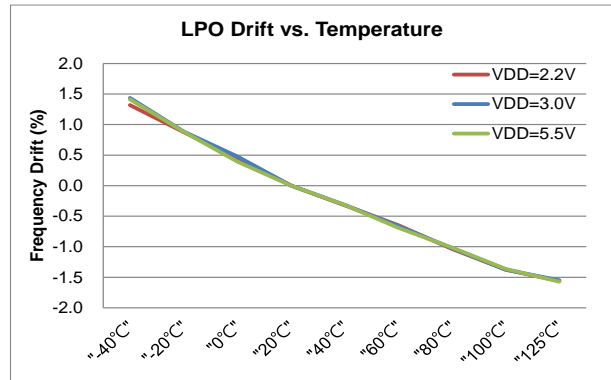


Figure5.1.2-4 LPO vs. Temperature

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.3. Power Management System

Typical values are at $T_A=25^\circ\text{C}$ and $V_{DD5V} = 3.0\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
VDDA LDO (Analog power)						
	Output voltage error		-5		5	%
	Capacitor loading		0.1	1	10	uF
	Settling time	Capacitor loading = 0.1uF, 99% of VDDA		100		us
	Operation current	Bias + Band gap + VDDA LDO		35	50	uA
	Dropout voltage	VDD=2.9V, VDAS[1:0]=10b, I _L =10mA		0.4		V
	Select VDDA output voltage, VDD=5.5V, I _L =0.1mA	VDAS[1:0]=00b	-5%	2.4	+5%	V
		VDAS[1:0]=01b		2.6		
		VDAS[1:0]=10b		2.9		
		VDAS[1:0]=11b		3.2		
	Select VDDA output voltage, VDD=2.6V, I _L =10mA	VDAS[1:0]=00b	-6%	2.4	+5%	V
	Voltage coefficient	VDD5V = 2.5 ~ 3.6V		0.2		%/V
		VDD5V = 3.6 ~ 5.5V		0.2		%/V
	Temperature coefficient			100		ppm/°C
VDD15 LDO (Digital Core power)						
	Output voltage		1.35	1.5	1.65	V
	Capacitor loading		0.1	0.47	1	uF
	Dropout voltage	Load = 10mA		0.2		V
	Voltage coefficient	VDD5V= 2.0 ~ 3.6V		0.5		%/V
		VDD5V= 3.6 ~ 5.5V		1		%/V
	Temperature coefficient			200		ppm/°C
REFO Buffer (Bnadgap reference Buffer)						
	Output voltage		1.1	1.2	1.3	V
	Capacitor loading		0.022	0.1	1	uF
	Operation current			20		uA
	Output current		-1		1	mA
	Temperature coefficient	VDDA=2.9 V		80		ppm/°C
	Voltage coefficient	VDDA= 2.4V ~ 3.6V		0.2		%/V

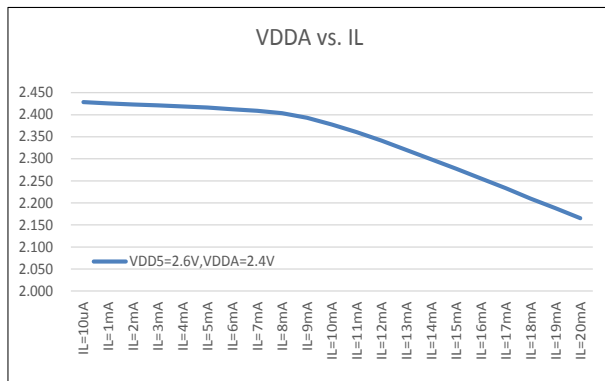


Figure5.1.3-1 VDDA vs. IL

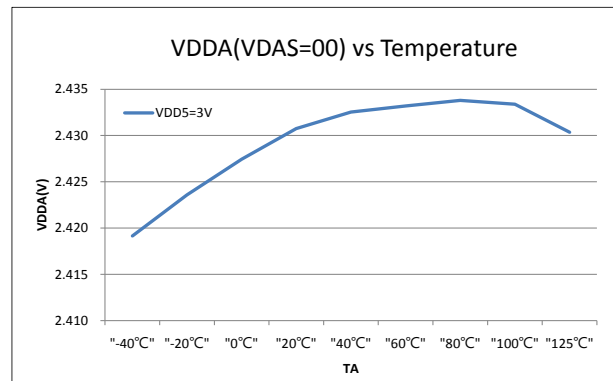


Figure5.1.3-2 VDDA vs. Temperature

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

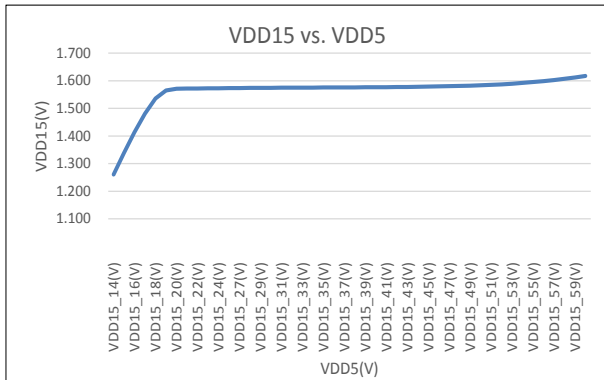


Figure5.1.3-3 VDD15 vs. VDD5

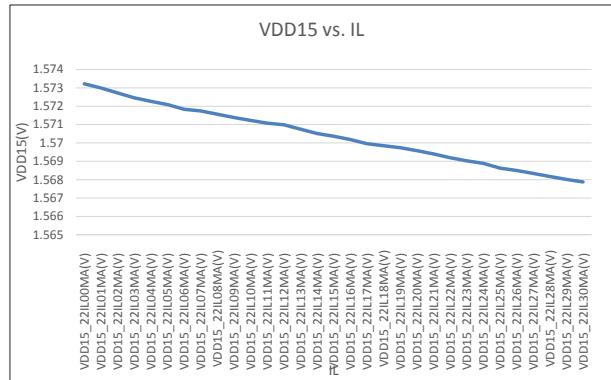


Figure5.1.3-4 VDD15 vs. IL

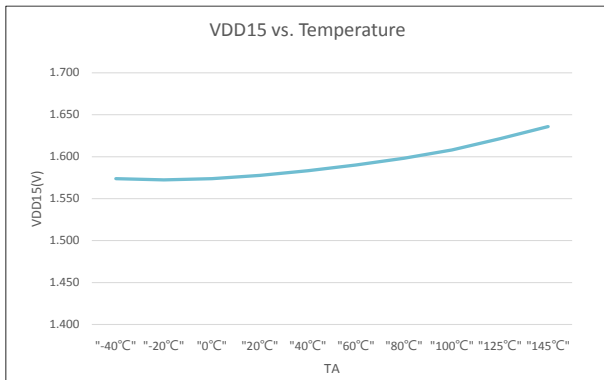


Figure5.1.3-5 VDD15 vs. Temperature

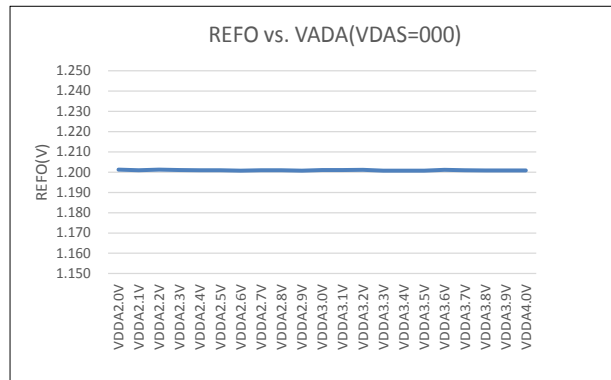


Figure5.1.3-6 REFO vs. VDDA

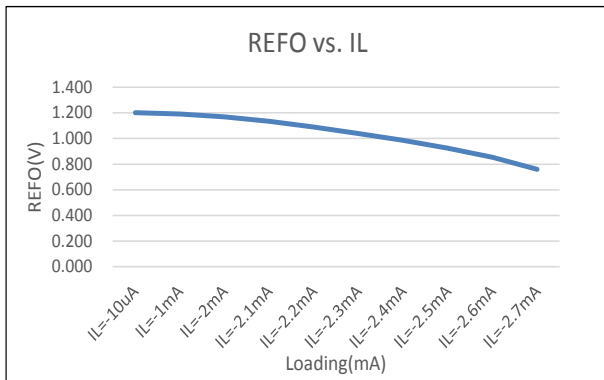


Figure5.1.3-7 REFO vs. IL

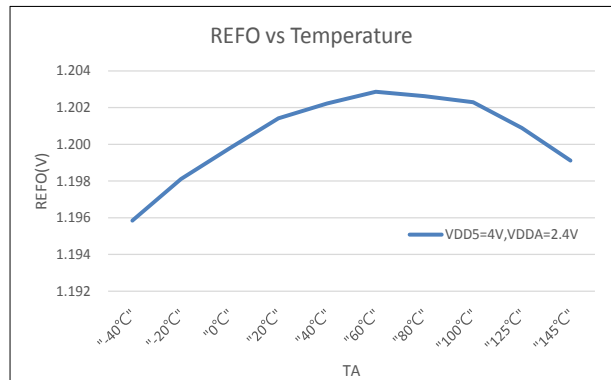


Figure5.1.3-8 REFO vs. Temperature

HY16F3913

21-bit ENOB ΣADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.4. Reset Management System

Typical values are at $T_A=25^{\circ}\text{C}$ and $V_{DD5V} = 3.0\text{V}$. Unless otherwise noted.

Sym.	Parameter	Min.	Typ.	Max.	Unit	
BOR1	Pulse length needed to accepted reset internally, t_{d-LVR}	2			us	
	V_{DD5V} Start Voltage to accepted reset internally ($H \rightarrow L$), V_{LVR1}	1.2	1.4	1.6	V	
	Temperature drift, $T_A=-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$		30		%	
	BOR1 current, I_{BOR1} , (include BOR1 and VDD15 LDO)		2.5	5	uA	
BOR2	Pulse length needed to accepted reset internally, t_{d-LVR2}	2			uS	
	V_{DD5V} Start Voltage to accepted reset internally ($L \rightarrow H$), V_{HYS2} , and BORTH[2:0]:	000b		1.7		V
		001b		2.0		
		010b		2.2		
		011b		2.5		
		100b		2.7		
		101b		3.0		
		110b		3.6		
		111b		4.0		
	V_{DD} Start Voltage to accepted reset internally ($H \rightarrow L$), V_{LVR2} , and BORTH[2:0]:	000b~111b	13%	$V_{HYS2}-0.06\text{V}$	13%	V
Hysteresis, $V_{HYS2-LVR2}$		60		mV		
BOR2 current, I_{BOR2}		10	15	uA		
Temperature Drift		5		%		
RST	Pulse length needed as RST pin to accepted reset internally, t_{d-RST}	2			us	
	Input Voltage to accepted reset voltage		1.1		V	
	Reset release voltage		1.6		V	

BOR1/BOR2 : Brownout Reset 1/2
RST : External Reset pin

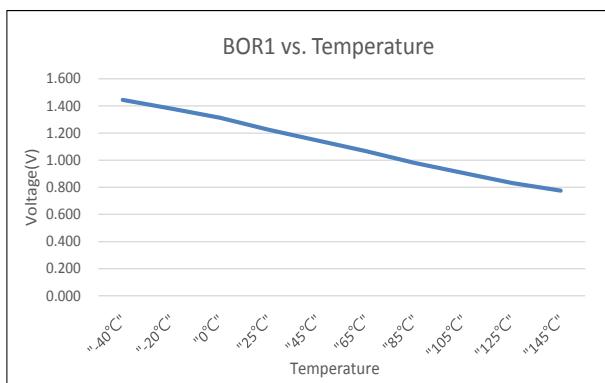


Figure5.1.4-1 BOR1 vs. Temperature

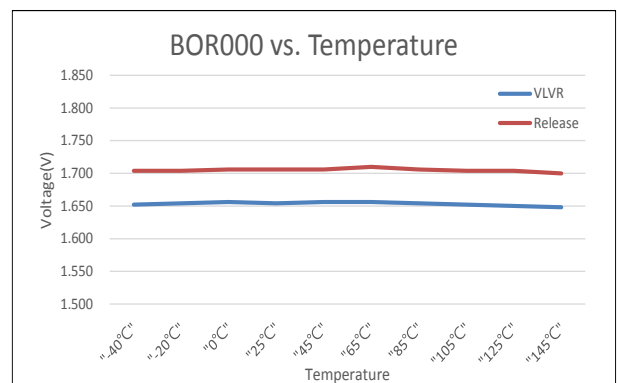


Figure5.1.4-2 BOR2 vs. Temperature

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.5. GPIO Port System

Typical values are at $T_A=25^{\circ}\text{C}$ and $V_{DD5V} = 3.3\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
PT 1 ~ 3 GPIO Port						
R_{PU}	Internal pull high resistor		65	85	105	kΩ
V_{IH}	Input high voltage		$0.75 \cdot V_{DD5V}$			V
V_{IL}	Input low voltage				$0.3 \cdot V_{DD5V}$	V
V_{hys}	Input Voltage hysteresis($V_{IH} - V_{IL}$)			$0.3 \cdot V_{DD5V}$		V
I_{LKG}	Leakage Current				0.1	uA
V_{OH}	High-level output voltage	$V_{DD5V} = 3.3\text{V}$, $I_{OH} = -10\text{mA}$,	$V_{DD5V} - 0.4$			
		$V_{DD5V} = 5\text{V}$, $I_{OH} = -15\text{mA}$,	$V_{DD5V} - 0.4$			
V_{OL}	Low-level output voltage	$V_{DD5V} = 3.3\text{V}$, $I_{OL} = 10\text{mA}$			$V_{SS} + 0.4$	
		$V_{DD5V} = 5\text{V}$, $I_{OL} = 15\text{mA}$			$V_{SS} + 0.4$	
PT 6 ~ 10, 13 GPIO Port						
R_{PU}	Internal pull high resistor			NA		
V_{IH}	Input high voltage		$0.75 \cdot V_{DD5V}$			V
V_{IL}	Input low voltage				$0.3 \cdot V_{DD5V}$	V
V_{hys}	Input Voltage hysteresis($V_{IH} - V_{IL}$)			$0.3 \cdot V_{DD5V}$		V
V_{OH}	High-level output voltage	$V_{DD5V} = 3.3\text{V}$, $I_{OH} = 10\text{mA}$,	$V_{DD5V} - 0.5$			
		$V_{DD5V} = 5\text{V}$, $I_{OH} = 15\text{mA}$,	$V_{DD5V} - 0.5$			
V_{OL}	Low-level output voltage	$V_{DD5V} = 3.3\text{V}$, $I_{OL} = -10\text{mA}$			$V_{SS} + 0.4$	
		$V_{DD5V} = 5\text{V}$, $I_{OL} = -15\text{mA}$			$V_{SS} + 0.4$	

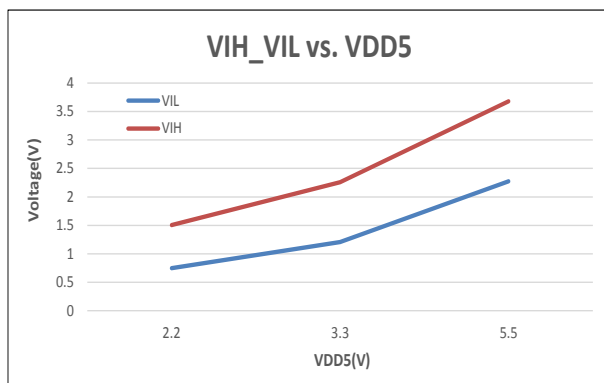


Figure 5.1.4-1 VIH/VIL vs. VDD5

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.6. ADC Management System

All specifications at $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{DDA} = \text{REFP} = 2.4\text{V}$, $\text{REFN} = \text{VSS}$, Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Analog Inputs						
	Full-scale input voltage (VINP - AINN)	Considering ADC performance matches ADC ENOB table. REFP=VDDA, REFN=VSS VREF be set to 1/2 only		$\pm 0.5 * \text{VREF} / \text{Gain}$		V
		Considering ADC performance matches ADC ENOB table. REFP=REFO_I REFN=VSS VREF be set to 1 only		$\pm \text{VREF} / \text{Gain}$		
	Common-mode input range	Gain = 1, @25°C	VSS-0.2V		VDDA	V
System Performance						
	Resolution	No missing codes		24		Bits
	Data rate			ADC Clock / OSR		SPS
	Digital filter settling time	Full setting		3		Data
	Integral nonlinearity (INL)	Differential input End-point fit, OSR=65536		30		PPM
	ADC Gain drift			5	10	ppm/ °C
	Normal-mode rejection	$f_{IN} = 60\text{Hz} \pm 1\text{Hz}$, Output rate = 15 SPS		70		dB
	Common-mode rejection	$\Delta V_{DDA} = 0.1\text{V} @ \text{DC}$		80		dB
	Input-referred noise	Output rate= 31 SPS, ADC Gain=1		2.04		uV, rms
	Power-supply rejection	$\Delta V_{DDA} = 0.1\text{V} @ \text{DC}$		80		dB
Voltage Reference Input						
	Voltage reference input	$\text{VREF} = \text{REFP} - \text{REFN}$			VDDA	V
	Positive Reference Input	REFP, @25°C	VDDA/2		VDDA	V
	Negative Reference Input	REFN, @25°C	VSS		VDDA/2	V
ADC Modulator Current						
ADC	ADC Modulator	VDD5V=3.3V, VDDA=2.4V, ADC Clock=1Mhz		300		uA
PGA	ADC PGA	VDD5V=3.3V, VDDA=2.4V		700		uA

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



<i>ENOB(RMS) with OSR/GAIN at C_{PUCK}=4MHz, A/D Clock=4M/4=1MHz, V_{DDA}=2.4V, V_{REF}=AI2-AI3=V_{DDA}-V_{SS}, VRGN=0.5; Vin=AI0-AI1, ext.short with 1K load cell</i>									
OSR					128	512	2048	8196	32768
Output rate(Hz)					7813	1953	488	122	31
Gain	=	PGAGN	x	ADGN					
1	=	off	x	1	16.48	17.5	18.47	19.15	20.18
2	=	off	x	2	16.38	17.61	18.19	19	20.25
3	=	off	x	3	16.22	17.22	18.17	19.06	20.19
4	=	off	x	4	15.84	16.92	17.97	19	20.34
4	=	8	x	1	16.5	17.52	18.43	19.07	19.7
8	=	16	x	1	16.13	17.11	18.18	19.09	19.7
16	=	32	x	1	16.15	16.81	17.63	18.83	19.71
4	=	8	x	4	15.3	15.94	17.23	18	19.05
8	=	16	x	4	14.55	15.77	16.67	17.53	18.44
16	=	32	x	4	14.18	15.14	16.2	17.37	18.15

<i>RMS Noise(uV) with OSR/GAIN at C_{PUCK}=4MHz, A/D Clock=4M/4=1MHz, V_{DDA}=2.4V, V_{REF}=AI2-AI3=V_{DDA}-V_{SS}, VRGN=0.5; Vin=AI0-AI1, ext.short with 1K load cell</i>									
OSR					128	512	2048	8196	32768
Output rate(Hz)					7813	1953	488	122	31
Gain	=	PGAGN	x	ADGN					
1	=	off	x	1	26.376	13.049	6.672	4.146	2.038
2	=	off	x	2	14.145	6.043	4.043	2.311	0.966
3	=	off	x	3	10.559	5.275	2.739	1.472	0.674
4	=	off	x	4	10.337	4.881	2.356	1.151	0.454
8	=	8	x	1	3.257	1.603	0.858	0.547	0.369
16	=	16	x	1	2.112	1.065	0.508	0.272	0.184
32	=	32	x	1	1.041	0.657	0.371	0.162	0.088
32	=	8	x	4	1.874	1.204	0.490	0.288	0.139
64	=	16	x	4	1.570	0.676	0.363	0.200	0.139
128	=	32	x	4	1.016	0.522	0.252	0.111	0.065

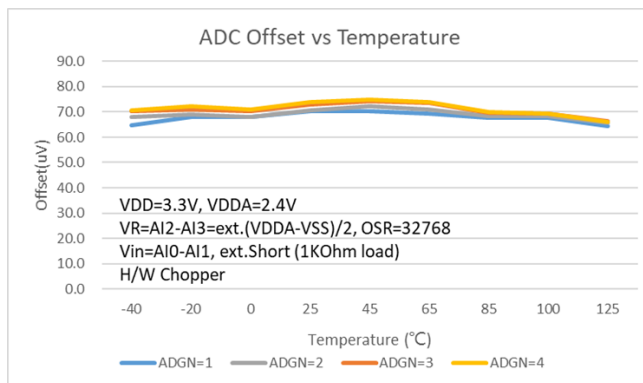


Figure5.1.6-1 ADC Offset vs. Temperature

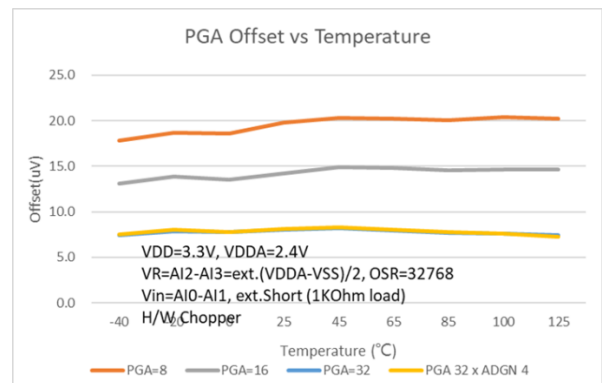


Figure5.1.6-2 PGA Offset vs. Temperature

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE

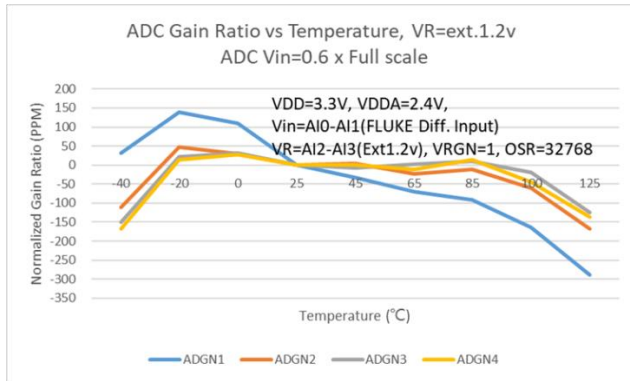


Figure5.1.6-3 ADC Gain Ratio vs. Temperature

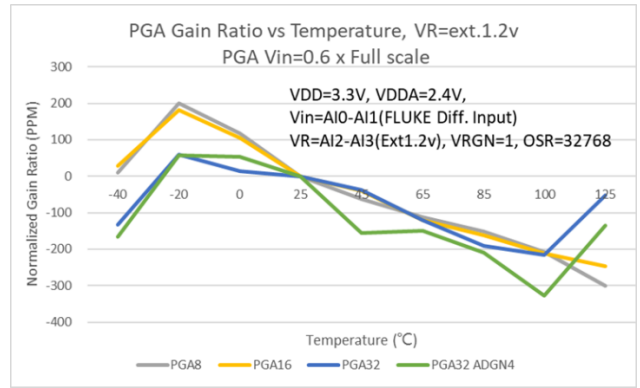


Figure5.1.6-4 PGA Gain Ratio vs. Temperature

HY16F3913

21-bit ENOB ΣΔADC, LCD Type 32-bit MCU & 128KB Flash
With AC Impedance Converter AFE



5.1.7. Internal Temperature Sensor

Typical values are at $T_A=25^\circ\text{C}$, $V_{DD5V} = 3.0\text{V}$, and $V_{DDA}=2.4\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
TC_S	Sensor temperature drift			172		$\mu\text{V}/^\circ\text{C}$
KT	Absolute temperature scale 0K			-286		$^\circ\text{C}$
TC_{ERR}	One point calibrate error temperature	Calibration at 25°C of -40°C - 85°C		± 2		$^\circ\text{C}$

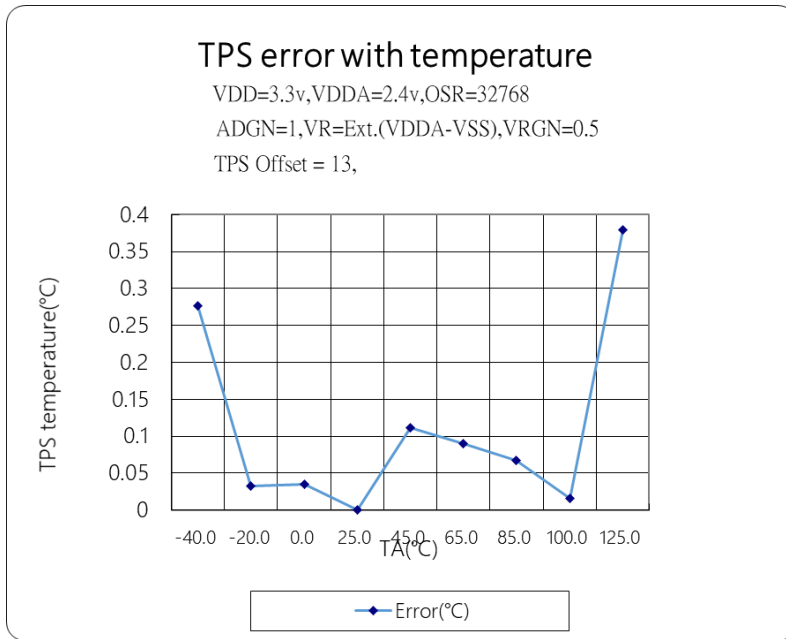


Figure 5.1.7-1 ADC Temperature Sensor Error

HY16F3913

21-bit ENOB ΣADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.1.8. LVD Comparator Management System

Typical values are at TA=25°C and VDD5V = 3.0V. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
LVD	Operation current, I _{V12_BOR}			2.5		uA	
	Operation current, I _{V12_BGR}			10		uA	
	V12_BOR Reference Voltage		1.1	1.2	1.3	V	
	V12_BOR Reference Voltage Temperature drift			200		PPM/°C	
	V12_BOR Reference Voltage to VDD5V Voltage drift			±2		%/V	
	V12_BGR Reference Voltage		1.15	1.2	1.25	V	
	V12_BGR Reference Voltage Temperature drift			50		PPM/°C	
	V12_BGR Reference Voltage to VDD5V Voltage drift			±2		%/V	
	Compare reference voltage temperature drift, T _A = -40°C ~ 85 °C				50		ppm/°C
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1111b				LVDIN		V
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1110b				4.0	5%	
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1101b				3.6		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1100b				3.3		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1011b				3.0		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1010b				2.9		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1001b				2.8		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=1000b				2.7		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0111b				2.6		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0110b				2.5		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0101b				2.4		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0100b				2.3		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0011b				2.2		
	Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0010b				2.1		
Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0001b				2.0			
Detect V _{DD5V} voltage rang by user option, V _{SVS} LVDS [3:0]=0000b				Off			

LVD : Low Voltage Detect

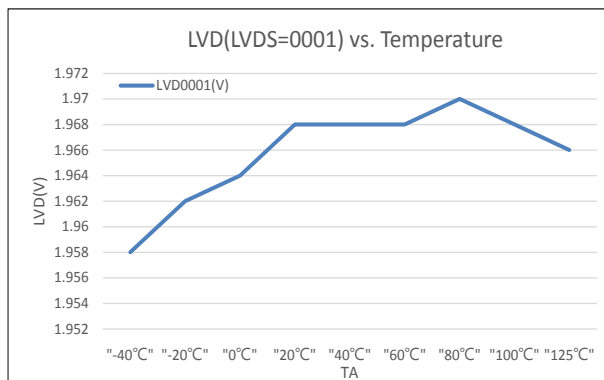


Figure 5.1.8-1 LVD vs. Temperature

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.1.9. LCD System

Typical values are at $T_A=25^{\circ}\text{C}$, $V_{DD5V} = 3.3\text{V}$, and $C_{VLCD}=4.7\mu\text{F}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
I_{LCD}	Operation Current Charge Pump Mode	W/O Panel		20		μA	
V_{LCD}	Supply Voltage Range	VLCD	With Buffer, ENLCDP[0]=0b	2.5		5.5	V
		ENLCDP[0]=1b @VDD5V > 2.0V	VLCD=111b, @VDD5V>=2.75V		5.0		V
			VLCD=110b @VDD5V>=2.5V		4.5		
			VLCD=101b @VDD5V>=2.2V		3.94		
			VLCD=100b @VDD5V>=2V		3.3		
			VLCD=011b		3.0		
	VLCD=010b		2.8				
VDD Voltage drift	ENLCDP[0]=1b		5		%		
Z_{LCD}	Output Impedance With LCD Buffer	$F_{LCD} = LS_CK/32/9$, VLCD = 3 V		10		$\text{K}\Omega$	

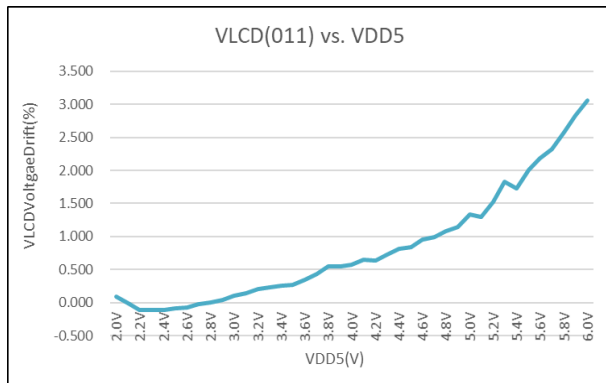


Figure 5.1.9-1 VLCD vs. VDD5

5.1.10. Flash Memory

Typical values are at $T_A=-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$, $V_{DD5V} = 3.3\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
	V_{DD5V} Supply voltage		2.0		5.5	V
	Program/Erase supply current				4	mA
	Data retention time		10			Years
	Number of program/Erase cycles(Endurance)		100			K Cycles
	Mass Erase time		10			ms
	Sector Erase time		2			ms
	Word Write time		20			us

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.2. AC Impedance Converter AFE Electrical Characteristics

ABSOLUTE MAXIMUM RATINGS

Absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Voltage applied at VDD1 to VSS1.....	-0.2 V to 6.0 V
Voltage applied to any pin.....	-0.2 V to VDD1 + 0.3 V
Diode current at any device terminal	±2 mA
Storage temperature	-55°C to 150°C
Operation temperature.....	-40°C to 85°C
Total power dissipation.....	0.5w
Maximum output current sink by CLKOUT pin.....	20mA

5.2.1. Recommended operating conditions

T_A = -40°C ~ 85°C, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{DD1}	Supply Voltage	All digital peripherals	2.2		5.5	V
V _{DDA1}	Supply Voltage	Analog peripherals	2.4		4.5	
V _{SS1}	Supply Voltage		0		0	

5.2.2. Internal RC Oscillator

T_A = 25°C, V_{DD1} = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
HAO	High Speed Oscillator frequency	2MHz Mode, HAOM[1:0]=00b	1.65	1.95	2.25	MHz
		4MHz Mode, HAOM[1:0]=01b	3.45	4.0	4.56	MHz
		8MHz Mode, HAOM[1:0]=10b	7.57	8.5	9.16	MHz
	HAO Trim Range[6:0]		-63		64	LSB
	2MHz HAO Trim LSB			0.345		%
	4MHz HAO Trim LSB			0.3		%
	8MHz HAO Trim LSB			0.21		%

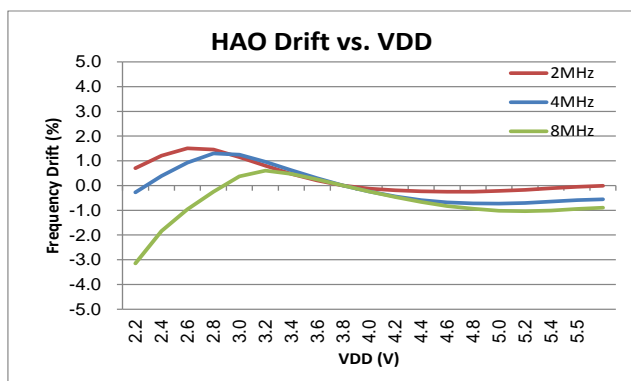


Figure 5.2.2-1 HAO vs. VDD1

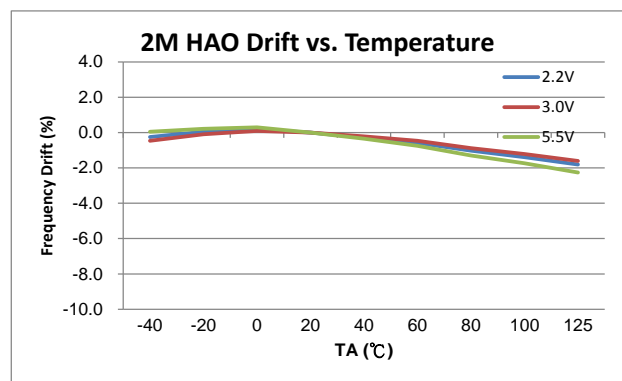


Figure 5.2.2-2 HAO(2.0MHz) vs. Temperature

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

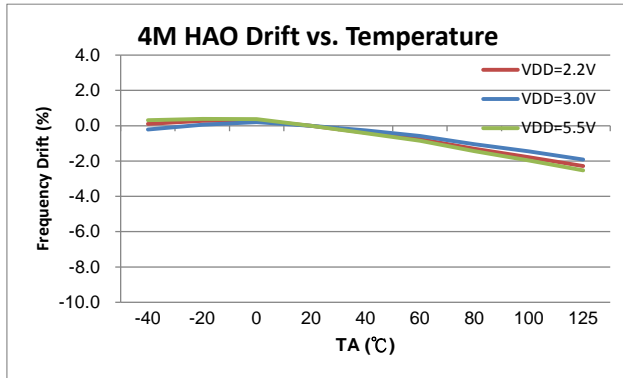


Figure 5.2.2-3 HAO(4.0MHz) vs. Temperature

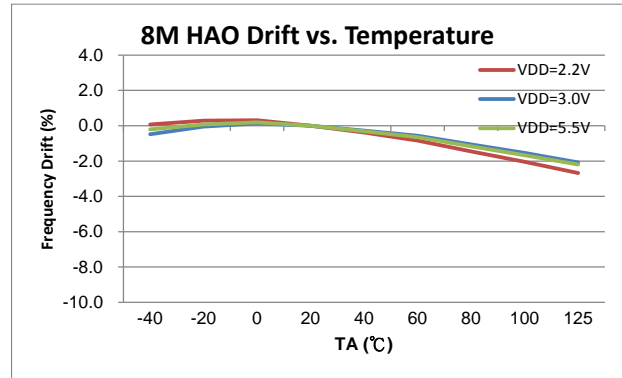


Figure 5.2.2-4 HAO(8.0MHz) vs. Temperature

5.2.3. Supply current into VDD1 excluding peripherals current

$T_A = 25^\circ\text{C}, V_{DD1} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{LP3}	Low Power 3	HAO = off, All IP Off, Sleep state		0.3	1.0	μA

HAO : Internal High Accuracy Oscillator frequency.

$T_A = 25^\circ\text{C}, V_{DD1} = 5.5\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{LP3}	Low Power 3	HAO = off, All IP Off, Sleep state		0.5	2	μA

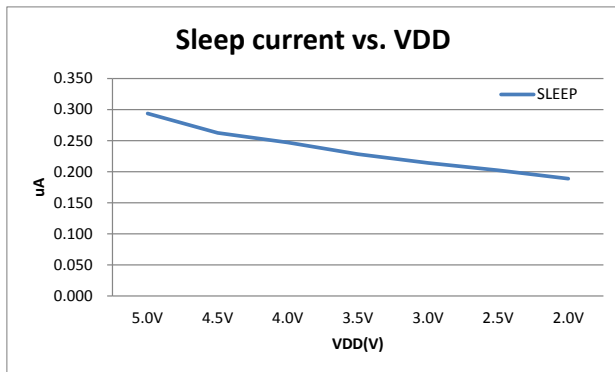


Figure 5.2.3-1 I_{LP3} vs. VDD1

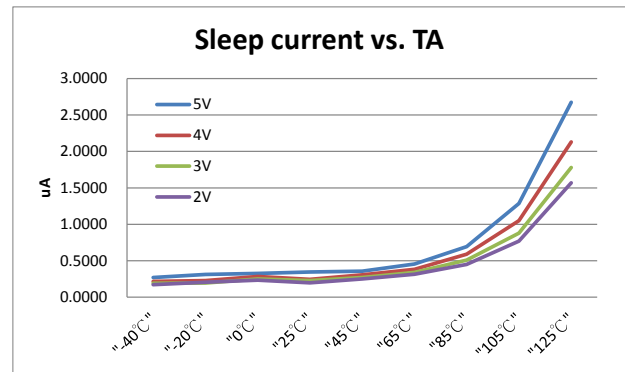


Figure 5.2.3-2 I_{LP3} vs. Temperature

HY16F3913

21-bit ENOB ΣADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.2.4. GPIO PORT CLKOUT/IRQ/AI9

$T_A = 25^\circ\text{C}, V_{DD1} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Analog Input						
I_{LKG}	Leakage Current				0.1	μA
R_{PU}	Port pull high resistance		351	390	429	$\text{k}\Omega$
Output voltage and current and frequency						
V_{OH}	High-level output voltage	$V_{DD1} < 4\text{V}, I_{OH} = 10\text{mA}$,	$V_{DD1} - 0.3$			V
		$V_{DD1} \geq 4\text{V}, I_{OH} = 15\text{mA}$,	$V_{DD1} - 0.4$			
V_{OL}	Low-level output voltage	$V_{DD1} < 4\text{V}, I_{OL} = -10\text{mA}$			$V_{SS1} + 0.3$	
		$V_{DD1} \geq 4\text{V}, I_{OL} = -15\text{mA}$			$V_{SS1} + 0.4$	

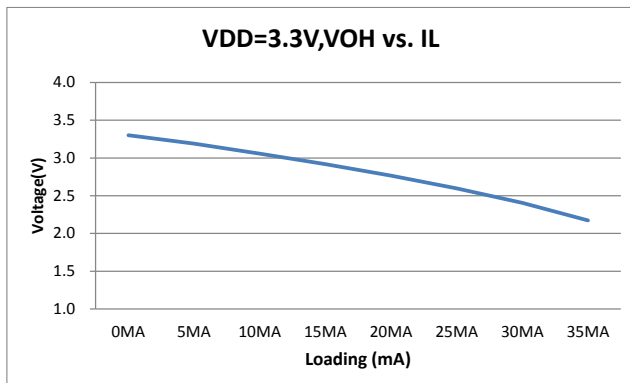


Figure 5.2.4-1 V_{OH} vs. I_{OH}

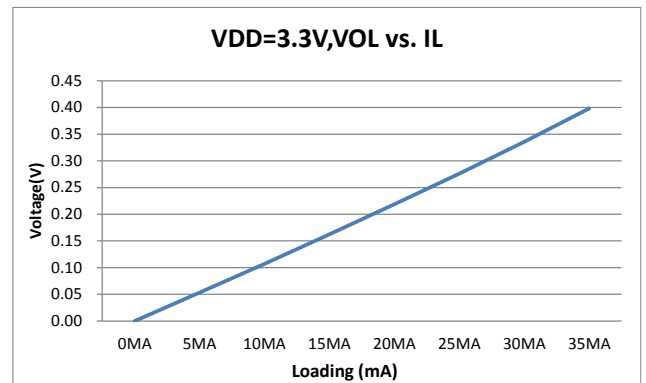


Figure 5.2.4-2 V_{OL} vs. I_{OL}

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

5.2.5. Brownout Reset (BOR)

$T_A = 25^\circ\text{C}, V_{DD1} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
BOR	Pulse length needed to accepted reset internally, t_{d-LVR}		2			μS
	V_{DD1} Start Voltage to accepted reset internally (L→H), V_{LVR}	$T_A = 25^\circ\text{C}$	1.5	1.65	1.8	V
	V_{DD1} Start Voltage to accepted reset internally (L→H), V_{LVR}	$T_A = -40^\circ\text{C} \sim 85^\circ\text{C}$	1.45		1.85	V
	Current consumption	$V_{DD1}=3.3\text{V}$		0.3		μA
		$V_{DD1}=5.5\text{V}$		0.5		μA

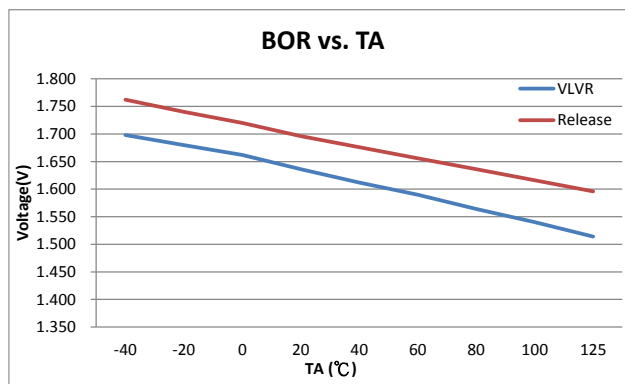


Figure 5.2.5-1 BOR vs. Temperature

5.2.6. Power System

T_A = 25°C, VDD1 = 3.0V, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
VDDA1	VDDA1 operation current, I _{VDDA1}	I _L = 0mA	LDOC[2:0]=000b		20		uA
	Select VDDA1 output voltage	I _L = 0.1mA, VDD1 ≥ VDDA1+0.25V	LDOC [2:0]=000b	2.28	2.4	2.52	V
			LDOC [2:0]=001b	2.47	2.6	2.73	V
			LDOC [2:0]=010b	2.755	2.9	3.045	V
			LDOC [2:0]=011b	3.135	3.3	3.465	V
			LDOC [2:0]=100b	3.42	3.6	3.78	V
			LDOC [2:0]=101b	3.8	4.0	4.2	V
			LDOC [2:0]=110b	4.275	4.5	4.725	V
			LDOC [2:0]=111b	4.75	5.0	5.25	V
Dropout voltage	I _L = 10mA	LDOC [2:0]=000b		400		mV	
Temperature drift	LDOC [2:0]=000b I _L = 10uA	T _A =-40°C~85°C		50		ppm/°C	
V _{DD1} Voltage drift	LDOC [2:0]=000b	V _{DD1} =VDDA1+0.25V~5.5V		±0.2		%/V	
REFO1	REFO1 operation current, I _{REFO1}	VDDA1=2.4V, ENV12=1b			50		uA
	output voltage, V _{REFO1}		I _L = 0mA,	1.14	1.2	1.26	V
			I _L = 0.2mA (include ESD resistance)	0.94		0.96	V _{REFO1}
	Temperature drift		T _A =-40°C~85°C		50		ppm/°C
V _{DDA1} Voltage drift				100		uV/V	
ACM1	ACM1 operation current, I _{ACM1}	VDDA1=2.4V, ENADC[0]=1b, ENACM=1b			50		uA
	Internal Analog Common Mode Voltage ,V _{ACM1} =1.2V or VDDA1/2		VCMS=0b, I _L = 0uA		VDDA1/2		V
			VCMS=1b, I _L = 0uA	1.14	1.2	1.26	V
	Temperature drift		T _A =-40°C~85°C, ENACM [0]=1b		50		ppm/°C

VDDA1 : Adjust Voltage Regulator,

ACM1 : Internal Analog Common Mode Voltage VDDA1/2 (No voltage output) or 1.2V

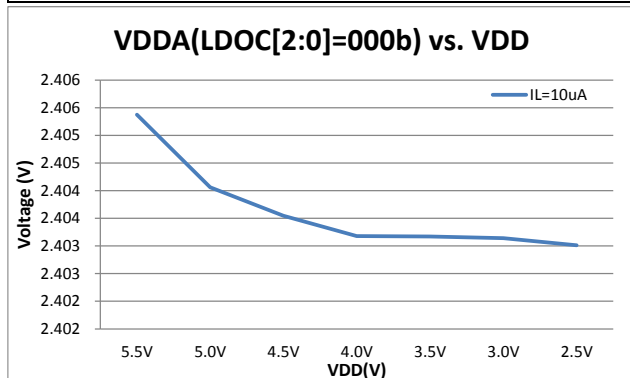


Figure 5.2.6-1 VDDA1(000b) vs. VDD1

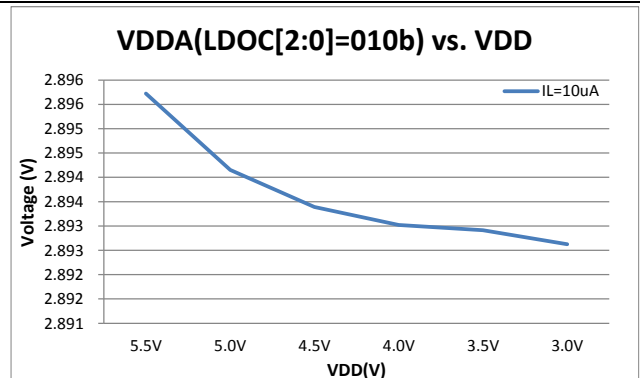


Figure 5.2.6-2 VDDA1(010b) vs. VDD1

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

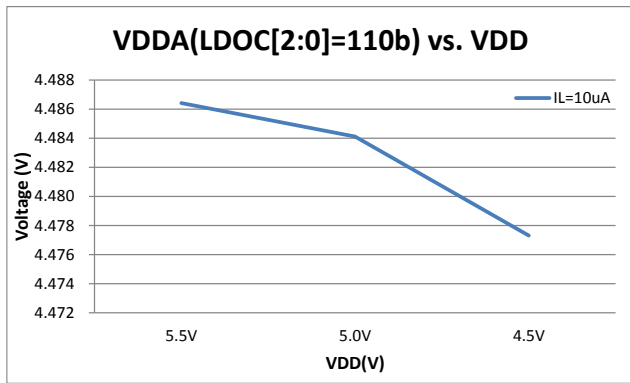


Figure 5.2.6-3 VDDA1(110b) vs. VDD1

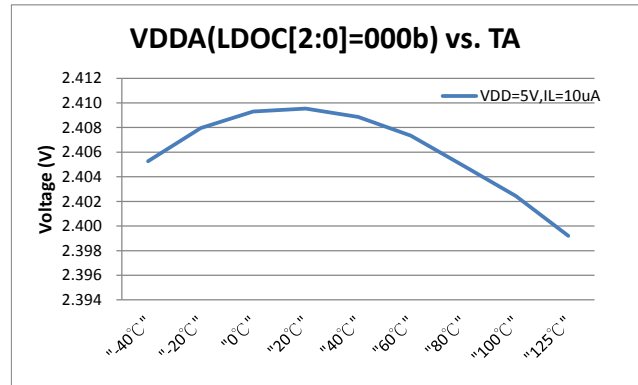


Figure 5.2.6-4 VDDA1(000b) vs. Temperature

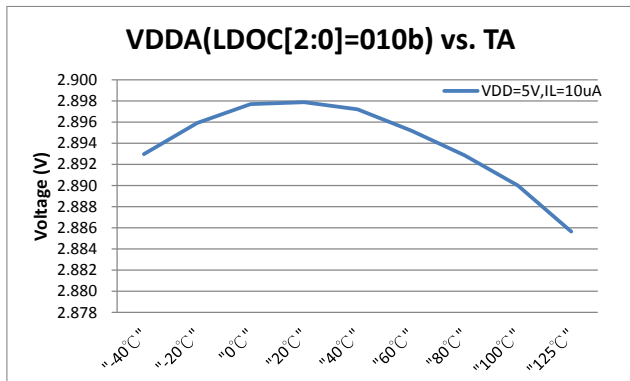


Figure 5.2.6-5 VDDA1(010b) vs. Temperature

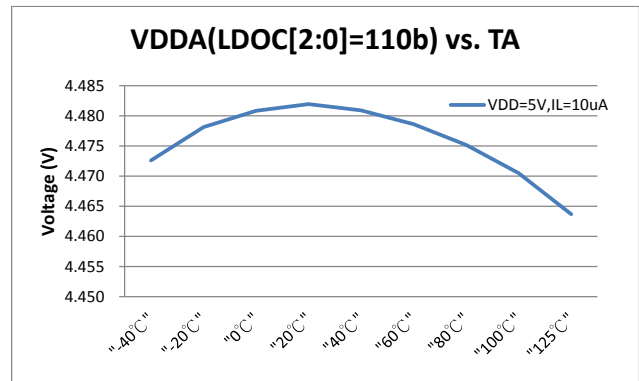


Figure 5.2.6-6 VDDA1(110b) vs. Temperature

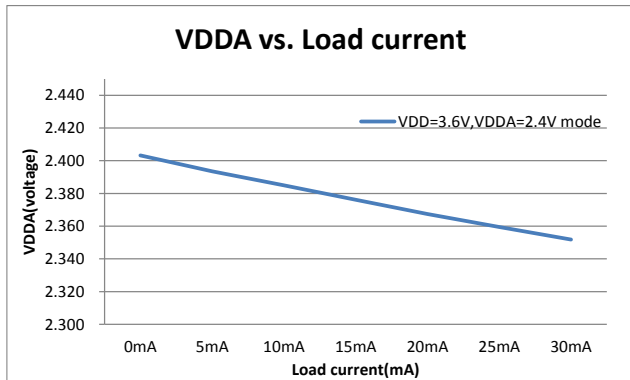


Figure 5.2.6-7 VDDA1 vs. Load current

5.2.7. ΣΔADC, Power Supply and recommended operating conditions

$T_A = 25^{\circ}\text{C}, V_{DD1} = 3.0\text{V}, V_{DDA1}=2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
V_{SD18}	Supply Voltage at VDDA1	ENVDDA[0]=0		2.4		4.5	V
f_{SD18}	Modulator sample frequency, ADC_CK				1000		KHz
	Over Sample Ratio, OSR			64		65536	
I_{SD18}	Operation supply current without PGA	ENADC[0]=1	GAIN =16, ADC_CK=1MHz		260		μA

5.2.7.1. ΣΔADC, performance

$T_A = 25^{\circ}\text{C}, V_{DD1} = 3.0\text{V}, V_{DDA1}=2.4\text{V}, V_{VR}=1.0\text{V}, \text{GAIN}=1$ without PGA, $f_{SD18}=1\text{MHz}$, unless otherwise noted

Sym.	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
INL	Integral Nonlinearity(INL)	$V_{DDA1}=2.4\text{V}, V_{VR}=1.0\text{V}, \Delta\text{SI}=\pm 200\text{mV}$			± 0.003	± 0.01	%FSR
		$V_{DDA1}=2.4\text{V}, V_{VR}=1.0\text{V}, \Delta\text{SI}=\pm 450\text{mV}$					
	No Missing Codes ³	ADC_CK=1MHz, OSR=64000		23			Bits
G_{SD18}	Temperature drift Gain x16	$T_A = -40^{\circ}\text{C} \sim 85^{\circ}\text{C}$,			10		ppm/ $^{\circ}\text{C}$
E_{OS}	Offset error of Full Scale Rang input voltage range with Chopper	$\Delta\text{AI}=0\text{V}$ $\Delta\text{VR}=1.2\text{V}$ DCSET[3:0]=<0000> * ΔAI is external short	Gain=2			1	%FSR
	Offset error temperature drift with chopper		GAIN=1		0.004		μV/ $^{\circ}\text{C}$
			GAIN=2		0.003		
			GAIN=4		0.003		
CM_{SD18}	Common-mode rejection	$V_{\text{CM}}=0.7\text{V}$ to 1.7V, $V_{\text{VR}}=1.0\text{V}$	$V_{\text{SI}}=0\text{V}$, GAIN=1		90		dB
		$V_{\text{CM}}=0.7\text{V}$ to 1.7V, $V_{\text{VR}}=1.0\text{V}$	$V_{\text{SI}}=0\text{V}$, GAIN=16		75		
PSRR	DC power supply rejection	$V_{DDA1}=3.0\text{V}$, $\Delta V_{DDA1}=\pm 100\text{mV}$, $V_{\text{VR}}=1.0\text{V}$, $V_{\text{SI}}=1.2\text{V}, V_{\text{SI}}=1.2\text{V}$,	GAIN=1 PGA=off		75		dB

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

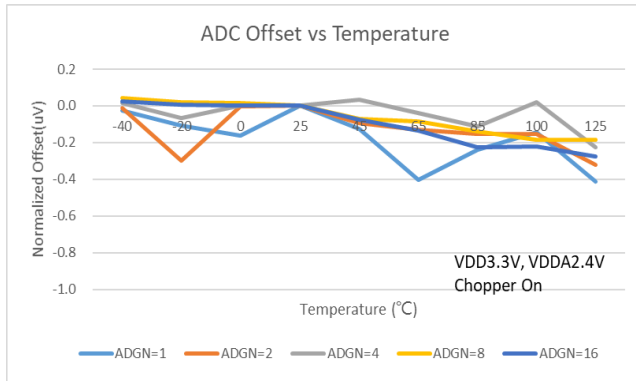


Figure 5.2.7-1 ADC Offset drift with Temperature

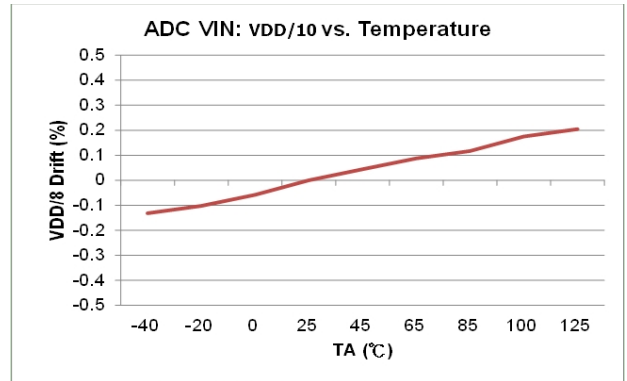


Figure 5.2.7-2 VDD1/10 drift with Temperature

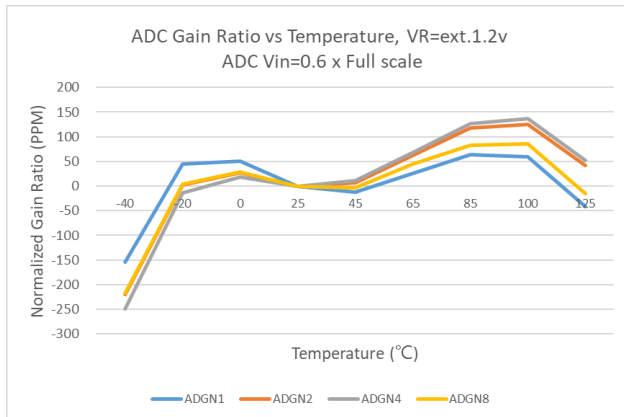


Figure 5.2.7-3 ADC Gain drift with Temperature

HY16F3913

21-bit ENOB Σ ADC, 32-bit MCU & 128KB Flash 4X44~8X40 LCD Driver



5.2.7.2. Σ ADC Noise Performance

$T_A = 25^\circ\text{C}, V_{DD1} = 3.0\text{V}, V_{DDA1}=2.4\text{V}$, unless otherwise noted

針對 Σ ADC 提供了重要的輸入雜訊規格。下表列出典型的雜訊規格表與 Gain, Output rate, 及單端最大輸入電壓等關係。測試條件設定在外部輸入訊號短路，參考電壓為 1.2V，取樣 1024 筆資料。

Max. Vin(mV) $=0.9V_{REF}^{(1)}$	OSR		32	64	125	250	500	1000	2000	4000	8000	16000	32000	64000
	Output rate(Hz)													
	Gain	PGAG = N x ADGN	31250	15625	8000	4000	2000	1000	500	250	125	63	31	16
± 2160	0.25	= off x 0.25	10.4	12.2	13.48	15.21	15.79	16.26	16.59	17.14	17.98	18.56	18.98	19.6
± 2160	0.5	= off x 0.5	10.4	12.21	13.63	15.29	15.81	16.45	17.03	17.49	17.97	18.36	18.98	19.41
± 1080	1	= off x 1	10.44	12.11	14.14	15.29	15.87	16.36	16.99	17.56	18.01	18.47	18.87	19.41
± 540	2	= off x 2	10.39	12.18	13.57	15.21	15.9	16.46	16.98	17.47	17.93	18.41	18.86	19.41
± 270	4	= off x 4	10.38	12.16	13.29	15.22	15.74	16.29	16.88	17.35	17.85	18.33	18.91	19.26
± 135	8	= off x 8	10.42	12.09	13.49	15.1	15.63	16.19	16.81	17.28	17.86	18.28	18.72	19.09
± 68	16	= off x 16	10.33	12	13.92	15.01	15.58	16.11	16.68	17.11	17.59	18.14	18.55	19

(1) Max. Vin(mV) is the max. input voltage single end to ground(VSS1)

Max. Vin(mV) $=0.9V_{REF}^{(1)}$	OSR		32	64	125	250	500	1000	2000	4000	8000	16000	32000	64000
	Output rate(Hz)													
	Gain	PGAG = N x ADGN	15625	7813	4000	2000	1000	500	250	125	63	31	16	8
± 2160	0.25	= off x 0.25	10.89	12.7	14.2	15.88	16.39	16.74	16.83	17.63	18.5	19.07	19.5	20.04
± 2160	0.5	= off x 0.5	10.8	12.65	14.21	15.66	16.25	16.93	17.38	17.92	18.47	19.01	19.48	20
± 1080	1	= off x 1	10.85	12.69	14.07	15.66	16.43	16.95	17.49	17.88	18.48	19.04	19.35	20.01
± 540	2	= off x 2	10.87	12.73	14.2	15.68	16.45	16.85	17.41	18.04	18.41	18.94	19.36	19.91
± 270	4	= off x 4	10.92	12.72	14.11	15.69	16.2	16.93	17.41	17.95	18.37	18.86	19.46	19.87
± 135	8	= off x 8	10.85	12.68	14.04	15.52	16.01	16.66	17.39	17.83	18.31	18.8	19.29	19.73
± 68	16	= off x 16	10.81	12.53	13.88	15.48	16.1	16.63	17.1	17.68	18.06	18.52	19.14	19.48

(1) Max. Vin(mV) is the max. input voltage single end to ground(VSS1)

Table 5.2.7-1 Σ ADC ENOB Table

Max. Vin(mV) $=0.9V_{REF}^{(1)}$	OSR		32	64	125	250	500	1000	2000	4000	8000	16000	32000	64000
	Output rate(Hz)													
	Gain	PGAG = N x ADGN	31250	15625	8000	4000	2000	1000	500	250	125	63	31	16
± 2160	0.25	= off x 0.25	7167.72	2052.62	846.32	255.25	170.77	122.81	97.90	66.85	37.35	25.06	18.76	12.19
± 2160	0.5	= off x 0.5	3585.84	1019.28	380.01	120.90	84.36	53.83	36.00	26.22	18.85	14.33	9.37	6.94
± 1080	1	= off x 1	1735.51	547.67	133.84	60.37	40.41	28.69	18.53	12.51	9.17	6.64	5.03	3.47
± 540	2	= off x 2	900.82	259.54	99.46	31.89	19.82	13.37	9.36	6.67	4.85	3.47	2.53	1.73
± 270	4	= off x 4	453.79	131.66	60.29	15.78	11.03	7.53	4.99	3.61	2.56	1.83	1.22	0.96
± 135	8	= off x 8	219.94	69.37	26.29	8.58	5.94	4.03	2.64	1.90	1.27	0.95	0.70	0.54
± 68	16	= off x 16	117.26	36.75	9.75	4.59	3.08	2.14	1.44	1.07	0.76	0.52	0.39	0.29

(1) Max. Vin(mV) is the max. input voltage single end to ground(VSS1)

Max. Vin(mV) $=0.9V_{REF}^{(1)}$	OSR		32	64	125	250	500	1000	2000	4000	8000	16000	32000	64000
	Output rate(Hz)													
	Gain	PGAG = N x ADGN	15625	7813	4000	2000	1000	500	250	125	63	31	16	8
± 2160	0.25	= off x 0.25	5078.12	1456.73	515.21	159.79	112.25	88.58	83.03	47.74	25.99	17.59	12.99	8.96
± 2160	0.5	= off x 0.5	2710.97	751.58	255.16	93.61	61.88	38.69	28.29	19.52	13.28	9.18	6.59	4.59
± 1080	1	= off x 1	1306.67	365.13	140.05	46.81	27.27	19.14	13.14	9.99	6.62	4.48	3.62	2.30
± 540	2	= off x 2	647.24	178.25	64.25	22.97	13.50	10.24	6.96	4.49	3.46	2.41	1.79	1.23
± 270	4	= off x 4	312.62	89.41	34.05	11.41	8.04	4.85	3.46	2.38	1.79	1.27	0.84	0.63
± 135	8	= off x 8	163.64	45.95	17.88	6.44	4.57	2.91	1.76	1.30	0.93	0.66	0.47	0.35
± 68	16	= off x 16	83.87	25.55	10.02	3.31	2.14	1.49	1.07	0.72	0.55	0.40	0.26	0.21

Table 5.2.7-2 Σ ADC RMS Noise Table

The RMS noise are referred to the input. The Effective Number of Bits (ENOB(RMS Bit)) is defined as:

$$ENOB(RMS) = \frac{\ln\left(\frac{FSR}{RMS\ Noise}\right)}{\ln(2)}$$

$$RMS\ Noise = \frac{\left(2 \times VREF \times \sqrt{\sum_{k=1}^{1024} (ADO[k] - Average)^2}\right)}{2^{23}}$$

Where FSR (Full - Scale Range) = $2 \times VREF / Gain$.

$$Average = \frac{\sum_{k=1}^{1024} (ADO[k])}{1024}$$

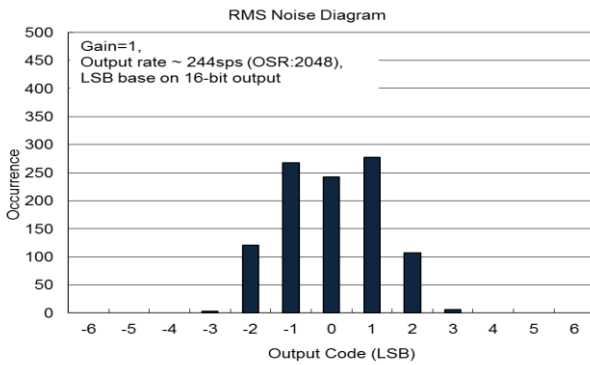


Figure 5.2.7-4 RMS Noise Diagram

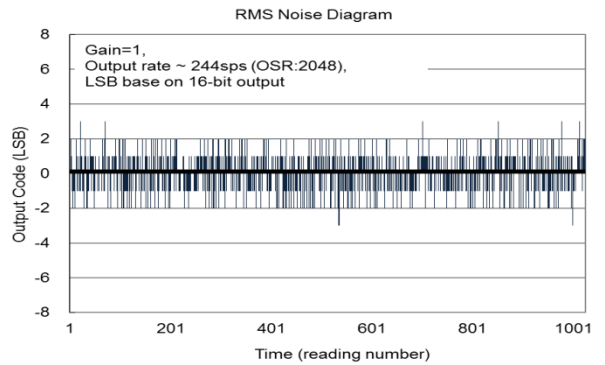


Figure 5.2.7-5 Output code Diagram

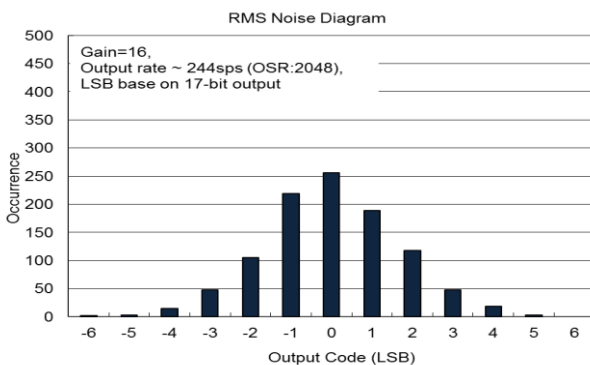


Figure 5.2.7-6 RMS Noise Diagram

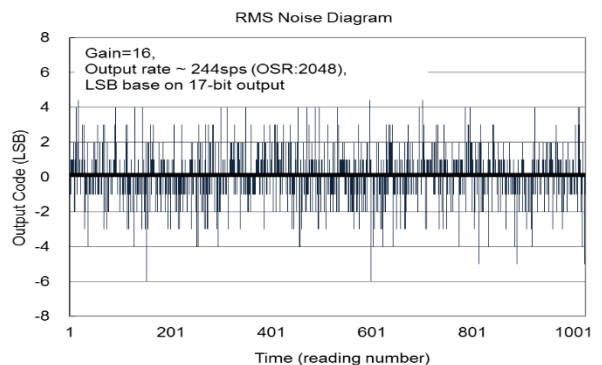


Figure 5.2.7-7 Output Code Diagram

HY16F3913

21-bit ENOB ΣADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

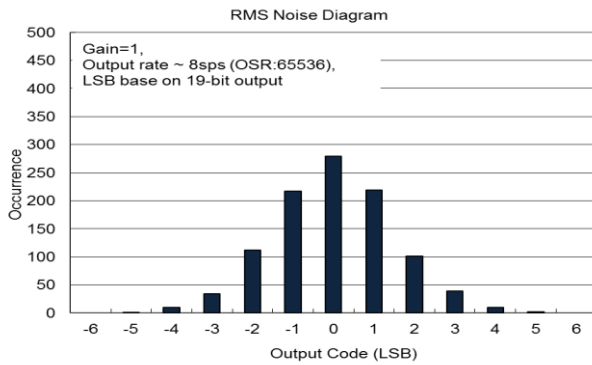


Figure 5.2.7-8 RMS Noise Diagram

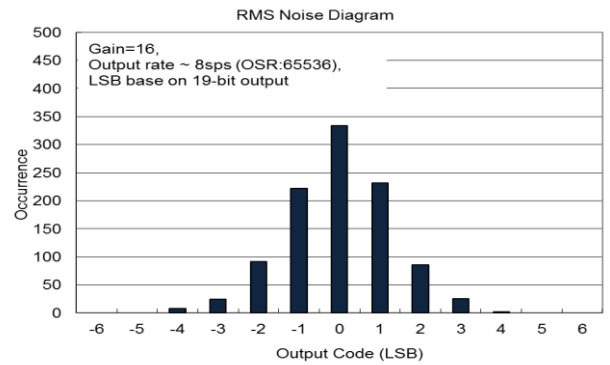


Figure 5.2.7-9 RMS Noise Diagram

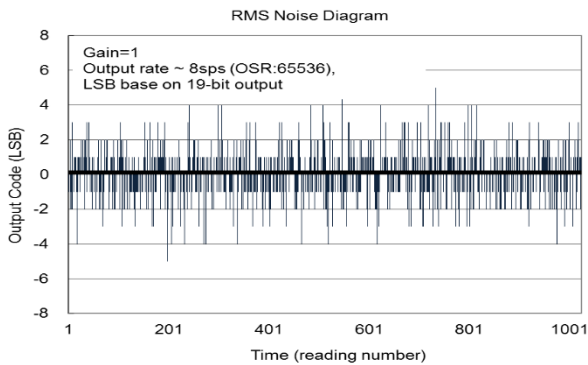


Figure 5.2.7-10 Output Code Diagram

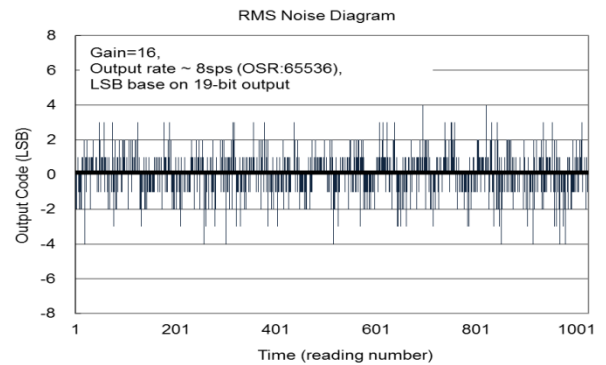


Figure 5.2.7-11 Output Code Diagram

5.2.7.3. ΣADC Temperature Sensor

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, $V_{DDA} = 2.4\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
TC _S	Sensor temperature drift			173		uV/°C
KT	Absolute Temperature Scale 0°K			-272		°C
TC _{ERR}	One point calibrate error temperature	Calibration at 25°C of -40°C~85°C		±2		°C

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

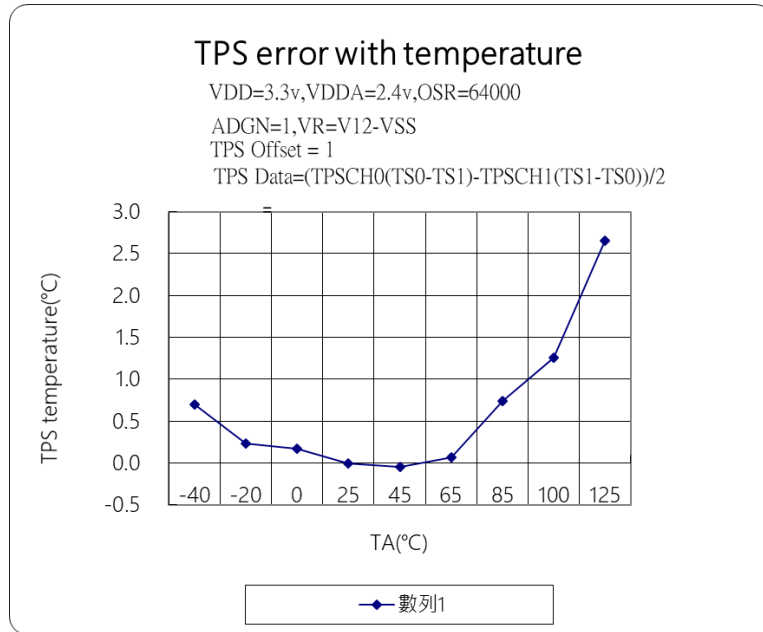


Figure 5.2.7-12 TPS Temperature Error

HY16F3913

21-bit ENOB ΣADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.2.8. Rail to Rail OPAMP1 、OPAMP2 、OPAMP3

T_A = 25°C, V_{DD1}= 3.0V, V_{DDA1}=2.4V, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{DDA1}	Power supply		2.4		4.5	V
V _{OUT}	Output range		0		V _{DDA1}	V
V _{IN}	Input common range		0		V _{DDA1}	V
I _{OPA}	OPAMP current			360		uA
I _{OPA_LOAD}	Output current loading (push or pull)	V _{DDA1} = 3.0V, 0.3V < Output voltage < V _{DDA1} -0.3V			1	mA
		V _{DDA1} = 2.4V, 0.3V < Output voltage < V _{DDA1} -0.3V			0.5	mA
C _{LOAD}	Max output capacitor load				1	nF
SR	Slew rate	Loading R=10K, C=100pF, 0.3V → V _{DDA1} -0.3V		0.6		V/uS
UGB	Unit gain bandwidth	Loading C=100pF		1000		KHz
V _{OS}	Offset error	V _{in} = 1.2V	-5		+5	mV
DFD	Digital filter delay	V _{DDA1} = 3.0V		2		uS
C _{SA}	Sample capacitor			10		pF

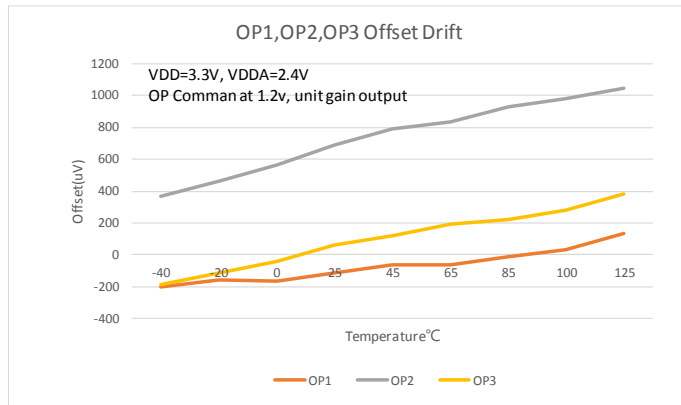


Figure 5.2.8-1 Rail to Rail OPAMP 1~3 Offset Drift with Temperature

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver



5.2.9. 12-Bit Resistance Ladders

Typical values are at $T_A=25^\circ\text{C}$ and $V_{DD1}= 3.0\text{V}$. Unless otherwise noted.

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
	Resolution	Monotonic		12		Bit
	Power Supply		2.4		VDDA1	V
	Operation current			50		μA
V_{OUT}	Output range	Output is between V_{refp} and V_{refn}	0		VDDA1	V
V_{REFP}	Positive reference voltage range	$V_{REFP} > V_{REFN}$	0		VDDA1	V
V_{REFN}	Negative reference voltage range		0		VDDA1	V
R_{LADDER}	One LSB resistance ladder			200		Ω
INL	Integral linearity error	$V_{refp} = 2.4\text{V}$, $V_{refn} = 0\text{V}$			±3	LSB
DNL	Differential linearity error	$V_{refp} = 2.4\text{V}$, $V_{refn} = 0\text{V}$			±1	LSB
Eos	Offset error	$V_{refp} = 2.4\text{V}$, $V_{refn} = 0\text{V}$			1	LSB

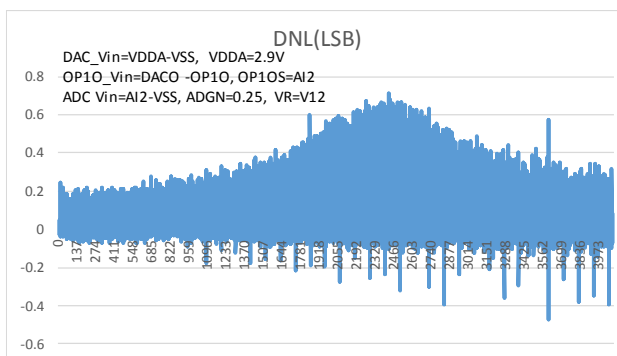


Figure 5.2.9-1 DNL(LSB)

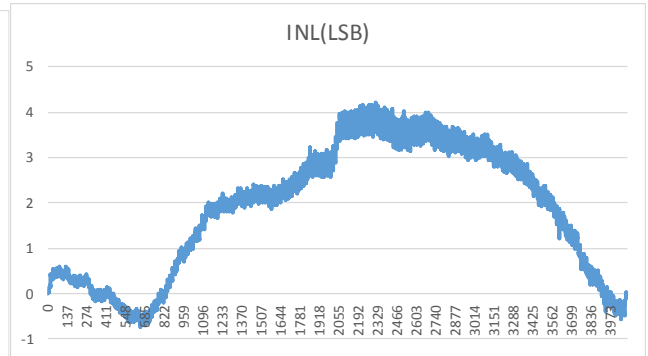


Figure 5.2.9-2 INL(LSB)

5.2.10. BIA Module

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
IAM1	Active mode 1	HAO = 8.5MHz, CPU_CK = 8.5MHz VDDA=2.4V · ENADC · ENACM ADC_CK=8.5M/8 SinWave=50K Vpp=200mV		1840		μA

HAO : Internal High Accuracy Oscillator frequency.

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.0\text{V}$, unless otherwise noted

Sym.	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Err1	Avg/S.D	(10K//1nF)//10K SinWave=5K Vpp=200mV			0.1	CV
Err2		(10K//1nF)//10K SinWave=10K Vpp=200mV			0.1	CV
Err3		(100K//1nF)//100K SinWave=5K Vpp=200mV			0.1	CV
Err4		(100K//1nF)//100K SinWave=10K Vpp=200mV			0.1	CV

S.D : standard deviation

HY16F3913

21-bit ENOB ΣADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

6. 訂貨資訊

下單品名 ¹	封裝型式	引腳數	封裝型式 描述方式		程式碼 編號 ²	出貨包裝 形式	個裝 數量	材料 組成	MSL ³
HY16F3913-L100	LQFP	100	L	100	-	Tray	90	Green ⁴	MSL-3
HY16F3913-N088	QFN	88	N	088	-	Tray	168	Green ⁴	MSL-3

HY16F3913-L100

↑ ↑
IC型號 IC封裝型式

¹ 產品名稱品名封裝型式描述方式裝型程式碼編號 (空白片 / 標準品 / 代客燒錄碼):

例如：您的需求是 HY16F3913 不帶程式碼的空白片且需要的產品是封裝片 LQFP100 出貨，則下單品名為 HY16F3913-L100，且需以 Tray 出貨，則除下單品名外，請特別註明出貨包裝形式為 Tray

例如：您的 HY16F3913 代客燒錄服務申請的程式碼編號為 009，而需求的產品是封裝片 LQFP100 出貨，則下單品名為 HY16F3913-L100-009，且需以 Tray 出貨，則除下單品名外，請特別註明出貨包裝形式為 Tray

例如：您的需求是 HY16F3913 不帶程式碼的空白片且需要的產品是封裝片 QFN88 出貨，則下單品名為 HY16F3913-N088，且需以 Tray 出貨，則除下單品名外，請特別註明出貨包裝形式為 Tray

例如：您的 HY16F3913 代客燒錄服務申請的程式碼編號為 001，而需求的產品是封裝片 QFN88 出貨，則下單品名為 HY16F3913-N088-001，且需以 Tray 出貨，則除下單品名外，請特別註明出貨包裝形式為 Tray

² 程式碼編號：

“式碼編號裝形式為外，請為標準品或代客燒錄申請的程式碼編號，而空白晶片不帶此碼。

³ MSL:

濕度敏感性等級係依據 IPC/JEDEC J-STD-020 的規範加以試驗分級，並參考 IPC/JEDEC J-STD-033 的標準處理、包裝、運輸與使用。

⁴ Green (RoHS & no Cl/Br):

HYCON 產品皆為 Green Product，符合 RoHS 指令，REACH 高關注物質(SVHC)以及無鹵素規定 (Br<900ppm or Cl<900ppm or (Br+Cl)<1500ppm)。

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

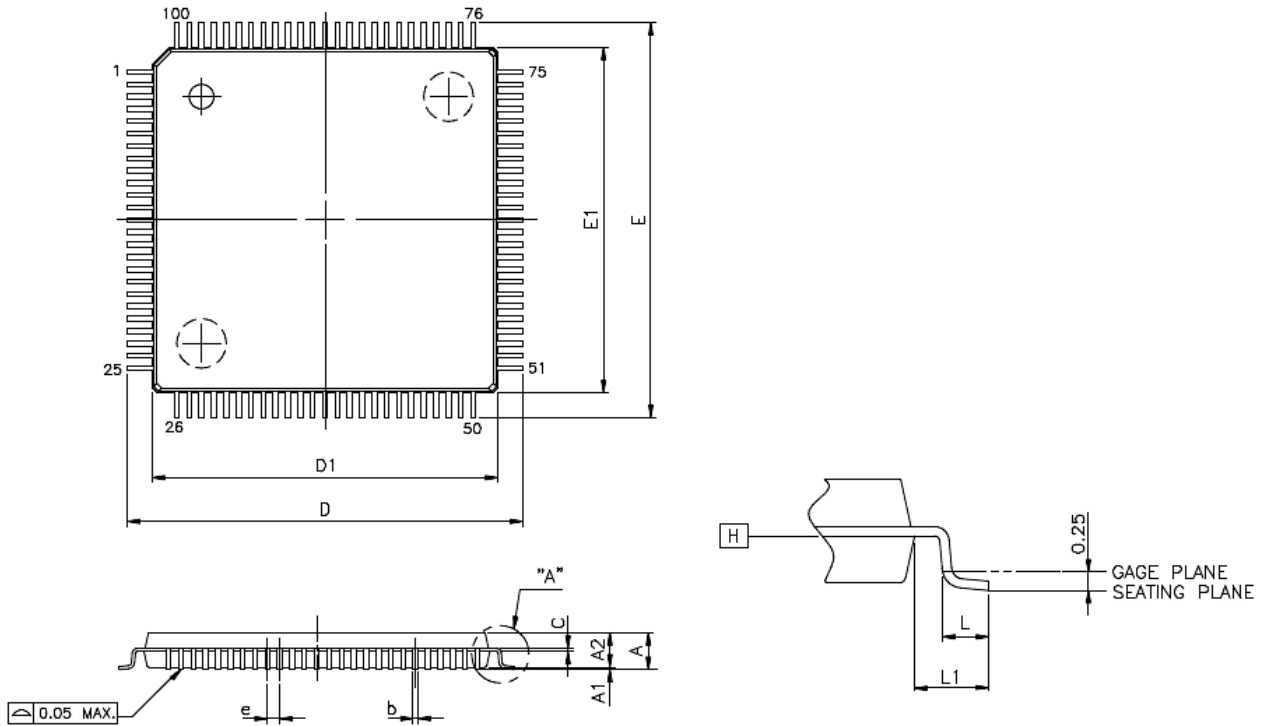


7. 封裝尺寸資訊

7.1. LQFP100(L100)

7.1.1. Package Dimensions LQFP100(14x14)

Unit: mm



VARIATIONS (ALL DIMENSIONS SHOWN IN MM)

SYMBOLS	MIN.	NOM.	MAX.
A	--	--	1.60
A1	0.05	--	0.15
A2	1.35	1.40	1.45
b	0.17	0.20	0.27
c	0.09	0.127	0.20
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
e	0.50 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		

Note:

1. All dimensions refer to JEDEC OUTLINE MS-026.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.

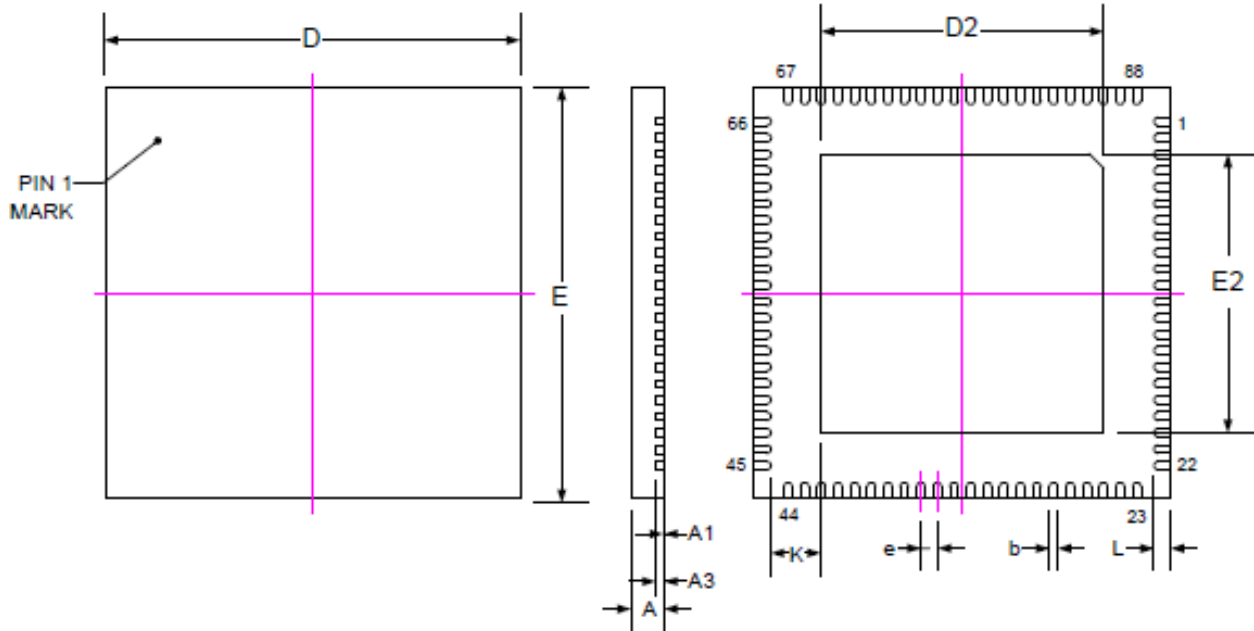
HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

7.2. QFN88(N088)(TYPE1)

7.2.1. Package Dimensions QFN88(10x10)

Unit: mm



SYMBOLS	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.15	0.20	0.25
D	10.00 BSC		
E	10.00 BSC		
e	0.40 BSC		
D2	6.75	6.80	6.85
E2	6.75	6.80	6.85
L	0.30	0.40	0.50
K	1.08	1.20	1.33

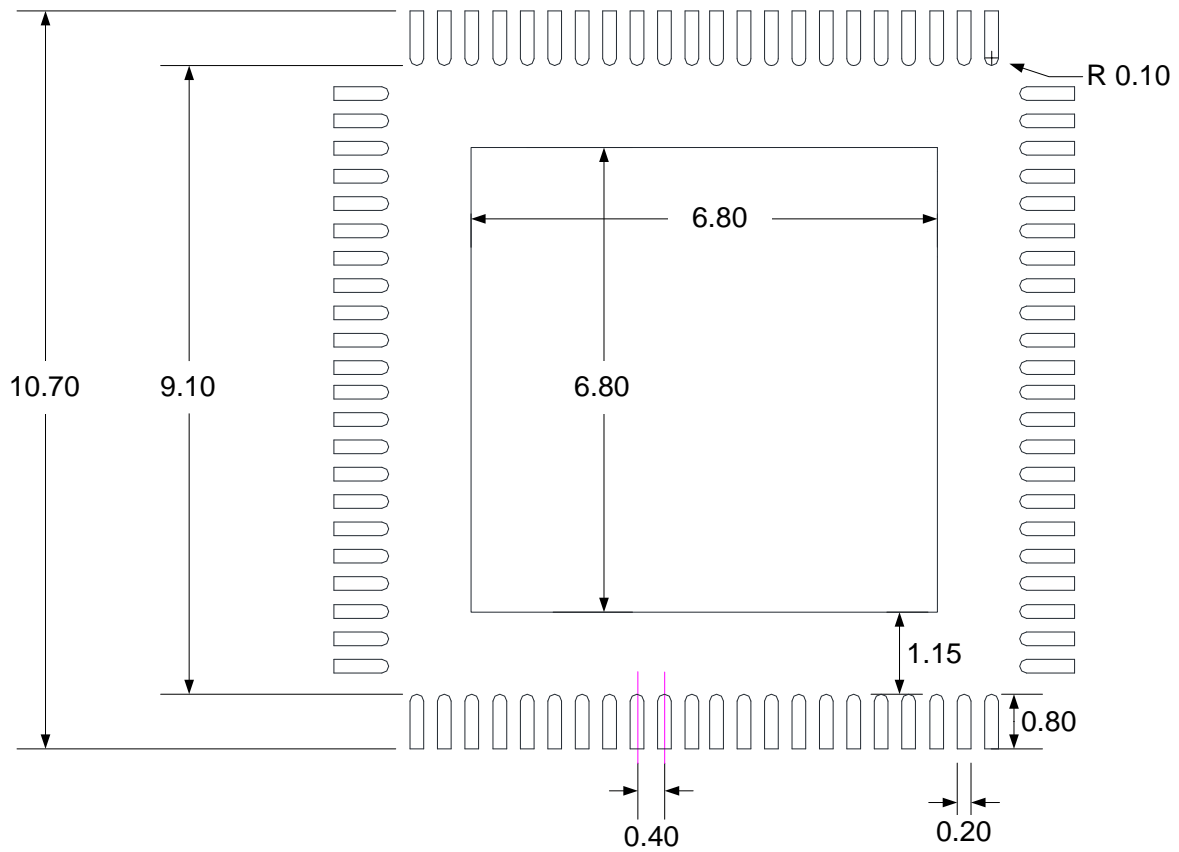
Note:

1. All dimensions refer to JEDEC OUTLINE MO-220.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.
4. https://www.hycontek.com/wp-content/uploads/QFN_DFN_PCB.pdf

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

7.2.2. Land Pattern Design Recommendations



Note:

1. Publication IPC-7351 is recommended for alternate designs
2. Unit : mm

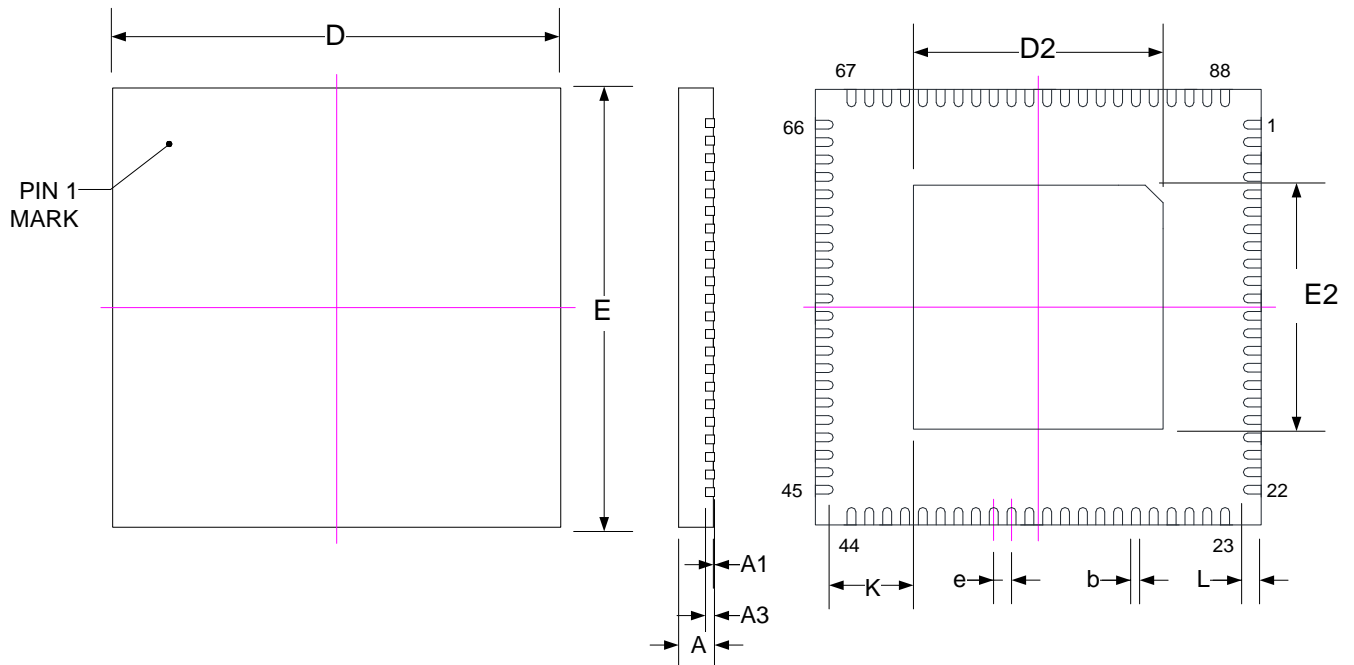
HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

7.3. QFN88(N088)(TYPE2)

7.3.1. Package Dimensions QFN88(10x10)

Unit: mm



SYMBOLS	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20 REF.		
b	0.15	0.20	0.25
D	10.00 BSC		
E	10.00 BSC		
e	0.40 BSC		
D2	5.45	5.60	5.75
E2	5.45	5.60	5.75
L	0.30	0.40	0.50
K	1.62	1.80	1.98

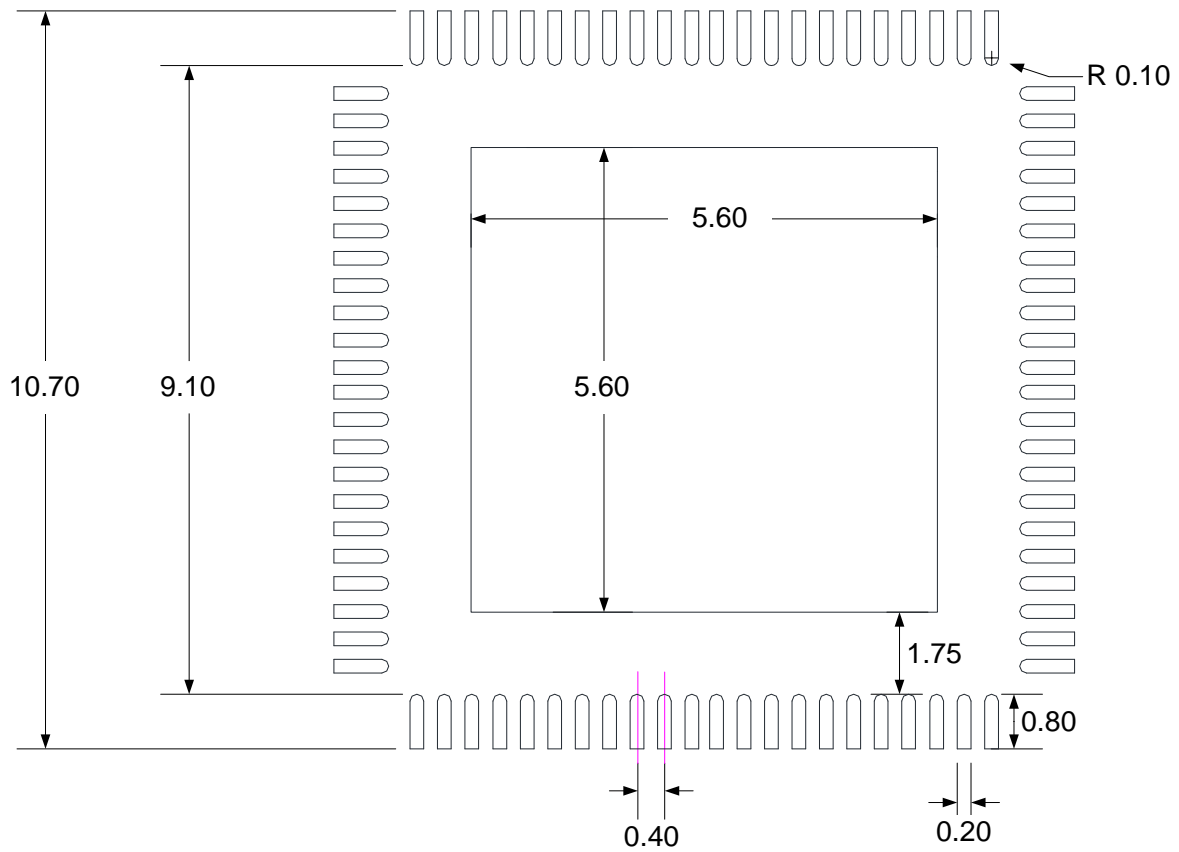
Note:

1. All dimensions refer to JEDEC OUTLINE MO-220.
2. Do not include Mold Flash or Protrusions.
3. Unit: mm.
4. https://www.hycontek.com/wp-content/uploads/QFN_DFN_PCB.pdf

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

7.3.2. Land Pattern Design Recommendations



Note:

1. Publication IPC-7351 is recommended for alternate designs
2. Unit : mm

HY16F3913

21-bit ENOB ΣΔADC, 32-bit MCU & 128KB Flash
4X44~8X40 LCD Driver

8. 修訂記錄

以下描述本文件差異較大的地方，而標點符號與字形的改變不在此描述範圍。

文件版次	頁次	日期	摘要
V01	ALL	2022/08/26	初版發行